FlashFlex51 MCU
SST89E564RD / SST89V564RD
SST89E554RC / SST89V554RC

FEATURES:

- **8-bit 8051-Compatible Microcontroller (MCU) with Embedded SuperFlash Memory**
  - Fully Software Compatible
  - Development Toolset Compatible
  - Pin-For-Pin Package Compatible
- **SST89E564RD/SST89E554RC Operation**
  - 0 to 40 MHz at 5V
- **SST89V564RD/SST89V554RC Operation**
  - 0 to 33 MHz at 3V
- **Total 1 KByte Internal RAM (256 Byte + 768 Byte)**
- **Dual Block SuperFlash EEPROM**
  - SST89E564RD/SST89V564RD:
    64 KByte primary block + 8 KByte secondary block (128-Byte sector size for both blocks)
  - SST89E554RC/SST89V554RC:
    32 KByte primary block + 8 KByte secondary block (128-Byte sector size for both blocks)
  - Individual Block Security Lock with SoftLock
  - Concurrent Operation during In-Application Programming (IAP)
  - Memory Overlay for Interrupt Support during IAP
- **Support External Address Range up to 64 KByte of Program and Data Memory**
- **Three High-Current Drive Port 1 pins**
- **Three 16-bit Timers/Counters**

- **Full-Duplex, Enhanced UART**
  - Framing Error Detection
  - Automatic Address Recognition
- **Eight Interrupt Sources at 4 Priority Levels**
- **Programmable Watchdog Timer (WDT)**
- **Programmable Counter Array (PCA)**
- **Four 8-bit I/O Ports (32 I/O Pins)**
- **Second DPTR register**
- **Low EMI Mode (Inhibit ALE)**
- **SPI Serial Interface**
- **Standard 12 Clocks per cycle, the device has an option to double the speed to 6 clocks per cycle.**
- **TTL- and CMOS-Compatible Logic Levels**
- **Brown-out Detection**
- **Low Power Modes**
  - Power-down Mode with External Interrupt Wake-up
  - Idle Mode
- **Temperature Ranges:**
  - Commercial (0°C to +70°C)
  - Industrial (-40°C to +85°C)
- **Packages Available**
  - 40-contact WQFN
  - 44-lead PLCC
  - 40-pin PDIP (Port 4 feature not available)
  - 44-lead TQFP
  - Non-Pb (lead-free) packages available

PRODUCT DESCRIPTION

The SST89E564RD, SST89V564RD, SST89E554RC, and SST89V554RC are members of the FlashFlex51 family of 8-bit microcontroller products designed and manufactured with SST's patented and proprietary SuperFlash CMOS semiconductor process technology. The split-gate cell design and thick-oxide tunneling injector offer significant cost and reliability benefits for our customers. The devices use the 8051 instruction set and are pin-for-pin compatible with standard 8051 microcontroller devices.

The devices come with 72/40 KByte of on-chip flash EEPROM program memory which is partitioned into 2 independent program memory blocks. The primary Block 0 occupies 64/32 KByte of internal program memory space and the secondary Block 1 occupies 8 KByte of internal program memory space.

The 8-KByte secondary flash block can be mapped to the lowest location of the 64-/32-KByte address space; it can also be hidden from the program counter and used as an independent EEPROM-like data memory.

In addition to the 72/40 KByte of EEPROM program memory on-chip, the devices can address up to 64 KByte of external program memory. In addition to 1024 x8 bits of on-chip RAM, up to 64 KByte of external RAM can be addressed.

The flash memory blocks can be programmed via a standard 87C5x OTP EPROM programmer fitted with a special adapter and the firmware for SST's devices. During power-on reset, the devices can be configured as either a slave to an external host for source code storage or a master to an external host for an in-application programming (IAP) operation. The devices are designed to be programmed in-system and in-application on the printed circuit board for maximum flexibility. The devices are pre-programmed with an example of the bootstrap loader in memory, demonstrating the initial user program code loading or subsequent user code updating via an IAP operation. A sample bootstrap loader is available for the user's reference and convenience only; SST does not guarantee its functionality or usefulness. Chip-Erase or Block-Erase operations will erase the pre-programmed sample code.

TABLE OF CONTENTS

LIST OF FIGURES

LIST OF TABLES

1.0 FUNCTIONAL BLOCKS

FUNCTIONAL BLOCK DIAGRAM

1. 64K x8 for SST89E564RD and SST89V564RD
   32K x8 for SST89E554RC and SST89V554RC

1207 B1.3

EOL Data Sheet

2.0 PIN ASSIGNMENTS

Top View
(contacts facing down)

1207 40-wqfn QI P4.1

FIGURE   2-1: PIN ASSIGNMENTS FOR 40-CONTACT WQFN

FIGURE   2-2: PIN ASSIGNMENTS FOR 40-PIN PDIP
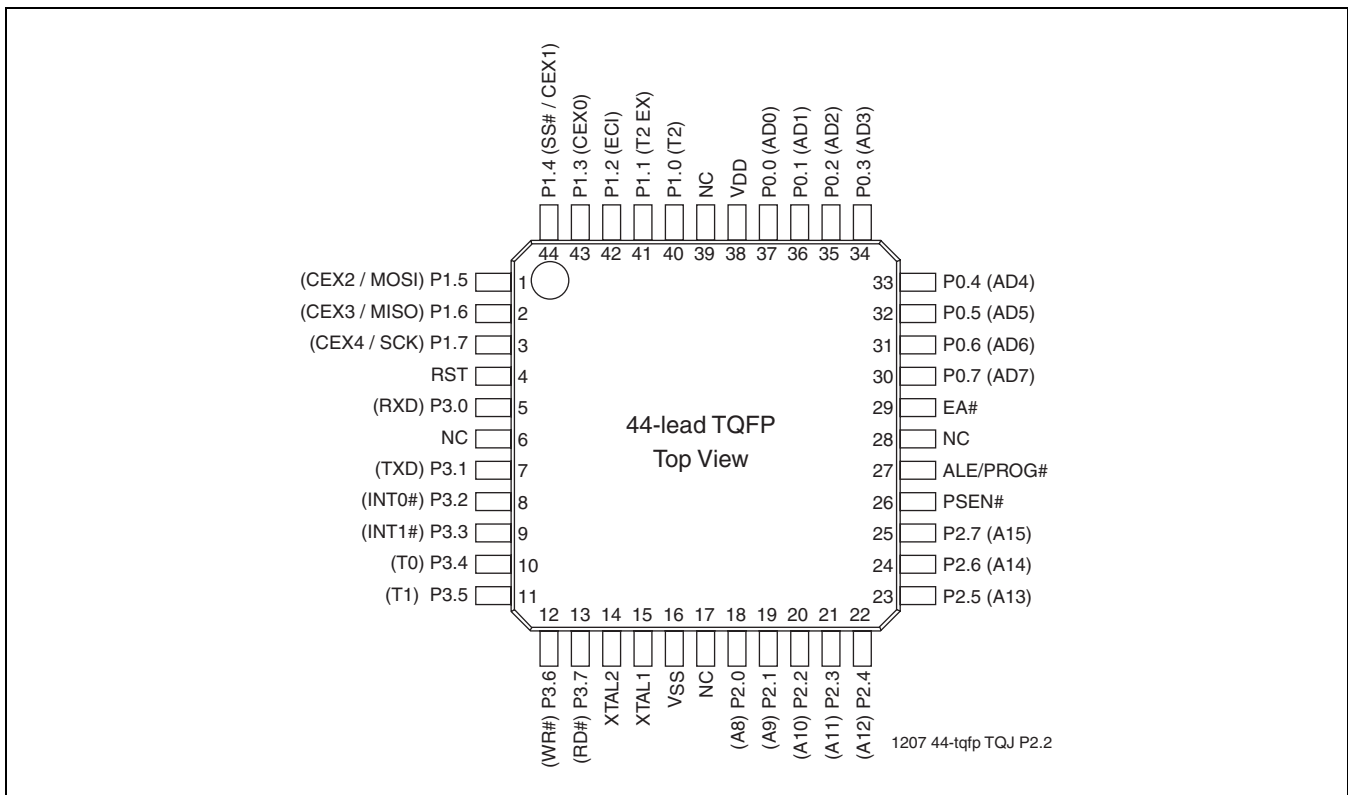
FIGURE   2-3: PIN ASSIGNMENTS FOR 44-LEAD TQFP
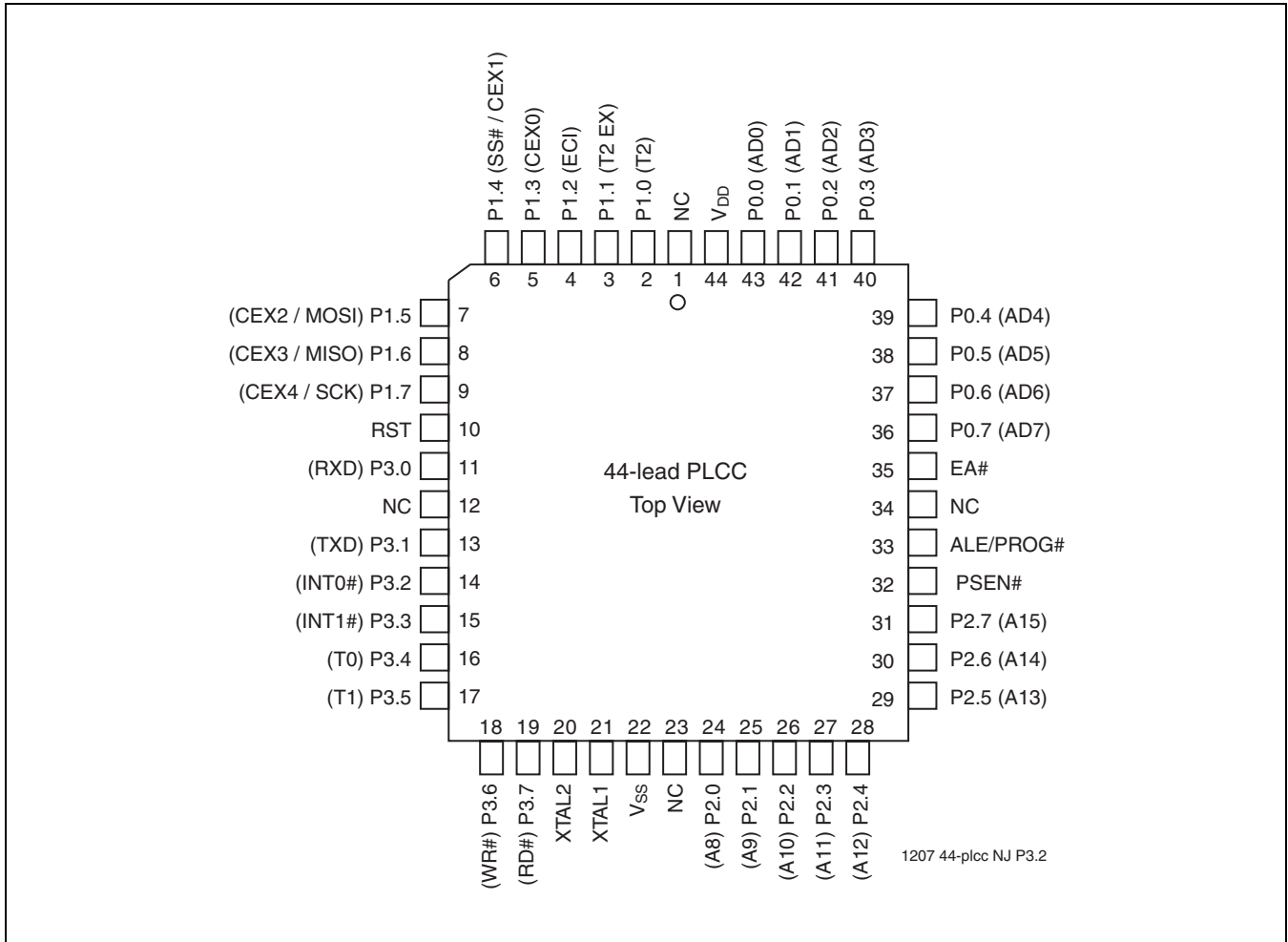
FIGURE   2-4: PIN ASSIGNMENTS FOR 44-LEAD PLCC

2.1 Pin Descriptions

TABLE 2-1: PIN DESCRIPTIONS (1 OF 2)

Symbol	Type[1]	Name and Functions
P0[7:0]	I/O	**Port 0:** Port 0 is an 8-bit open drain bi-directional I/O port. As an output port each pin can sink several LS TTL inputs. Port 0 pins that have '1's written to them float, and in this state can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external code and data memory. In this application, it uses strong internal pull-ups when transitioning to '1's. Port 0 also receives the code bytes during the external host mode programming, and outputs the code bytes during the external host mode verification. External pull-ups are required during program verification or as a general purpose I/O port.
P1[7:0]	I/O with internal pull-up	**Port 1:** Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can drive LS TTL inputs. Port 1 pins are pulled high by the internal pull-ups when '1's are written to them and can be used as inputs in this state. As inputs, Port 1 pins that are externally pulled low will source current (I_{IL}, see Tables 13-6 and 13-7) because of the internal pull-ups. P1[5, 6, 7] have high current drive of 16 mA. Port 1 also receives the low-order address bytes during the external host mode programming and verification.
P1[0]	I/O	**T2:** External count input to Timer/Counter 2 or Clock-out from Timer/Counter 2
P1[1]	I	**T2EX:** Timer/Counter 2 capture/reload trigger and direction control
P1[2]	I	**ECI:** External Clock Input This signal is the external clock input for the PCA.
P1[3]	I/O	**CEX0:** Capture/Compare External I/O for PCA Module 0 Each capture/compare module connects to a Port 1 pin for external I/O. When not used by the PCA, this pin can handle standard I/O.
P1[4]	I/O	**SS#:** Slave port select input for SPI **OR** **CEX1:** Capture/Compare External I/O for PCA Module 1
P1[5]	I/O	**MOSI:** Master Output line, Slave Input line for SPI **OR** **CEX2:** Capture/Compare External I/O for PCA Module 2
P1[6]	I/O	**MISO:** Master Input line, Slave Output line for SPI **OR** **CEX3:** Capture/Compare External I/O for PCA Module 3
P1[7]	I/O	**SCK:** Master clock output, slave clock input line for SPI **OR** **CEX4:** Capture/Compare External I/O for PCA Module 4
P2[7:0]	I/O with internal pull-up	**Port 2:** Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. Port 2 pins are pulled high by the internal pull-ups when '1's are written to them and can be used as inputs in this state. As inputs, Port 2 pins that are externally pulled low will source current (I_{IL}, see Tables 13-6 and 13-7) because of the internal pull-ups. Port 2 sends the high-order address byte during fetches from external program memory and during accesses to external Data Memory that use 16-bit address (MOVX@DPTR). In this application, it uses strong internal pull-ups when transitioning to '1's. Port 2 also receives some control signals and a partial of high-order address bits during the external host mode programming and verification.
P3[7:0]	I/O with internal pull-up	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 3 output buffers can drive LS TTL inputs. Port 3 pins are pulled high by the internal pull-ups when '1's are written to them and can be used as inputs in this state. As inputs, Port 3 pins that are externally pulled low will source current (I_{IL}, see Tables 13-6 and 13-7) because of the internal pull-ups. Port 3 also receives some control signals and a partial of high-order address bits during the external host mode programming and verification.
P3[0]	I	**RXD:** Universal Asynchronous Receiver/Transmitter (UART) - Receive input
P3[1]	O	**TXD:** UART - Transmit output

EOL Data Sheet

TABLE   2-1: PIN DESCRIPTIONS (CONTINUED) (2 OF 2)

Symbol	Type[1]	Name and Functions
P3[2]	I	**INT0#:** External Interrupt 0 Input
P3[3]	I	**INT1#:** External Interrupt 1 Input
P3[4]	I	**T0:** External count input to Timer/Counter 0
P3[5]	I	**T1:** External count input to Timer/Counter 1
P3[6]	O	**WR#:** External Data Memory Write strobe
P3[7]	O	**RD#:** External Data Memory Read strobe
PSEN#	I/O	**Program Store Enable:** PSEN# is the Read strobe to external program. When the device is executing from internal program memory, PSEN# is inactive (High). When the device is executing code from external program memory, PSEN# is activated twice each machine cycle, except that two PSEN# activations are skipped during each access to external data memory. A forced high-to-low input transition on the PSEN# pin while the RST input is continually held high for more than 10 machine cycles will cause the device to enter external host mode programming.
RST	I	**Reset:** While the oscillator is running, a "high" logic state on this pin for two machine cycles will reset the device. If the PSEN# pin is driven by a high-to-low input transition while the RST input pin is held "high," the device will enter the external host mode, otherwise the device will enter the normal operation mode.
EA#	I	**External Access Enable:** EA# must be connected to V_{SS} in order to enable the device to fetch code from the external program memory. EA# must be strapped to V_{DD} for internal program execution. However, Security lock level 4 will disable EA#, and program execution is only possible from internal program memory. The EA# pin can tolerate a high voltage[2] of 12V. (See Section 13.0, "Electrical Specification")
ALE/PROG#	I/O	**Address Latch Enable:** ALE is the output signal for latching the low byte of the address during an access to external memory. This pin is also the programming pulse input (PROG#) for flash programming. Normally the ALE[3] is emitted at a constant rate of 1/6 the crystal frequency[4] and can be used for external timing and clocking. One ALE pulse is skipped during each access to external data memory. However, if AO is set to 1, ALE is disabled. (See "Auxiliary Register (AUXR)" in Section 3.6, "Special Function Registers")
NC	I/O	**No Connect**
XTAL1	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	O	**Crystal 2:** Output from the inverting oscillator amplifier.
V_{DD}	I	**Power Supply**
V_{SS}	I	**Ground**

T2-1.4 1207

1. I = Input; O = Output
2. It is not necessary to receive a 12V programming supply voltage during flash programming.
3. ALE loading issue: When ALE pin experiences higher loading (>30pf) during the reset, the MCU may accidentally enter into modes other than normal working mode. The solution is to add a pull-up resistor of 3-50 KΩ to V_{DD}, e.g. for ALE pin.
4. For 6 clock mode, ALE is emitted at 1/3 of crystal frequency.

3.0 MEMORY ORGANIZATION

The device has separate address spaces for program and data memory.

3.1 Program Flash Memory

There are two internal flash memory blocks in the device. The primary flash memory block (Block 0) has 64/32 KByte. The secondary flash memory block (Block 1) has 8 KByte. Since the total program address space is limited to 64 KByte, the SFCF[1:0] bit are used to control program

bank selection. Please refer to Figure 3-1 and Figure 3-2 for the program memory configurations. Program bank selection is described in the next section.

The 64K/32K x8 primary SuperFlash block is organized as 512/256 sectors, each sector consists of 128 Bytes.

The 8K x8 secondary SuperFlash block is organized as 64 sectors, each sector consists also of 128 Bytes.

For both blocks, the 7 least significant program address bits select the byte within the sector. The remainder of the program address bits select the sector within the block.
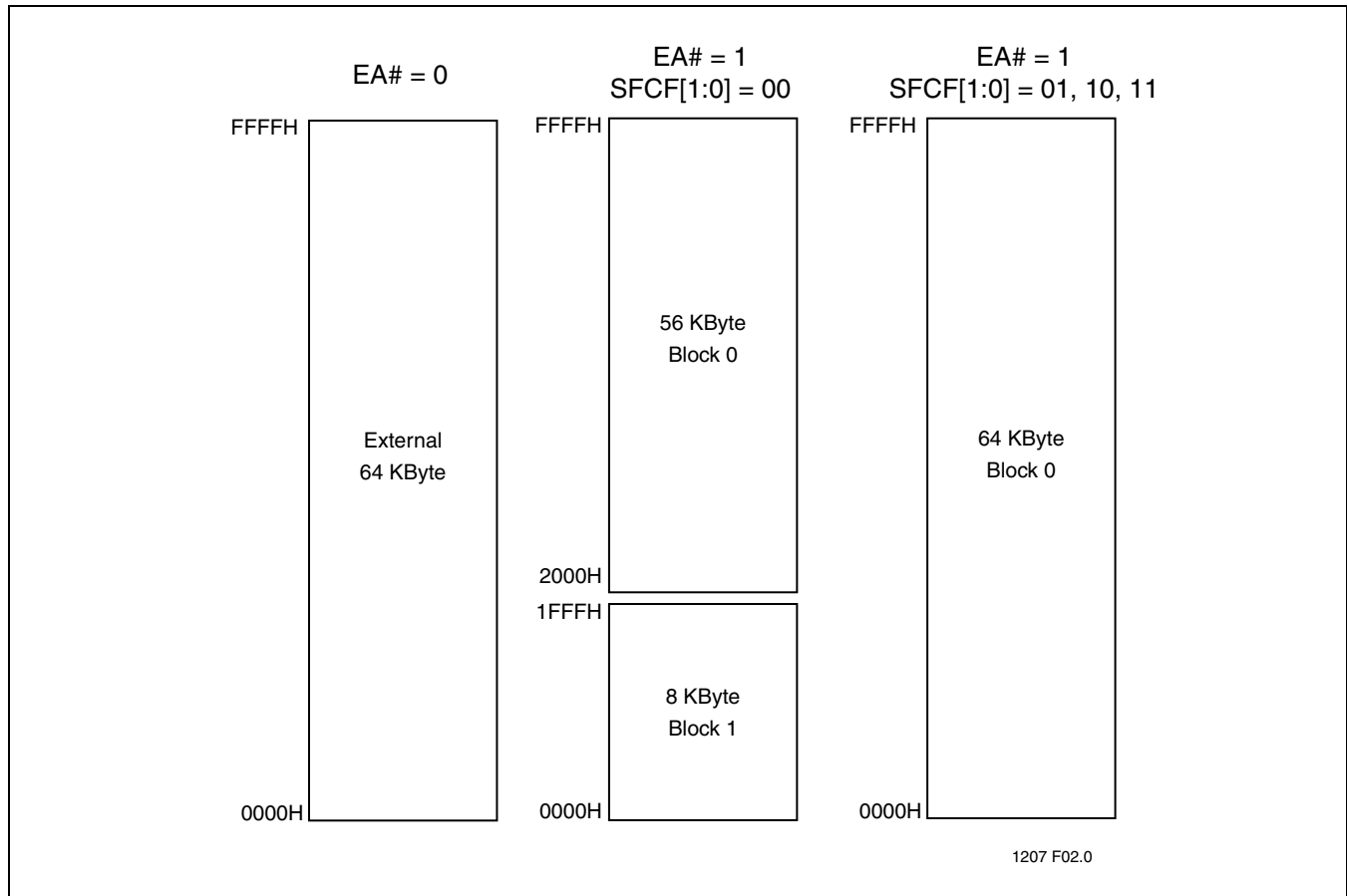
FIGURE 3-1: PROGRAM MEMORY ORGANIZATION FOR SST89E/V564RD
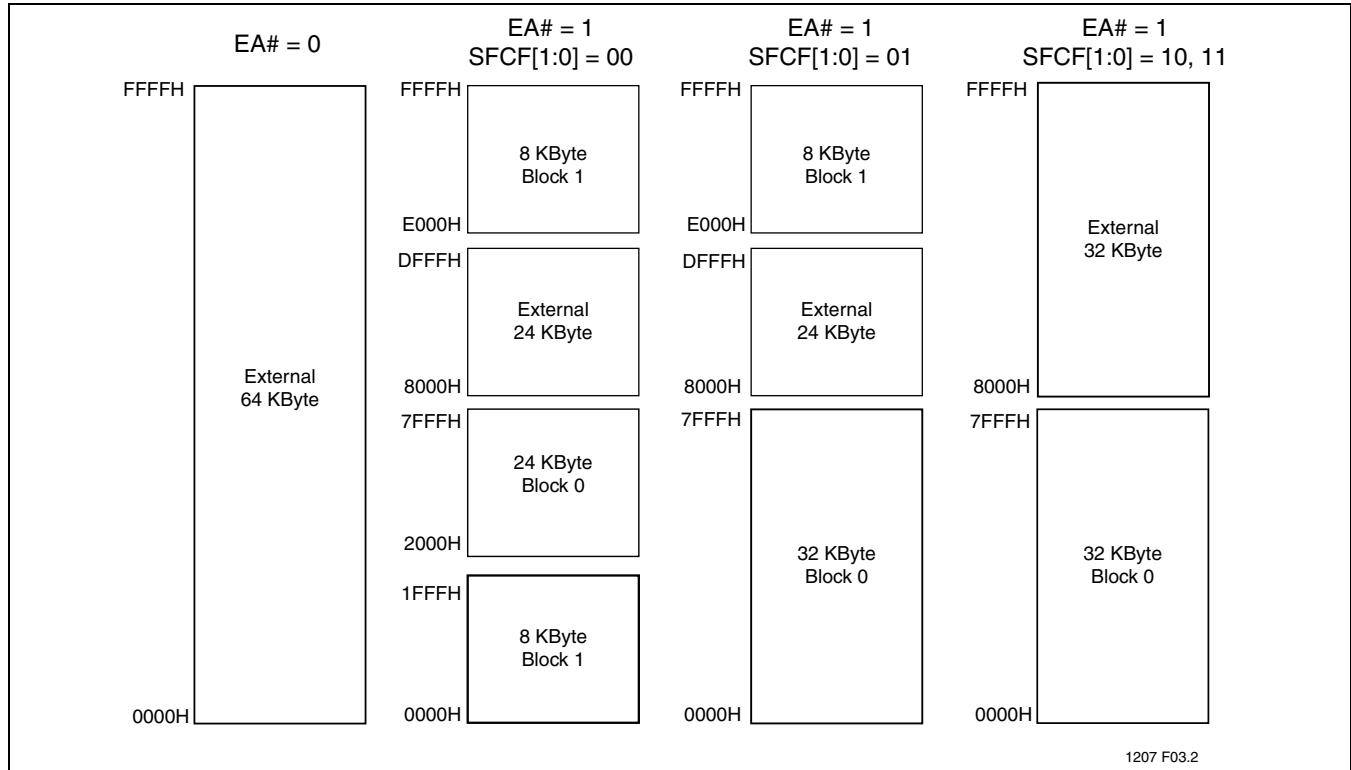
FIGURE   3-2: PROGRAM MEMORY ORGANIZATION FOR SST89E/V554RC

3.2 Program Memory Block Switching

The program memory block switching feature of the device allows either Block 1 or the lowest 8 KByte of Block 0 to be used for the lowest 8 KByte of the program address space. SFCF[1:0] controls program memory block switching.

TABLE   3-1: SFCF VALUES FOR PROGRAM MEMORY BLOCK SWITCHING FOR SST89E/V564RD

SFCF[1:0]	Program Memory Block Switching
01, 10, 11	Block 1 is not visible to the program counter (PC). Block 1 is reachable only via in-application programming from 0000H - 1FFFH.
00	Block 1 is overlaid onto the low 8K of the program address space; occupying address locations 0000H - 1FFFH. When the PC falls within 0000H - 1FFFH, the instruction will be fetched from Block 1 instead of Block 0. Outside of 0000H - 1FFFH, Block 0 is used. Locations 0000H - 1FFFH of Block 0 are reachable through in-application programming.

T3-1.1 1207

TABLE   3-2: SFCF VALUES FOR PROGRAM MEMORY BLOCK SWITCHING FOR SST89E/V554RC

SFCF[1:0]	Program Memory Block Switching
10, 11	Block 1 is not visible to the PC; Block 1 is reachable only via in-application programming from E000H - FFFFH.
01	Both Block 0 and Block 1 are visible to the PC. Block 0 is occupied from 0000H - 7FFFH. Block 1 is occupied from E000H - FFFFH.
00	Block 1 is overlaid onto the low 8K of the program address space; occupying address locations 0000H - 1FFFH. When the PC falls within 0000H - 1FFFH, the instruction will be fetched from Block 1 instead of Block 0. Outside of 0000H - 1FFFH, Block 0 is used. Locations 0000H - 1FFFH of Block 0 are reachable through in-application programming.

T3-2.0 1207

3.2.1 Reset Configuration of Program Memory Block Switching

Program memory block switching is initialized after reset according to the state of the Start-up Configuration bit SC0 and/or SC1. The SC0 and SC1 bits are programmed via an external host mode command or an IAP Mode command. See Table 4-2 and Table 4-7.

Once out of reset, the SFCF[0] bit can be changed dynamically by the program for desired effects. Changing SFCF[0] will not change the SC0 bit.

Caution must be taken when dynamically changing the SFCF[0] bit. Since this will cause different physical memory to be mapped to the logical program address space. The user must avoid executing block switching instructions within the address range 0000H to 1FFFH.

TABLE 3-3: SFCF VALUES UNDER DIFFERENT RESET CONDITIONS (SST89E/V554RC)

		State of SFCF[1:0] after:		
SC1[1]	SC0[1]	Power-on or External Reset	WDT Reset or Brown-out Reset	Software Reset
U (1)	U (1)	00 (default)	x0	10
U (1)	P (0)	01	x1	11
P (0)	U (1)	10	10	10
P (0)	P (0)	11	11	11

T3-3.1 1207

1. P = Programmed (Bit logic state = 0),
   U = Unprogrammed (Bit logic state = 1)

TABLE 3-4: SFCF VALUES UNDER DIFFERENT RESET CONDITIONS (SST89E/V564RD)

	State of SFCF[1:0] after:		
SC0[1]	Power-on or External Reset	WDT Reset or Brown-out Reset	Software Reset
U (1)	00 (default)	x0	10
P (0)	01	x1	11

T3-4.1 1207

1. P = Programmed (Bit logic state = 0),
   U = Unprogrammed (Bit logic state = 1)

3.3 Data RAM Memory

The data RAM has 1024 bytes of internal memory. The RAM can be addressed up to 64KB for external data memory.

3.4 Expanded Data RAM Addressing

The SST89E/V554RC and SSTE/V564RD both have the capability of 1K of RAM. See Figure 3-3.

The device has four sections of internal data memory:

1. The lower 128 Bytes of RAM (00H to 7FH) are directly and indirectly addressable.

2. The higher 128 Bytes of RAM (80H to FFH) are indirectly addressable.

3. The special function registers (80H to FFH) are directly addressable only.

4. The expanded RAM of 768 Bytes (00H to 2FFH) is indirectly addressable by the move external instruction (MOVX) and clearing the EXTRAM bit. (See "Auxiliary Register (AUXR)" in Section 3.6, "Special Function Registers")

Since the upper 128 bytes occupy the same addresses as the SFRs, the RAM must be accessed indirectly. The RAM and SFRs space are physically separate even though they have the same addresses.

When instructions access addresses in the upper 128 bytes (above 7FH), the MCU determines whether to access the SFRs or RAM by the type of instruction given. If it is indirect, then RAM is accessed. If it is direct, then an SFR is accessed. See the examples below.

Indirect Access:

    MOV   @R0, #data   ; R0 contains 90H

Register R0 points to 90H which is located in the upper address range. Data in "#data" is written to RAM location 90H rather than port 1.

Direct Access:

    MOV   90H, #data   ; write data to P1

Data in "#data" is written to port 1. Instructions that write directly to the address write to the SFRs.

To access the expanded RAM, the EXTRAM bit must be cleared and MOVX instructions must be used. The extra 768 bytes of memory is physically located on the chip and logically occupies the first 768 bytes of external memory (addresses 000H to 2FFH).

When EXTRAM = 0, the expanded RAM is indirectly addressed using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. Accessing the expanded RAM does not affect ports P0, P3.6 (WR#), P3.7 (RD#), or P2. With EXTRAM = 0, the expanded RAM can be accessed as in the following example.

EOL Data Sheet

Expanded RAM Access (Indirect Addressing only):

MOVX   @DPTR, A   ; DPTR contains 0A0H

DPTR points to 0A0H and data in "A" is written to address 0A0H of the expanded RAM rather than external memory. Access to external memory higher than 2FFH using the MOVX instruction will access external memory (0300H to FFFFH) and will perform in the same way as the standard 8051, with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals.

When EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 8051. Using MOVX @Ri provides an 8-bit address with multiplexed data on Port 0. Other output port pins can be used to output higher order address bits. This provides external paging capabilities. Using MOVX @DPTR generates a 16-bit address. This allows external addressing up the 64K. Port 2 provides the high-order eight address bits (DPH), and Port 0 multiplexes the low order eight address bits (DPL) with data. Both MOVX @Ri and MOVX @DPTR generates the necessary read and write signals (P3.6 - WR# and P3.7 - RD#) for external memory use. Table 3-5 shows external data memory RD#, WR# operation with EXTRAM bit.

The stack pointer (SP) can be located anywhere within the 256 bytes of internal RAM (lower 128 bytes and upper 128 bytes). The stack pointer may not be located in any part of the expanded RAM.

TABLE   3-5: EXTERNAL DATA MEMORY RD#, WR# WITH EXTRAM BIT

	MOVX @DPTR, A or MOVX A, @DPTR		MOVX @Ri, A or MOVX A, @Ri
AUXR	**ADDR < 0300H**	**ADDR >= 0300H**	**ADDR = Any**
EXTRAM = 0	RD# / WR# not asserted	RD# / WR# asserted	RD# / WR# not asserted[1]
EXTRAM = 1	RD# / WR# asserted	RD# / WR# asserted	RD# / WR# asserted

T3-5.0 1207

1. Access limited to ERAM address within 0 to 0FFH; cannot access 100H to 02FFH.
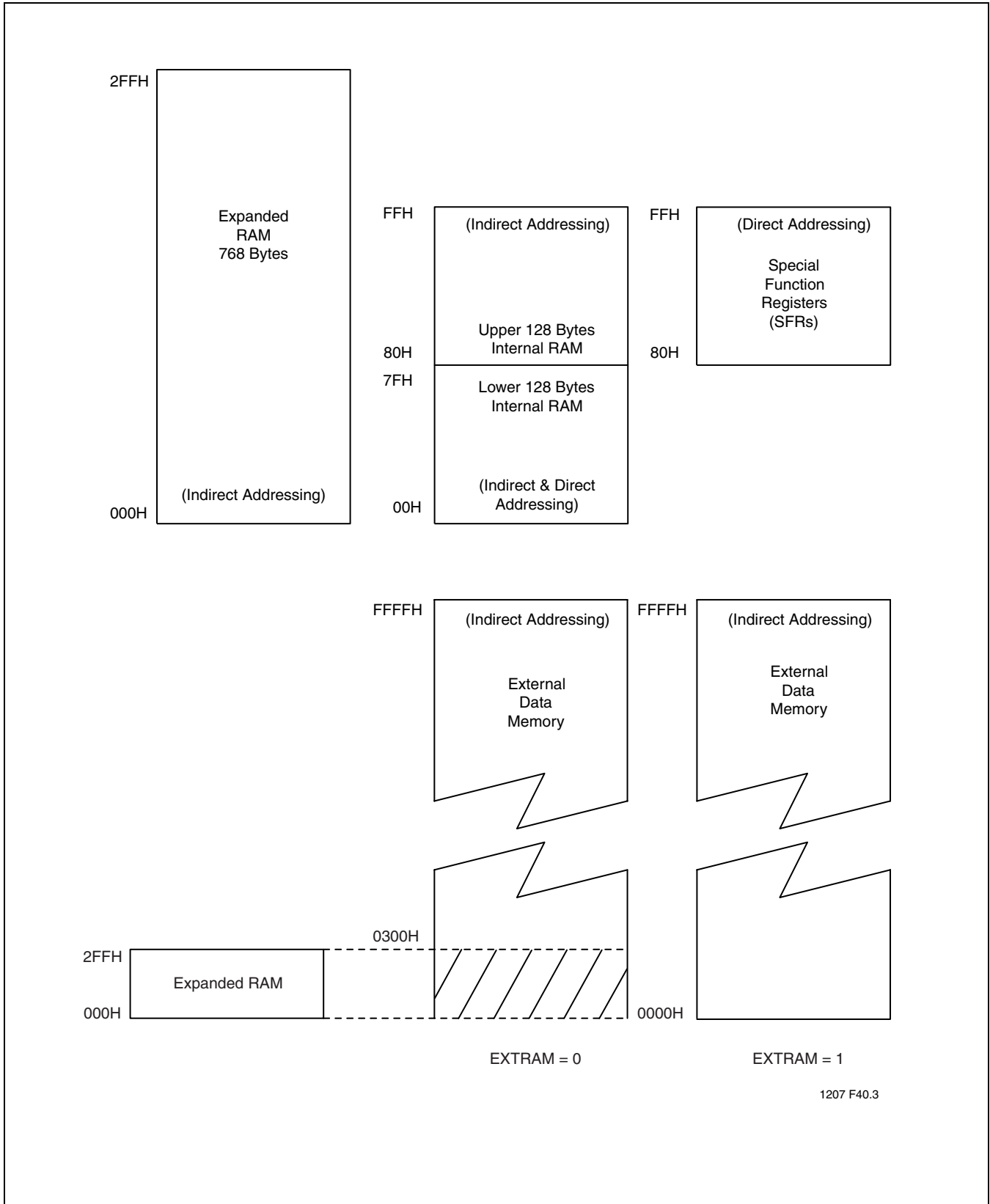
FIGURE   3-3: INTERNAL AND EXTERNAL DATA MEMORY STRUCTURE

EOL Data Sheet

3.5 Dual Data Pointers

The device has two 16-bit data pointers. The DPTR Select (DPS) bit in AUXR1 determines which of the two data pointers is accessed. When DPS=0, DPTR0 is selected; when DPS=1, DPTR1 is selected. Quickly switching between the two data pointers can be accomplished by a single INC instruction on AUXR1. (See Figure 3-4)
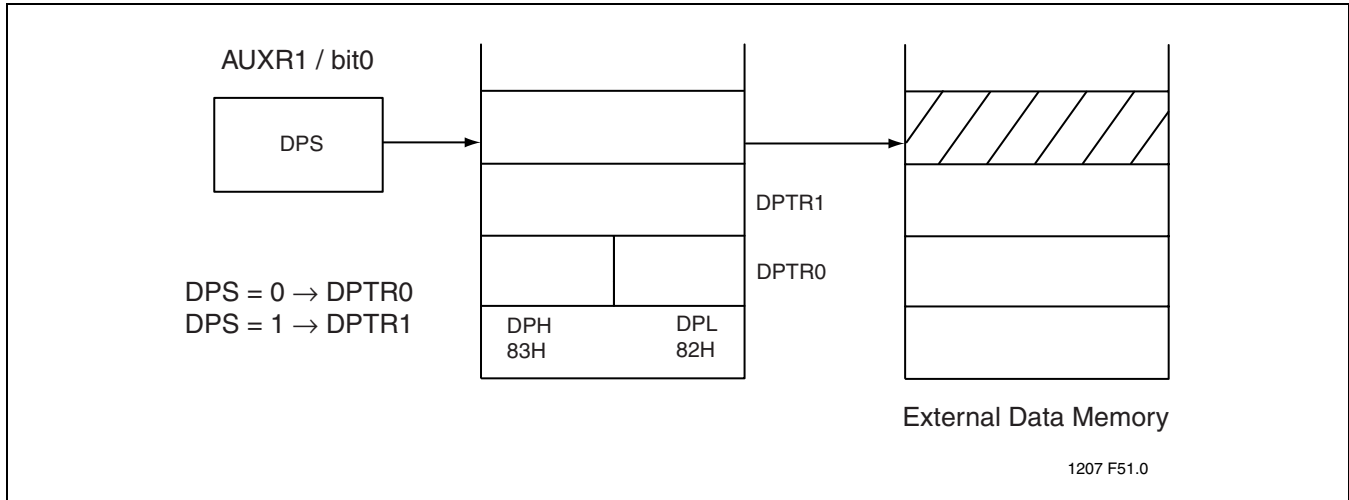
FIGURE   3-4: DUAL DATA POINTER ORGANIZATION

3.6 Special Function Registers

Most of the unique features of the FlashFlex51 microcontroller family are controlled by bits in special function registers (SFRs) located in the SFR memory map shown in Table 3-6. Individual descriptions of each SFR are provided and reset values indicated in Tables 3-7 to 3-11.

TABLE   3-6: FLASHFLEX51 SFR MEMORY MAP

	8 BYTES							
F8H	IPA[1]	CH	CCAP0H	CCAP1H	CCAP2H	CCAP3H	CCAP4H		FFH
F0H	B[1]							IPAH	F7H
E8H	IEA[1]	CL	CCAP0L	CCAP1L	CCAP2L	CCAP3L	CCAP4L		EFH
E0H	ACC[1]								E7H
D8H	CCON[1]	CMOD	CCAPM0	CCAPM1	CCAPM2	CCAPM3	CCAPM4		DFH
D0H	PSW[1]					SPCR			D7H
C8H	T2CON[1]	T2MOD	RCAP2L	RCAP2H	TL2	TH2			CFH
C0H	WDTC[1]								C7H
B8H	IP[1]	SADEN							BFH
B0H	P3[1]	SFCF	SFCM	SFAL	SFAH	SFDT	SFST	IPH	B7H
A8H	IE[1]	SADDR	SPSR						AFH
A0H	P2[1]		AUXR1						A7H
98H	SCON[1]	SBUF							9FH
90H	P1[1]								97H
88H	TCON[1]	TMOD	TL0	TL1	TH0	TH1	AUXR		8FH
80H	P0[1]	SP	DPL	DPH		WDTD	SPDR	PCON	87H

T3-6.2 1207

1. Bit addressable SFRs

S71207-07-EOL   12/06

TABLE   3-7: CPU RELATED SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function								Reset Value
			MSB							LSB	
ACC[1]	Accumulator	E0H	ACC[7:0]								00H
B[1]	B Register	F0H	B[7:0]								00H
PSW[1]	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	F1	P	00H
SP	Stack Pointer	81H	SP[7:0]								07H
DPL	Data Pointer Low	82H	DPL[7:0]								00H
DPH	Data Pointer High	83H	DPH[7:0]								00H
IE[1]	Interrupt Enable	A8H	EA	EC	ET2	ES	ET1	EX1	ET0	EX0	00H
IEA[1]	Interrupt Enable A	E8H	-	-	-	-	EBO	-	-	-	xxxx0xxxb
IP[1]	Interrupt Priority Reg	B8H	-	PPC	PT2	PS	PT1	PX1	PT0	PX0	x0000000b
IPH	Interrupt Priority Reg High	B7H	-	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	x0000000b
IPA[1]	Interrupt Priority Reg A	F8H	-	-	-	-	PBO	-	-	-	xxxx0xxxb
IPAH	Interrupt Priority Reg A High	F7H	-	-	-	-	PBOH	-	-	-	xxxx0xxxb
PCON	Power Control	87H	SMOD1	SMOD0	BOF	POF	GF1	GF0	PD	IDL	00010000b
AUXR	Auxiliary Reg	8EH	-	-	-	-	-	-	EXTRAM	AO	xxxxxx00b
AUXR1	Auxiliary Reg 1	A2H	-	-	-	-	GF2	0	-	DPS	xxxx00x0b

T3-7.2 1207

1. Bit Addressable SFRs

TABLE   3-8: FLASH MEMORY PROGRAMMING SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function								Reset Value
			MSB							LSB	
SFCF	SuperFlash Configuration	B1H	-	IAPEN	-	-	-	-	SWR	BSEL	x0xxxx00b
SFCM	SuperFlash Command	B2H	FIE	FCM[6:0]							00H
SFAL	SuperFlash Address Low	B3H	SuperFlash Low Order Byte Address Register - A_7 to A_0 (SFAL)								00H
SFAH	SuperFlash Address High	B4H	SuperFlash High Order Byte Address Register - A_{15} to A_8 (SFAH)								00H
SFDT	SuperFlash Data	B5H	SuperFlash Data Register								00H
SFST	SuperFlash Status	B6H	SB1_i	SB2_i	SB3_i	-	EDC_i	FLASH_BUSY	-	-	000x00xxb

T3-8.3 1207

EOL Data Sheet

TABLE 3-9: WATCHDOG TIMER SFRS

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	Reset Value
WDTC[1]	Watchdog Timer Control	C0H	-	-	-	WDOUT	WDRE	WDTS	WDT	SWDT	xxx00x00b
WDTD	Watchdog Timer Data/Reload	85H	Watchdog Timer Data/Reload								00H

T3-9.0 1207

1. Bit Addressable SFRs

TABLE 3-10: TIMER/COUNTERS SFRS

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	Reset Value
TMOD	Timer/Counter Mode Control	89H	Timer 1				Timer 0				00H
			GATE	C/T#	M1	M0	GATE	C/T#	M1	M0	
TCON[1]	Timer/Counter Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
TH0	Timer 0 MSB	8CH	TH0[7:0]								00H
TL0	Timer 0 LSB	8AH	TL0[7:0]								00H
TH1	Timer 1 MSB	8DH	TH1[7:0]								00H
TL1	Timer 1 LSB	8BH	TL1[7:0]								00H
T2CON[1]	Timer / Counter 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2#	CP/RL2#	00H
T2MOD	Timer2 Mode Control	C9H	-	-	-	-	-	-	T2OE	DCEN	xxxxxx00b
TH2	Timer 2 MSB	CDH	TH2[7:0]								00H
TL2	Timer 2 LSB	CCH	TL2[7:0]								00H
RCAP2H	Timer 2 Capture MSB	CBH	RCAP2H[7:0]								00H
RCAP2L	Timer 2 Capture LSB	CAH	RCAP2L[7:0]								00H

T3-10.0 1207

1. Bit Addressable SFRs

TABLE 3-11: INTERFACE SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	RESET Value
SBUF	Serial Data Buffer	99H	SBUF[7:0]								Indeterminate
SCON[1]	Serial Port Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SADDR	Slave Address	A9H	SADDR[7:0]								00H
SADEN	Slave Address Mask	B9H	SADEN[7:0]								00H
SPCR	SPI Control Register	D5H	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04H
SPSR	SPI Status Register	AAH	SPIF	WCOL							00H
SPDR	SPI Data Register	86H	SPDR[7:0]								00H
P0[1]	Port 0	80H	P0[7:0]								FFH
P1[1]	Port 1	90H	-	-	-	-	-	-	T2EX	T2	FFH
P2[1]	Port 2	A0H	P2[7:0]								FFH
P3[1]	Port 3	B0H	RD#	WR#	T1	T0	INT1#	INT0#	TXD	RXD	FFH

T3-11.1 1207

1. Bit Addressable SFRs

TABLE 3-12: PCA SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	RESET Value
CH CL	PCA Timer/Counter	F9H E9H	CH[7:0] CL[7:0]								00H 00H
CCON[1]	PCA Timer/Counter Control Register	D8H	CF	CR	-	CCF4	CCF3	CCF2	CCF1	CCF0	00x00000b
CMOD	PCA Timer/Counter Mode Register	D9H	CIDL	WDTE	-	-	-	CPS1	CPS0	ECF	00xxx000b
CCAP0H	PCA Module 0 Compare/Capture Registers	FAH	CCAP0H[7:0]								00H
CCAP0L		EAH	CCAP0L[7:0]								00H
CCAP1H	PCA Module 1 Compare/Capture Registers	FBH	CCAP1H[7:0]								00H
CCAP1L		EBH	CCAP1L[7:0]								00H
CCAP2H	PCA Module 2 Compare/Capture Registers	FCH	CCAP2H[7:0]								00H
CCAP2L		ECH	CCAP2L[7:0]								00H
CCAP3H	PCA Module 3 Compare/Capture Registers	FDH	CCAP3H[7:0]								00H
CCAP3L		EDH	CCAP3L[7:0]								00H
CCAP4H	PCA Module 4 Compare/Capture Registers	FEH	CCAP4H[7:0]								00H
CCAP4L		EEH	CCAP4L[7:0]								00H
CCAPM0	PCA Compare/Capture Module Mode Registers	DAH	-	ECOM0	CAPP0	CAPN0	MAT0	TOG0	PWM0	ECCF0	x0000000b
CCAPM1		DBH	-	ECOM1	CAPP1	CAPN1	MAT1	TOG1	PWM1	ECCF1	x0000000b
CCAPM2		DCH	-	ECOM2	CAPP2	CAPN2	MAT2	TOG2	PWM2	ECCF2	x0000000b
CCAPM3		DDH	-	ECOM3	CAPP3	CAPN3	MAT3	TOG3	PWM3	ECCF3	x0000000b
CCAPM4		DEH	-	ECOM4	CAPP4	CAPN4	MAT4	TOG4	PWM4	ECCF4	x0000000b

T3-12.1 1207

1. Bit Addressable SFRs

SuperFlash Configuration Register (SFCF)

Location	7	6	5	4	3	2	1	0	Reset Value
B1H	-	IAPEN	-	-	-	-	SWR	BSEL	x0xxxx00b

Symbol	Function
IAPEN	Enable IAP operation 0: IAP commands are disabled 1: IAP commands are enabled
SWR	Software Reset See Section 10.2, "Software Reset"
BSEL	Program memory block switching bit See Figure 3-1, Figure 3-2, Table 3-3, and Table 3-4.

SuperFlash Command Register (SFCM)

Location	7	6	5	4	3	2	1	0	Reset Value
B2H	FIE	FCM6	FCM5	FCM4	FCM3	FCM2	FCM1	FCM0	00H

Symbol	Function
FIE	Flash Interrupt Enable. 0: INT1# is not reassigned. 1: INT1# is re-assigned to signal IAP operation completion. External INT1# interrupts are ignored.
FCM[6:0]	Flash operation command

000_0001b Chip-Erase
000_1011b Sector-Erase
000_1101b Block-Erase
000_1100b Byte-Verify[1]
000_1110b Byte-Program
000_1111b Prog-SB1
000_0011b Prog-SB2
000_0101b Prog-SB3
000_1001b Prog-SC0
000_1001b Prog-SC1
000_1000b Enable-Clock-Double

All other combinations are not implemented, and reserved for future use.

1. Byte-Verify has a single machine cycle latency and will not generate any INT1# interrupt regardless of FIE.

SuperFlash Address Registers (SFAL)

Location	7	6	5	4	3	2	1	0	Reset Value
B3H			SuperFlash Low Order Byte Address Register						00H

Symbol	Function
SFAL	Mailbox register for interfacing with flash memory block. (Low order address register).

SuperFlash Address Registers (SFAH)

Location	7	6	5	4	3	2	1	0	Reset Value
B4H			SuperFlash High Order Byte Address Register						00H

Symbol	Function
SFAH	Mailbox register for interfacing with flash memory block. (High order address register).

SuperFlash Data Register (SFDT)

Location	7	6	5	4	3	2	1	0	Reset Value
B5H				SuperFlash Data Register					00H

Symbol	Function
SFDT	Mailbox register for interfacing with flash memory block. (Data register).

SuperFlash Status Register (SFST) (Read Only Register)

Location	7	6	5	4	3	2	1	0	Reset Value
B6H	SB1_i	SB2_i	SB3_i	-	EDC_i	FLASH_BUSY	-	-	xxxxx0xxb

Symbol	Function
SB1_i	Security Bit 1 status (inverse of SB1 bit)
SB2_i	Security Bit 2 status (inverse of SB2 bit)
SB3_i	Security Bit 3 status (inverse of SB3 bit) Please refer to Table 9-1 for security lock options.
EDC_i	Double Clock Status 0: 12 clocks per machine cycle 1: 6 clocks per machine cycle
FLASH_BUSY	Flash operation completion polling bit. 0: Device has fully completed the last IAP command. 1: Device is busy with flash operation.

EOL Data Sheet

Interrupt Enable (IE)

Location	7	6	5	4	3	2	1	0	Reset Value
A8H	EA	EC	ET2	ES	ET1	EX1	ET0	EX0	00H

Symbol	Function
EA	Global Interrupt Enable. 0 = Disable 1 = Enable
EC	PCA Interrupt Enable.
ET2	Timer 2 Interrupt Enable.
ES	Serial Interrupt Enable.
ET1	Timer 1 Interrupt Enable.
EX1	External 1 Interrupt Enable.
ET0	Timer 0 Interrupt Enable.
EX0	External 0 Interrupt Enable.

Interrupt Enable A (IEA)

Location	7	6	5	4	3	2	1	0	Reset Value
E8H	-	-	-	-	EBO	-	-	-	xxxx0xxxb

Symbol	Function
EBO	Brown-out Interrupt Enable. 1 = Enable the interrupt 0 = Disable the interrupt

Interrupt Priority (IP)

Location	7	6	5	4	3	2	1	0	Reset Value
B8H	-	PPC	PT2	PS	PT1	PX1	PT0	PX0	x0000000b

Symbol	Function
PPC	PCA interrupt priority bit.
PT2	Timer 2 interrupt priority bit.
PS	Serial Port interrupt priority bit.
PT1	Timer 1 interrupt priority bit.
PX1	External interrupt 1 priority bit.
PT0	Timer 0 interrupt priority bit.
PX0	External interrupt 0 priority bit.

Interrupt Priority High (IPH)

Location	7	6	5	4	3	2	1	0	Reset Value
B7H	-	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	x0000000b

Symbol	Function
PPCH	PCA interrupt priority bit high.
PT2H	Timer 2 interrupt priority bit high.
PSH	Serial Port interrupt priority bit high.
PT1H	Timer 1 interrupt priority bit high.
PX1H	External interrupt 1 priority bit high.
PT0H	Timer 0 interrupt priority bit high.
PX0H	External interrupt 0 priority bit high.

Interrupt Priority A (IPA)

Location	7	6	5	4	3	2	1	0	Reset Value
F8H	-	-	-	-	PBO	-	-	-	xxxx0xxxb

Symbol	Function
PBO	Brown-out interrupt priority bit.

Interrupt Priority A High (IPAH)

Location	7	6	5	4	3	2	1	0	Reset Value
F7H	-	-	-	-	PBOH	-	-	-	xxxx0xxxb

Symbol	Function
PBOH	Brown-out Interrupt priority bit high.

EOL Data Sheet

Auxiliary Register (AUXR)

Location	7	6	5	4	3	2	1	0	Reset Value
8EH	-	-	-	-	-	-	EXTRAM	AO	xxxxxx00b

Symbol	Function
EXTRAM	Internal/External RAM access 0: Internal Expanded RAM access within range of 00H to 2FFH using MOVX @Ri / @DPTR. Beyond 300H, the MCU always accesses external data memory. For details, refer to Section 3.4, "Expanded Data RAM Addressing" . 1: External data memory access.
AO	Disable/Enable ALE 0: ALE is emitted at a constant rate of 1/3 the oscillator frequency in 6 clock mode, 1/6 f_{OSC} in 12 clock mode. 1: ALE is active only during a MOVX or MOVC instruction.

Auxiliary Register 1 (AUXR1)

Location	7	6	5	4	3	2	1	0	Reset Value
A2H	-	-	-	-	GF2	0	-	DPS	xxxx00x0b

Symbol	Function
GF2	General purpose user-defined flag.
DPS	DPTR registers select bit. 0: DPTR0 is selected. 1: DPTR1 is selected.

Watchdog Timer Control Register (WDTC)

Location	7	6	5	4	3	2	1	0	Reset Value
C0H	-	-	-	WDOUT	WDRE	WDTS	WDT	SWDT	xxx00000b

Symbol	Function
WDOUT	Watchdog output enable. 0: Watchdog reset will not be exported on Reset pin. 1: Watchdog reset if enabled by WDRE, will assert Reset pin for 32 clocks.
WDRE	Watchdog timer reset enable. 0: Disable watchdog timer reset. 1: Enable watchdog timer reset.
WDTS	Watchdog timer reset flag. 0: External hardware reset or power-on reset clears the flag. Flag can also be cleared by writing a 1. Flag survives if chip reset happened because of watchdog timer overflow. 1: Hardware sets the flag on watchdog overflow.
WDT	Watchdog timer refresh. 0: Hardware resets the bit when refresh is done. 1: Software sets the bit to force a watchdog timer refresh.
SWDT	Start watchdog timer. 0: Stop WDT. 1: Start WDT.

Watchdog Timer Data/Reload Register (WDTD)

Location	7	6	5	4	3	2	1	0	Reset Value
85H				Watchdog Timer Data/Reload					00H

Symbol	Function
WDTD	Initial/Reload value in Watchdog Timer. New value won't be effective until WDT is set.

PCA Timer/Counter Control Register[1] (CCON)

Location	7	6	5	4	3	2	1	0	Reset Value
D8H	CF	CR	-	CCF4	CCF3	CCF2	CCF1	CCF0	00x00000b

1. Bit addressable

Symbol	Function
CF	PCA Counter Overflow Flag Set by hardware when the counter rolls over. CF flags an interrupt if bit ECF in CMOD is set. CF may be set by either hardware or software, but can only cleared by software.
CR	PCA Counter Run control bit Set by software to turn the PCA counter on. Must be cleared by software to turn the PCA counter off.
-	Not implemented, reserved for future use. **Note:** User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.
CCF4	PCA Module 4 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF3	PCA Module 3 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF2	PCA Module 2 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF1	PCA Module 1 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF0	PCA Module 0 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.

EOL Data Sheet

PCA Timer/Counter Mode Register[1] (CMOD)

Location	7	6	5	4	3	2	1	0	Reset Value
D9H	CIDL	WDTE	-	-	-	CPS1	CPS0	ECF	00xxx000b

1. Not bit addressable

Symbol	Function
Symbol	**Function**
CIDL	Counter Idle Control:

CIDL   Counter Idle Control:
0: Programs the PCA Counter to continue functioning during idle mode
1: Programs the PCA Counter to be gated off during idle

WDTE   Watchdog Timer Enable:
0: Disables Watchdog Timer function on PCA module 4
1: Enables Watchdog Timer function on PCA module 4

-       Not implemented, reserved for future use.
Note: User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.

CPS1   PCA Count Pulse Select bit 1

CPS0   PCA Count Pulse Select bit 2

CPS1	CPS0	Selected PCA Input[1]	
0	0	0	Internal clock, $f_{OSC}/6$ in 6 clock mode ($f_{OSC}/12$ in 12 clock mode)
0	1	1	Internal clock, $f_{OSC}/2$ in 6 clock mode ($f_{OSC}/4$ in 12 clock mode)
1	0	2	Timer 0 overflow
1	1	3	External clock at ECI/P1.2 pin
			(max. rate = $f_{OSC}/4$ in 6 clock mode, $f_{OSC}/8$ in 12 clock mode)

1. f_{OSC} = oscillator frequency

ECF   PCA Enable Counter Overflow interrupt:
0: Disables the CF bit in CCON
1: Enables CF bit in CCON to generate an interrupt

PCA Compare/Capture Module Mode Register[1] (CCAPMn)

Location	7	6	5	4	3	2	1	0	Reset Value
DAH	-	ECOM0	CAPP0	CAPN0	MAT0	TOG0	PWM0	ECCF0	00xxx000b
DBH	-	ECOM1	CAPP1	CAPN1	MAT1	TOG1	PWM1	ECCF1	00xxx000b
DCH	-	ECOM2	CAPP2	CAPN2	MAT2	TOG2	PWM2	ECCF2	00xxx000b
DDH	-	ECOM3	CAPP3	CAPN3	MAT3	TOG3	PWM3	ECCF3	00xxx000b
DEH	-	ECOM4	CAPP4	CAPN4	MAT4	TOG4	PWM4	ECCF4	00xxx000b

1. Not bit addressable

Symbol	Function
-	Not implemented, reserved for future use. **Note:** User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.
ECOMn	Enable Comparator 0: Disables the comparator function 1: Enables the comparator function
CAPPn	Capture Positive 0: Disables positive edge capture on CEX[4:0] 1: Enables positive edge capture on CEX[4:0]
CAPNn	Capture Negative 0: Disables negative edge capture on CEX[4:0] 1: Enables negative edge capture on CEX[4:0]
MATn	Match: Set ECOM[4:0] and MAT[4:0] to implement the software timer mode 0: Disables software timer mode 1: A match of the PCA counter with this module's compare/capture register causes the CCFn bit in CCON to be set, flagging an interrupt.
TOGn	Toggle 0: Disables toggle function 1: A match of the PCA counter with this module's compare/capture register causes the the CEXn pin to toggle.
PWMn	Pulse Width Modulation mode 0: Disables PWM mode 1: Enables CEXn pin to be used as a pulse width modulated output
ECCFn	Enable CCF Interrupt 0: Disables compare/capture flag CCF[4:0] in the CCON register to generate an interrupt request. 1: Enables compare/capture flag CCF[4:0] in the CCON register to generate an interrupt request.

SPI Control Register (SPCR)

Location	7	6	5	4	3	2	1	0	Reset Value
D5H	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	00H

Symbol	Function
SPIE	If both SPIE and ES are set to one, SPI interrupts are enabled.
SPE	SPI enable bit. 0: Disables SPI. 1: Enables SPI and connects SS#, MOSI, MISO, and SCK to pins P1.4, P1.5, P1.6, P1.7.
DORD	Data Transmission Order. 0: MSB first in data transmission. 1: LSB first in data transmission.
MSTR	Master/Slave select. 0: Selects Slave mode. 1: Selects Master mode.
CPOL	Clock Polarity 0: SCK is low when idle (Active High). 1: SCK is high when idle (Active Low).
CPHA	Clock Phase control bit. 0: Shift triggered on the leading edge of the clock. 1: Shift triggered on the trailing edge of the clock.
SPR1, SPR0	SPI Clock Rate Select bits. These two bits control the SCK rate of the device configured as master. SPR1 and SPR0 have no effect on the slave. The relationship between SCK and the oscillator frequency, f_{OSC}, is as follows:

SPR1	SPR0	SCK = f_{OSC} divided by
0	0	4
0	1	16
1	0	64
1	1	128

SPI Status Register (SPSR)

Location	7	6	5	4	3	2	1	0	Reset Value
AAH	SPIF	WCOL	-	-	-	-	-	-	00xxxxxxb

Symbol	Function
SPIF	SPI Interrupt Flag. Upon completion of data transfer, this bit is set to 1. If SPIE =1 and ES =1, an interrupt is then generated. This bit is cleared by software.
WCOL	Write Collision Flag. Set if the SPI data register is written to during data transfer. This bit is cleared by software.

SPI Data Register (SPDR)

Location	7	6	5	4	3	2	1	0	Reset Value
86H				SPDR[7:0]					00H

Power Control Register (PCON)

Location	7	6	5	4	3	2	1	0	Reset Value
87H	SMOD1	SMOD0	BOF	POF	GF1	GF0	PD	IDL	00010000b

Symbol	Function
SMOD1	Double Baud rate bit. If SMOD1 = 1, Timer 1 is used to generate the baud rate, and the serial port is used in modes 1, 2, and 3.
SMOD0	FE/SM0 Selection bit. 0: SCON[7] = SM0 1: SCON[7] = FE,
BOF	Brown-out detection status bit, this bit will not be affected by any other reset. BOF should be cleared by software. Power-on reset will also clear the BOF bit. 0: No brown-out. 1: Brown-out occurred
POF	Power-on reset status bit, this bit will not be affected by any other reset. POF should be cleared by software. 0: No Power-on reset. 1: Power-on reset occurred
GF1	General-purpose flag bit.
GF0	General-purpose flag bit.
PD	Power-down bit, this bit is cleared by hardware after exiting from power-down mode. 0: Power-down mode is not activated. 1: Activates Power-down mode.
IDL	Idle mode bit, this bit is cleared by hardware after exiting from idle mode. 0: Idle mode is not activated. 1: Activates idle mode.

Serial Port Control Register (SCON)

Location	7	6	5	4	3	2	1	0	Reset Value
98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00000000b

Symbol	Function
Symbol	**Function**

FE — Set SMOD0 = 1 to access FE bit.
0: No framing error
1: Framing Error. Set by receiver when an invalid stop bit is detected. This bit needs to be cleared by software.

SM0 — SMOD0 = 0 to access SM0 bit.
Serial Port Mode Bit 0

SM1 — Serial Port Mode Bit 1

SM0	SM1	Mode	Description	Baud Rate[1]
0	0	0	Shift Register	$f_{OSC}/6$ (6 clock mode) or $f_{OSC}/12$ (12 clock mode)
0	1	1	8-bit UART	Variable
1	0	2	9-bit UART	$f_{OSC}/32$ or $f_{OSC}/16$ (6 clock mode) or $f_{OSC}/64$ or $f_{OSC}/32$ (12 clock mode)
1	1	3	9-bit UART	Variable

1. f_{OSC} = oscillator frequency

SM2 — Enables the Automatic Address Recognition feature in Modes 2 or 3. If SM2 = 1 then RI will not be set unless the received 9th data bit (RB8) is 1, indicating an address, and the received byte is a given or broadcast address. In Mode 1, if SM2 = 1 then RI will not be activated unless a valid stop bit was received. In Mode 0, SM2 should be 0.

REN — Enables serial reception.
0: to disable reception.
1: to enable reception.

TB8 — The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.

RB8 — In Modes 2 and 3, the 9th data bit that was received. In Mode 1, if SM2 = 0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.

TI — Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission, Must be cleared by software.

RI — Receive interrupt flag. Set by hardware at the end of the8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

Timer/Counter 2 Control Register (T2CON)

Location	7	6	5	4	3	2	1	0	Reset Value
C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2#	CP/RL2#	00H

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflow to be used for the transmit clock.
EXEN2	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/stop control for Timer 2. A logic 1 starts the timer.
C/T2#	Timer or counter select (Timer 2) 0: Internal timer (OSC/6 in 6 clock mode, OSC/12 in 12 clock mode) 1: External event counter (falling edge triggered)
CP/RL2#	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto-reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

Timer/Counter 2 Mode Control (T2MOD)

Location	7	6	5	4	3	2	1	0	Reset Value
C9H	-	-	-	-	-	-	T2OE	DCEN	xxxxxx00b

Symbol	Function
-	Not implemented, reserved for future use. **Note:** User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.
T2OE	Timer 2 Output Enable bit.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

EOL Data Sheet

4.0 FLASH MEMORY PROGRAMMING

The device internal flash memory can be programmed or erased using the following two methods:

- External Host Programming mode
- In-Application Programming (IAP) mode

4.1 External Host Programming Mode

External host programming mode allows the user to program the flash memory directly without using the CPU. External host mode is entered by forcing PSEN# from a logic high to a logic low while RST input is being held continuously high. The device will stay in external host mode as long as RST = 1 and PSEN# = 0.

A Read-ID operation is necessary to "arm" the device in external host mode, and no other external host mode commands can be enabled until a Read-ID is performed. In external host mode, the internal flash memory blocks are accessed through the re-assigned I/O port pins (see Figure 4-1 for details) by an external host, such as a MCU programmer, a PCB tester or a PC-controlled development board.

TABLE   4-1: EXTERNAL HOST MODE COMMANDS FOR SST89E/V564RD[1]

Operation	RST	PSEN#	PROG#/ ALE	EA#	P3[7]	P3[6]	P2[7]	P2[6]	P0[7:0]	P3[5:4] P2[5:0]	P1[7:0]
Read-ID	V_{IH1}	V_{IL}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IL}	V_{IL}	DO	AH	AL
Chip-Erase	V_{IH1}	V_{IL}	$\Downarrow^2$	V_{IH}	V_{IL}	V_{IL}	V_{IL}	V_{IH}	X	X	X
Block-Erase	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IL}	V_{IH}	X	X	X
Sector-Erase	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IH}	V_{IH}	X	AH	AL
Byte-Program	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IL}	DI	AH	AL
Byte-Verify (Read)	V_{IH1}	V_{IL}	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	DO	AH	AL
Select-Block0	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	55H	X
Select-Block1	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	A5H	X
Prog-SC0	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	5AH	X
Prog-SB1	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IH}	X	X	X
Prog-SB2	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IL}	V_{IL}	V_{IH}	V_{IH}	X	X	X
Prog-SB3	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IL}	V_{IH}	V_{IL}	V_{IH}	X	X	X
Enable-Clock-Double	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IL}	X	55H	X

T4-1.2 1207

1. External Host programming mode is guaranteed at 25°C (room temperature) only
2. Symbol $\Downarrow$ signifies a negative pulse and the command is asserted during the low state of PROG#/ALE input. All other combinations of the above input pins are invalid and may result in unexpected behaviors.
Note: V_{IL} = Input Low Voltage; V_{IH} = Input High Voltage; V_{IH1} = Input High Voltage (XTAL, RST); X = Don't care; AL = Address low order byte; AH = Address high order byte; DI = Data Input; DO = Data Output

TABLE 4-2: EXTERNAL HOST MODE COMMANDS FOR SST89E/V554RC[1]

Operation	RST	PSEN#	PROG#/ ALE	EA#	P3[7]	P3[6]	P2[7]	P2[6]	P0[7:0]	P3[5:4] P2[5:0]	P1[7:0]
Read-ID	V_{IH1}	V_{IL}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IL}	V_{IL}	DO	AH	AL
Chip-Erase	V_{IH1}	V_{IL}	$\Downarrow^2$	V_{IH}	V_{IL}	V_{IL}	V_{IL}	V_{IH}	X	X	X
Block-Erase	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IL}	V_{IH}	X	A[15:13]	X
Sector-Erase	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IH}	V_{IH}	X	AH	AL
Byte-Program	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IL}	DI	AH	AL
Byte-Verify (Read)	V_{IH1}	V_{IL}	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	DO	AH	AL
Prog-SC0	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	5AH	X
Prog-SC1	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	AAH	X
Prog-SB1	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IH}	V_{IH}	V_{IH}	X	X	X
Prog-SB2	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IL}	V_{IL}	V_{IH}	V_{IH}	X	X	X
Prog-SB3	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IL}	V_{IH}	V_{IL}	V_{IH}	X	X	X
Enable-Clock-Double	V_{IH1}	V_{IL}	$\Downarrow$	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IL}	X	55H	X

T4-2.1 1207

1. External Host programming mode is guaranteed at 25°C (room temperature) only
2. Symbol $\Downarrow$ signifies a negative pulse and the command is asserted during the low state of PROG#/ALE input.
   All other combinations of the above input pins are invalid and may result in unexpected behaviors.

Note: V_{IL} = Input Low Voltage; V_{IH} = Input High Voltage; V_{IH1} = Input High Voltage (XTAL, RST); X = Don't care; AL = Address low order byte; AH = Address high order byte; DI = Data Input; DO = Data Output; A[15:13] = 0xxb for Block 0 and A[15:13] = 111b for Block 1
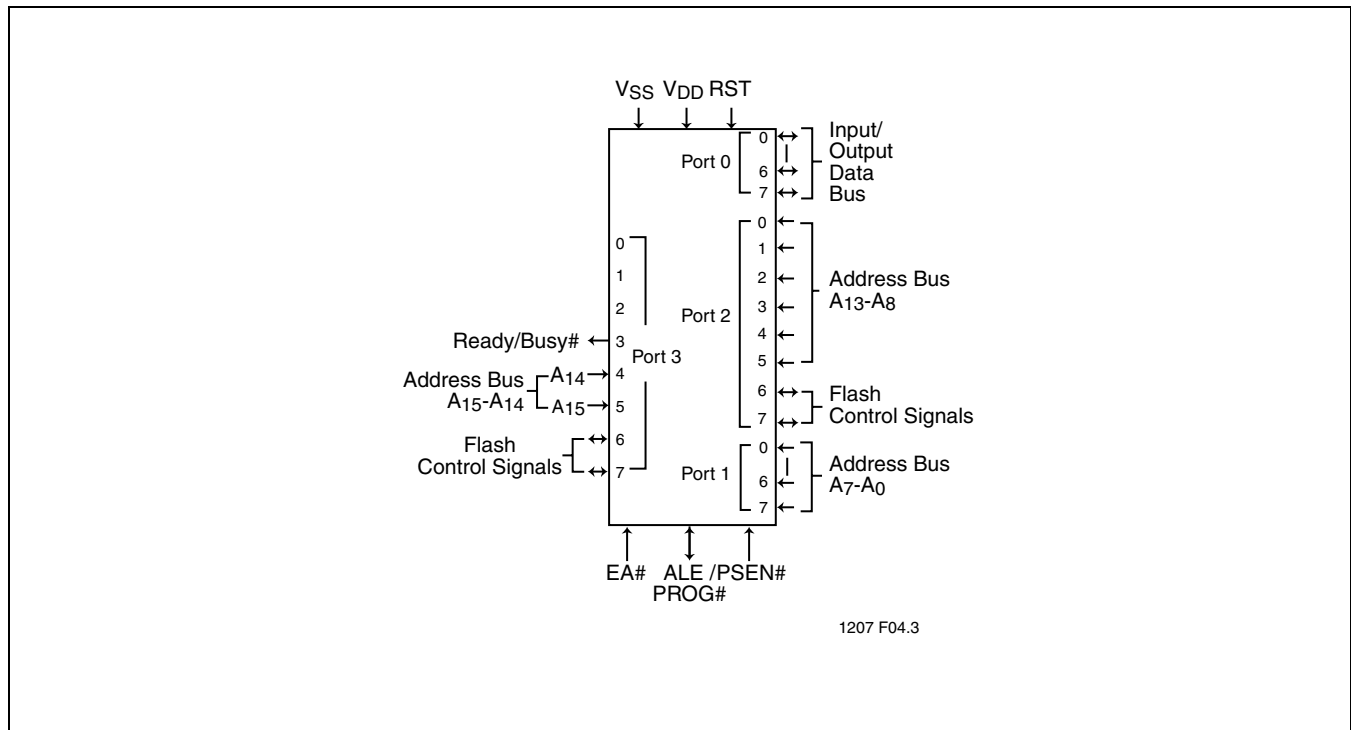

FIGURE 4-1: I/O PIN ASSIGNMENTS FOR EXTERNAL HOST MODE

EOL Data Sheet

4.1.1 Product Identification

The Read-ID command accesses the Signature Bytes that identify the device and the manufacturer as SST. External programmers primarily use these Signature Bytes in the selection of programming algorithms. The Read-ID command is selected by the command code of 0H on P3[7:6] and P2[7:6]. See Figure 13-14 for timing waveforms.

TABLE 4-3: PRODUCT IDENTIFICATION

	Address	Data
Manufacturer's ID	30H	BFH
Device ID		
SST89E564RD	31H	91H
SST89V564RD	31H	90H
SST89E554RC	31H	99H
SST89V554RC	31H	98H

T4-3.0 1207

4.1.2 Arming Command

An arming command sequence must take place before any external host mode sequence command is recognized by the device. This prevents accidental triggering of external host mode commands due to noise or programmer error. The arming command is as follows:

1. PSEN# goes low while RST is high. This will get the machine in external host mode, re-configuring the pins, and turning on the on-chip oscillator.

2. A Read-ID command is issued, and after 1 ms the external host mode commands can be issued.

After the above sequence, all other external host mode commands are enabled. Before the Read-ID command is received, all other external host mode commands received are ignored.

4.1.3 External Host Mode Commands

The external host mode commands are Read-ID, Chip-Erase, Block-Erase, Sector-Erase, Byte-Program, Byte-Verify, Prog-SB1, Prog-SB2, Prog-SB3, Prog-SC0, Prog-SC1, Select-Block0, Select-Block1. See Tables 4-1 and 4-2 for all signal logic assignments, Figure 4-1 for I/O pin assignments, and Table 13-11 for the timing parameters. The critical timing for all Erase and Program commands is generated by an on-chip flash memory controller. The high-to-low transition of the PROG# signal initiates the Erase or Program commands, which are synchronized internally. The Read commands are asynchronous reads, independent of the PROG# signal level.

A detailed description of the external host mode commands follows.

The Select-Block0 command enables Block 0 to be programmed in external host mode. Once this command is executed, all subsequent external host Commands will be directed at Block 0. See Figure 13-15 for timing waveforms. This command applies to SST89E564RD/SST89V564RD only.

The Select-Block1 command enables Block 1 (8 KByte Block) to be programmed. Once this command is executed, all subsequent external host Commands that are directed to the address range below 2000H will be directed at Block 1. The Select-Block1 command only affects the lowest 8 KByte of the program address space. For addresses greater than or equal to 2000H, Block 0 is accessed by default. Upon entering external host mode, Block 1 is selected by default. See Figure 13-15 for timing waveforms. This command applies to SST89E564RD/SST89V564RD only.

The Chip-Erase, Block-Erase, and Sector-Erase commands are used for erasing all or part of the memory array. Erased data bytes in the memory array will be erased to FFH. Memory locations that are to be programmed must be in the erased state prior to programming.

The Chip-Erase command erases all bytes in both memory blocks, regardless of any previous Select-Block0 or Select-Block1 commands. Chip-Erase ignores the Security Lock status and will erase the Security Lock, returning the device to its Unlocked state. The Chip-Erase command will also erase the SC0 bit. Upon completion of Chip-Erase command, Block 1 will be the selected block. See Figure 13-16 for timing waveforms.

The Block-Erase command erases all bytes in the selected memory blocks. This command will not be executed if the security lock is enabled. The selection of the memory block to be erased is determined by the prior execution Select-Block0 or Select-Block1 command. See Figures 13-17 and 13-18 for the timing waveforms.

The Sector-Erase command erases all of the bytes in a sector. The sector size for the flash memory is 128 Bytes. This command will not be executed if the Security lock is enabled. See Figure 13-19 for timing waveforms.

The Byte-Program command is used for programming new data into the memory array. Programming will not take place if any security locks are enabled. See Figure 13-20 for timing waveforms.

The Byte-Verify command allows the user to verify that the device correctly performed an Erase or Program command. This command will be disabled if any security locks are enabled. See Figure 13-23 for timing waveforms.

The Prog-SB1, Prog-SB2, Prog-SB3 commands program the security bits, the functions of these bits are described in the Security Lock section and also in Table 9-1. Once programmed, these bits can only be erased through a Chip-Erase command. See Figure 13-21 for timing waveforms.

Prog-SC0 command programs SC0 bit, which determines the state of SFCF[0] out of reset. Once programmed, SC0 can only be restored to an erased state via a Chip-Erase command. See Figure 13-22 for timing waveforms.

Prog-SC1 command programs SC1 bit, which determines the state of SFCF[1] out of reset. Once programmed, SC1 can only be restored to an erased state via a Chip-Erase command. See Figure 13-22 for timing waveforms. Prog-SC1 is for SST89E554RC/SST89V554RC only.

4.1.4 External Host Mode Clock Source

In external host mode, an internal oscillator will provide clocking for the device, and the oscillator is unaffected by the clock doubler logic. The on-chip oscillator will be turned on as the device enters external host mode; i.e. when PSEN# goes low while RST is high. During external host mode, the CPU core is held in reset. Upon exit from external host mode, the internal oscillator is turned off.

4.1.5 Flash Operation Status Detection Via External Host Handshake

The device provides two methods for an external host to detect the completion of a flash memory operation to optimize the Program or Erase time. The end of a flash memory operation cycle can be detected by:

1. monitoring the Ready/Busy# bit at P3[3];

2. monitoring the Data# Polling bit at P0[3].

4.1.5.1 Ready/Busy# (P3[3])
The progress of the flash memory programming can be monitored by the Ready/Busy# output signal. P3[3] is driven low, some time after ALE/PROG# goes low during a flash memory operation to indicate the Busy# status of the Flash Control Unit (FCU). P3[3] is driven high when the flash programming operation is completed to indicate the ready status.

4.1.5.2 Data# Polling (P0[3])
During a Program operation, any attempts to read (Byte-Verify), while the device is busy, will receive the complement of the data of the last byte loaded (logic low, i.e. "0" for an Erase) on P0[3] with the rest of the bits "0". During a Program operation, the Byte-Verify command is reading the data of the last byte loaded, not the data at the address specified.

4.1.6 Instructions to Perform External Host Mode Commands

To program data into the memory array, apply power supply voltage (V_{DD}) to V_{DD} and RST pins, and perform the following steps:

1. Maintain RST high and set PSEN# from logic high to low, in sequence according to the appropriate timing diagram.

2. Raise EA# High (V_{IH}).

3. Issue Read-ID command to enable the external host mode.

4. Verify that the memory blocks or sectors for programming is in the erased state, FFH. If they are not erased, then erase them using the appropriate Erase command.

5. Select the memory location using the address lines (P3[5:4], P2[5:0], P1[7:0]).

6. Present the data in on P0[7:0].

7. Pulse ALE/PROG#, observing minimum pulse width.

8. Wait for low to high transition on Ready/Busy# (P3[3]).

9. Repeat steps 5 - 8 until programming is finished.

10. Verify the flash memory contents.

4.1.7 Additional Read Commands in External Host Mode

The procedure to issue additional read commands, shown in Table 4-4 below, is the same as the read ID command format, only the address is changed. Here is a short list of useful features:

- Read the status of the security bits (SB1_i, SB2_i, SB3_i).

- Read the configuration bits (SC0_i, SC1_i) status.

- Read the clock mode (EDC_i) status.

Note: Commands shown in Table 4-4 are not the ARMING type.

EOL Data Sheet

TABLE   4-4: ADDITIONAL READ COMMANDS IN EXTERNAL HOST MODE

Address	Data							
60H	X	X	X	SC1_i	SC0_i	SB1_i	SB2_i	SB3_i
61H	X	X	X	X	X	X	EDC_i	X

T4-4.4 1207

X = Don't care

4.2 In-Application Programming Mode

The device offers either 72 or 40 KByte of in-application programmable flash memory. During in-application programming, the CPU of the microcontroller enters IAP mode. The two blocks of flash memory allow the CPU to execute user code from one block, while the other is being erased or reprogrammed concurrently. The CPU may also fetch code from an external memory while all internal flash is being reprogrammed. The mailbox registers (SFST, SFCM, SFAL, SFAH, SFDT and SFCF) located in the special function register (SFR), control and monitor the device's erase and program process.

Table 4-7 outlines the commands and their associated mailbox register settings.

4.2.1 In-Application Programming Mode Clock Source

During IAP mode, both the CPU core and the flash controller unit are driven off the external clock. However, an internal oscillator will provide timing references for Program and Erase operations. The internal oscillator is only turned on when required, and is turned off as soon as the flash operation is completed.

4.2.2 Memory Bank Selection for In-Application Programming Mode

With the addressing range limited to 16 bit, only 64 KByte of program address space is "visible" at any one time. As shown in Table 4-5, bank selection (the configuration of EA# and SFCF[1:0]), allows Block 1 memory to be overlaid on the lowest 8 KByte of Block 0 memory, making Block 1 reachable. The same concept is employed to allow both Block 0 and Block 1 flash to be accessible to IAP operations. Code from a block that is not visible may not be used as a source to program another address. However, a block that is not "visible" may be programmed by code from the other block through mailbox registers.

The device allows IAP code in one block of memory to program the other block of memory, but may not program any location in the same block. If an IAP operation originates physically from Block 0, the target of this operation is implicitly defined to be in Block 1. If the IAP operation originates physically from Block 1, then the target address is implicitly defined to be in Block 0. If the IAP operation originates from external program space, then, the target will depend on the address and the state of bank selection.

4.2.3 IAP Enable Bit

The IAP enable bit, SFCF[6], enables in-application programming mode. Until this bit is set, all flash programming IAP commands will be ignored.

TABLE   4-5: IAP ADDRESS RESOLUTION FOR SST89E/V564RD

EA#	SFCF[1:0]	Address of IAP Inst.	Target Address	Block Being Programmed
1	00	>= 2000H (Block 0)	>= 2000H (Block 0)	None[1]
1	00	>= 2000H (Block 0)	< 2000H (Block 1)	Block 1
1	00	< 2000H (Block 1)	Any (Block 0)	Block 0
1	01, 10, 11	Any (Block 0)	>= 2000H (Block 0)	None[1]
1	01, 10, 11	Any (Block 0)	< 2000H (Block 1)	Block 1
0	00	From external	>= 2000H (Block 0)	Block 0
0	00	From external	< 2000H (Block 1)	Block 1
0	01, 10, 11	From external	Any (Block 0)	Block 0

T4-5.0 1207

1. No operation is performed because code from one block may not program the same originating block
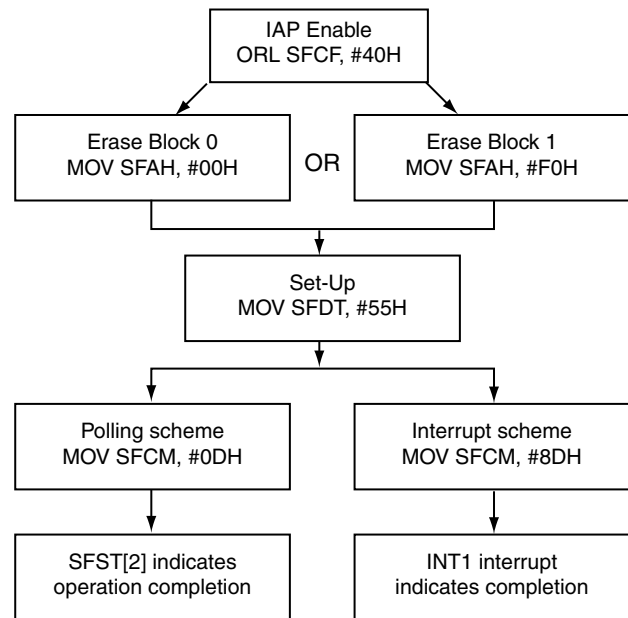
4.2.4 In-Application Programming Mode Commands

All of the following commands can only be initiated in the IAP mode. In all situations, writing the control byte to the SFCM register will initiate all of the operations. All commands will not be enabled if the security locks are enabled on the selected memory block.

The Program command is for programming new data into the memory array. The portion of the memory array to be programmed should be in the erased state, FFH. If the memory is not erased, it should first be erased with an appropriate Erase command. **Warning: Do not attempt to write (program or erase) to a block that the code is currently fetching from. This will cause unpredictable program behavior and may corrupt program data.**

4.2.4.1 Chip-Erase

The Chip-Erase command erases all bytes in both memory blocks. This command is only allowed when EA#=0 (external memory execution). Additionally this command is not permitted when the device is in level 4 locking. In all other instances, this command ignores the Security Lock status and will erase the security lock bits and re-map bits.

```
        IAP Enable
       ORL SFCF, #40H
             |
             v
          Set-Up
       MOV SFDT, #55H
         /        \
        v          v
  Polling scheme    Interrupt scheme
  MOV SFCM, #01H    MOV SFCM, #81H
        |               |
        v               v
  SFST[2] indicates  INT1 interrupt
  operation          indicates completion
  completion
```
1207 F43.0

4.2.4.2 Block-Erase

The Block-Erase command erases all bytes in one of the two memory blocks (Block 0 or Block 1). The selection of the memory block to be erased is determined by the (SFAH[7]) of the SuperFlash Address Register. For SST89x564RD, refer to Table 4-5. For SST89x554RC, if SFAH[7] = 0b, the primary flash memory Block 0 is selected. If SFAH[7:4] = EH, the secondary flash memory Block 1 is selected. The Block-Erase command sequence for SST89x554RC is as follows:

```
        IAP Enable
       ORL SFCF, #40H
         /        \
        v          v
  Erase Block 0  OR  Erase Block 1
  MOV SFAH, #00H     MOV SFAH, #F0H
         \        /
          v      v
          Set-Up
       MOV SFDT, #55H
         /        \
        v          v
  Polling scheme    Interrupt scheme
  MOV SFCM, #0DH    MOV SFCM, #8DH
        |               |
        v               v
  SFST[2] indicates  INT1 interrupt
  operation          indicates completion
  completion
```
1207 F44.2

4.2.4.3 Sector-Erase

The Sector-Erase command erases all of the bytes in a sector. The sector size for the flash memory blocks is 128 Bytes. The selection of the sector to be erased is determined by the contents of SFAH and SFAL.

```
        IAP Enable
       ORL SFCF, #40H
             |
             v
    Program sector address
    MOV SFAH, #sector_addressH
    MOV SFAL, #sector_addressL
         /        \
        v          v
  Polling scheme    Interrupt scheme
  MOV SFCM, #0BH    MOV SFCM, #8BH
        |               |
        v               v
  SFST[2] indicates  INT1 interrupt
  operation          indicates completion
  completion
```
1207 F45.1

4.2.4.4 Byte-Program

The Byte-Program command programs data into a single byte. The address is determined by the contents of SFAH and SFAL. The data byte is in SFDT.

```
┌─────────────────────┐
│   IAP Enable        │
│   ORL SFCF, #40H    │
└─────────────────────┘
          │
          ▼
┌─────────────────────────┐
│  Program byte address   │
│  MOV SFAH, #byte_addressH│
│  MOV SFAL, #byte_addressL│
└─────────────────────────┘
          │
          ▼
┌─────────────────────────┐
│  Move data to SFDT      │
│  MOV SFDT, #data        │
└─────────────────────────┘
       │         │
       ▼         ▼
┌──────────────┐ ┌──────────────┐
│ Polling scheme│ │Interrupt scheme│
│ MOV SFCM, #0EH│ │ MOV SFCM, #8EH│
└──────────────┘ └──────────────┘
       │                │
       ▼                ▼
┌──────────────┐ ┌──────────────┐
│ SFST[2] indicates│ │ INT1 interrupt│
│ operation completion│ │ indicates completion│
└──────────────┘ └──────────────┘
```

1207 F46.1
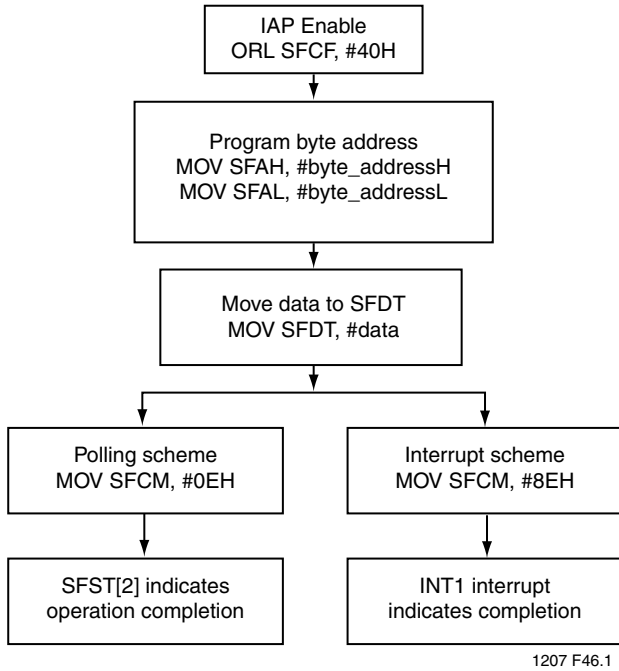
4.2.4.5 Byte-Verify

The Byte-Verify command allows the user to verify that the device has correctly performed an Erase or Program command. Byte-Ve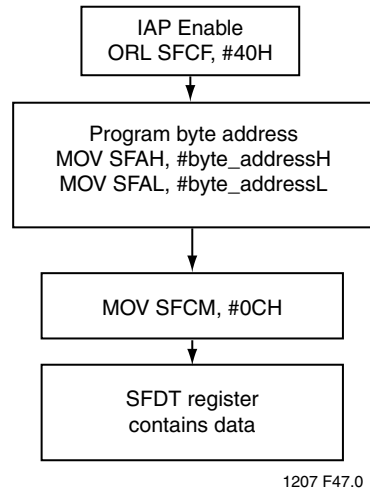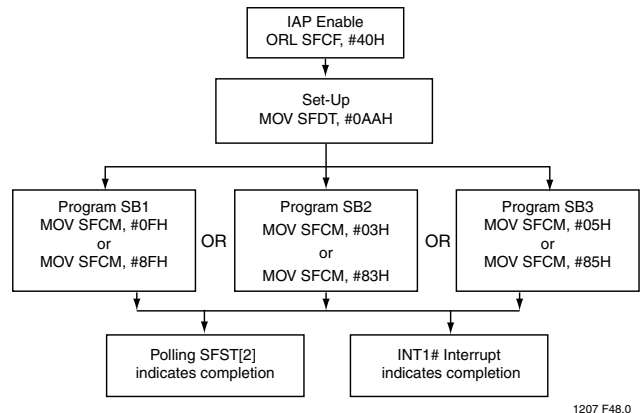rify command returns the data byte in SFDT if the command is successful. The user is required to check that the previous flash operation has fully completed before issuing a Byte-Verify. Byte-Verify command execution time is short enough that there is no need to poll for command completion and no interrupt is generated.

```
┌─────────────────────┐
│   IAP Enable        │
│   ORL SFCF, #40H    │
└─────────────────────┘
          │
          ▼
┌─────────────────────────┐
│  Program byte address   │
│  MOV SFAH, #byte_addressH│
│  MOV SFAL, #byte_addressL│
└─────────────────────────┘
          │
          ▼
┌─────────────────────────┐
│  MOV SFCM, #0CH         │
└─────────────────────────┘
          │
          ▼
┌─────────────────────────┐
│  SFDT register          │
│  contains data          │
└─────────────────────────┘
```

1207 F47.0

4.2.4.6 Prog-SB3, Prog-SB2, Prog-SB1

Prog-SB3, Prog-SB2, Prog-SB1 commands are used to program the security bits (see Table 9-1). Completion of any of these commands, the security options will be updated immediately.

Security bits previously in un-programmed state can be programmed by these commands. Prog-SB3, Prog-SB2 and Prog-SB1 commands should only reside in Block 1 or external code memory.

```
┌─────────────────────┐
│   IAP Enable        │
│   ORL SFCF, #40H    │
└─────────────────────┘
          │
          ▼
┌─────────────────────┐
│   Set-Up            │
│   MOV SFDT, #0AAH   │
└─────────────────────┘
     │     │     │
     ▼     ▼     ▼
┌──────────┐OR┌──────────┐OR┌──────────┐
│Program SB1│ │Program SB2│ │Program SB3│
│MOV SFCM,#0FH│ │MOV SFCM,#03H│ │MOV SFCM,#05H│
│   or     │ │   or     │ │   or     │
│MOV SFCM,#8FH│ │MOV SFCM,#83H│ │MOV SFCM,#85H│
└──────────┘ └──────────┘ └──────────┘
        │              │
        ▼              ▼
┌──────────────┐ ┌──────────────┐
│Polling SFST[2]│ │INT1# Interrupt│
│indicates completion│ │indicates completion│
└──────────────┘ └──────────────┘
```
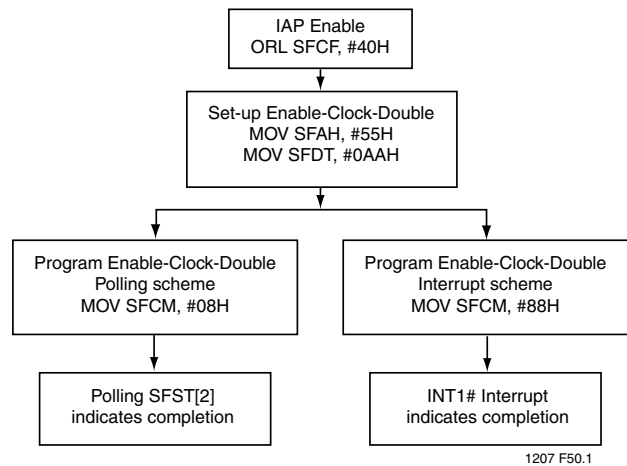
1207 F48.0

4.2.4.7 Prog-SC0, Prog-SC1

Prog-SC0 command is used to program the SC0 bit. This command only changes the SC0 bit and has no effect on BSEL bit until after a reset cycle.

SC0 bit previously in un-programmed state can be programmed by this command. The Prog-SC0 command should reside only in Block 1 or external code memory.

Prog-SC1 command is used to program the SC1 bit. This command only changes the SC1 bit and has no effect on SFCF[1] bit until after a reset cycle.

SC1 bit previously in un-programmed state can be programmed by this command. The Prog-SC1 command should reside only in Block 1 or external code memory.

```
┌─────────────────────────┐
│       IAP Enable        │
│     ORL SFCF, #40H      │
└─────────────────────────┘
        │
   ┌────┴────────────┐
   ▼                 ▼
┌──────────────┐  ┌──────────────┐
│ Set-up       │  │ Set-up       │
│ Program SC0  │  │ Program SC1  │
│ MOV SFAH,#5AH│  │ MOV SFAH,#0AAH│
│ MOV SFDT,#0AAH│ │ MOV SFDT,#0AAH│
└──────────────┘  └──────────────┘
   │                 │
   ▼                 ▼
┌──────────────┐  ┌──────────────┐
│ Program SC0  │  │ Program SC0  │
│ or SC1 -     │  │ or SC1 -     │
│ Polling scheme│ │ Interrupt scheme│
│ MOV SFCM,#09H│  │ MOV SFCM,#89H│
└──────────────┘  └──────────────┘
   │                 │
   ▼                 ▼
┌──────────────┐  ┌──────────────┐
│ Polling SFST[2]│ │ INT1# Interrupt│
│ indicates    │  │ indicates    │
│ completion   │  │ completion   │
└──────────────┘  └──────────────┘
                         1207 F49.2
```

4.2.4.8 Enable-Clock-Double

Enable-Clock-Double command is used to make the MCU run at 6 clocks per machine cycle. The standard (default) is 12 clocks per machine cycle (i.e. clock double command disabled).

.

```
┌─────────────────────────┐
│       IAP Enable        │
│     ORL SFCF, #40H      │
└─────────────────────────┘
        │
        ▼
┌─────────────────────────┐
│ Set-up Enable-Clock-Double│
│     MOV SFAH, #55H      │
│     MOV SFDT, #0AAH     │
└─────────────────────────┘
        │
   ┌────┴────────────┐
   ▼                 ▼
┌──────────────┐  ┌──────────────┐
│ Program      │  │ Program      │
│ Enable-Clock-Double│ │ Enable-Clock-Double│
│ Polling scheme│ │ Interrupt scheme│
│ MOV SFCM,#08H│  │ MOV SFCM,#88H│
└──────────────┘  └──────────────┘
   │                 │
   ▼                 ▼
┌──────────────┐  ┌──────────────┐
│ Polling SFST[2]│ │ INT1# Interrupt│
│ indicates    │  │ indicates    │
│ completion   │  │ completion   │
└──────────────┘  └──────────────┘
                         1207 F50.1
```

There are no IAP counterparts for the external host commands Select-Block0 and Select-Block1.
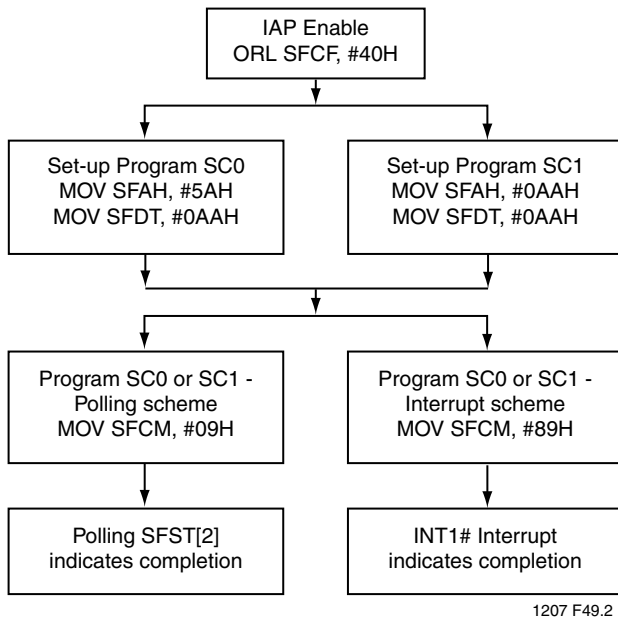
4.2.5 Polling

A command that uses the polling method to detect flash operation completion should poll on the FLASH_BUSY bit (SFST[2]). When FLASH_BUSY de-asserts (logic 0), the device is ready for the next operation.

MOVC instruction may also be used for verification of the Programming and Erase operation of the flash memory. MOVC instruction will fail if it is directed at a flash block that is still busy.

4.2.6 Interrupt Termination

If interrupt termination is selected, (SFCM[7] is set), then an interrupt (INT1) will be generated to indicate flash operation completion. Under this condition, the INT1 becomes an internal interrupt source. The INT1# pin can now be used as a general purpose port pin and it cannot be the source of External Interrupt 1 during in-application programming.

In order to use an interrupt to signal flash operation termination. EX1 and EA bits of IE register must be set. The IT1 bit of TCON register must also be set for edge trigger detection.

EOL Data Sheet

TABLE 4-6: IAP Commands[1] for SST89E/V564RD

Operation	SFCM [6:0][2]	SFDT [7:0]	SFAH [7:0]	SFAL [7:0]
Chip-Erase[3]	01H	55H	X[4]	X
Block-Erase[5]	0DH	55H	AH	X
Sector-Erase[5]	0BH	X	AH[6]	AL[7]
Byte-Program[5]	0EH	DI[8]	AH	AL
Byte-Verify (Read)[5]	0CH	DO[8]	AH	AL
Prog-SB1[9]	0FH	AAH	X	X
Prog-SB2[9]	03H	AAH	X	X
Prog-SB3[9]	05H	AAH	X	X
Prog-SC0[9]	09H	AAH	5AH	X
Enable-Clock-Double[9]	08H	AAH	55H	X

T4-6.4 1207

1. SFCF[6]=1 enables IAP commands; SFCF[6]=0 disables IAP commands.
2. Interrupt/Polling enable for flash operation completion
   SFCM[7] =1: Interrupt enable for flash operation completion
        0: polling enable for flash operation completion
3. Chip-Erase only functions in IAP mode when EA#=0 (external memory execution) and device is not in level 4 locking.
4. X can be V_{IL} or V_{IH}, but no other value.
5. Refer to Table 4-5 for address resolution
6. AH = Address high order byte
7. AL = Address low order byte
8. DI = Data Input, DO = Data Output, all other values are in hex.
9. Instruction must be located in Block 1 or external code memory.
Note: DISIAPL pin in PLCC or TQFP will also disable IAP commands if it is externally pulled low when reset.

TABLE 4-7: IAP Commands[1] for SST89E/V554RC

Operation	SFCM [6:0][2]	SFDT [7:0]	SFAH [7:0]	SFAL [7:0]
Chip-Erase[3]	01H	55H	X[4]	X
Block-Erase	0DH	55H	AH[5]	X
Sector-Erase	0BH	X	AH	AL[6]
Byte-Program	0EH	DI[7]	AH	AL
Byte-Verify (Read)[8]	0CH	DO[7]	AH	AL
Prog-SB1[9]	0FH	AAH	X	X
Prog-SB2[9]	03H	AAH	X	X
Prog-SB3[9]	05H	AAH	X	X
Prog-SC0[9]	09H	AAH	5AH	X
Prog-SC1[9]	09H	AAH	AAH	X
Enable-Clock-Double[9]	08H	AAH	55H	X

T4-7.2 1207

1. SFCF[6]=1 enables IAP commands; SFCF[6]=0 disables IAP commands.
2. Interrupt/Polling enable for flash operation completion
   SFCM[7] =1: Interrupt enable for flash operation completion
        0: polling enable for flash operation completion
3. Chip-Erase only functions in IAP mode when EA#=0 (external memory execution) and device is not in level 4 locking.
4. X can be V_{IL} or V_{IH}, but no other value.
5. AH = Address high order byte
6. AL = Address low order byte
7. DI = Data Input, DO = Data Output, all other values are in hex.
8. SFAH[7:5] = 111b selects Block 1, SFAH[7] = 0b selects Block 0
9. Instruction must be located in Block 1 or external code memory.
Note: DISIAPL pin in PLCC or TQFP will also disable IAP commands if it is externally pulled low when reset.

5.0 TIMERS/COUNTERS

5.1 Timers

The device has three 16-bit registers that can be used as either timers or event counters. The three timers/counters are denoted Timer 0 (T0), Timer 1 (T1), and Timer 2 (T2). Each is designated a pair of 8-bit registers in the SFRs. The pair consists of a most significant (high) byte and least significant (low) byte. The respective registers are TL0, TH0, TL1, TH1, TL2, and TH2.

5.2 Timer Set-up

Refer to Table 3-10 for TMOD, TCON, and T2CON registers regarding timers T0, T1, and T2. The following tables provide TMOD values to be used to set up Timers T0, T1, and T2.

Except for the baud rate generator mode, the values given for T2CON do not include the setting of the TR2 bit. Therefore, bit TR2 must be set separately to turn the timer on.

TABLE 5-1: TIMER/COUNTER 0

			TMOD	
	Mode	**Function**	**Internal Control[1]**	**External Control[2]**
Used as Timer	0	13-bit Timer	00H	08H
	1	16-bit Timer	01H	09H
	2	8-bit Auto-Reload	02H	0AH
	3	Two 8-bit Timers	03H	0BH
Used as Counter	0	13-bit Timer	04H	0CH
	1	16-bit Timer	05H	0DH
	2	8-bit Auto-Reload	06H	0EH
	3	Two 8-bit Timers	07H	0FH

T5-1.0 1207

1. The Timer is turned ON/OFF by setting/clearing bit TR0 in the software.
2. The Timer is turned ON/OFF by the 1 to 0 transition on INT0# (P3.2) when TR0 = 1 (hardware control).

TABLE 5-2: TIMER/COUNTER 1

			TMOD	
	Mode	**Function**	**Internal Control[1]**	**External Control[2]**
Used as Timer	0	13-bit Timer	00H	80H
	1	16-bit Timer	10H	90H
	2	8-bit Auto-Reload	20H	A0H
	3	Does not run	30H	B0H
Used as Counter	0	13-bit Timer	40H	C0H
	1	16-bit Timer	50H	D0H
	2	8-bit Auto-Reload	60H	E0H
	3	Not available	-	-

T5-2.0 1207

1. The Timer is turned ON/OFF by setting/clearing bit TR1 in the software.
2. The Timer is turned ON/OFF by the 1 to 0 transition on INT1# (P3.3) when TR1 = 1 (hardware control).

TABLE 5-3: TIMER/COUNTER 2

		T2CON	
	Mode	**Internal Control[1]**	**External Control[2]**
Used as Timer	16-bit Auto-Reload	00H	08H
	16-bit Capture	01H	09H
	Baud rate generator receive and transmit same baud rate	34H	36H
	Receive only	24H	26H
	Transmit only	14H	16H
Used as Counter	16-bit Auto-Reload	02H	0AH
	16-bit Capture	03H	0BH

T5-3.0 1207

1. Capture/Reload occurs only on timer/counter overflow.
2. Capture/Reload occurs on timer/counter overflow and a 1 to 0 transition on T2EX (P1.1) pin except when Timer 2 is used in the baud rate generating mode.

EOL Data Sheet

5.3 Programmable Clock-Out

A 50% duty cycle clock can be programmed to come out on P1.0. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed:

1. to input the external clock for Timer/Counter 2, or

2. to output a 50% duty cycle clock ranging from 122 Hz to 8 MHz at a 16 MHz operating frequency (61 Hz to 4 MHz in 12 clock mode).

To configure Timer/Counter 2 as a clock generator, bit C/#T2 (in T2CON) must be cleared and bit T2OE in T2MOD must be set. Bit TR2 (T2CON.2) also must be set to start the timer.

The Clock-Out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L) as shown in this equation:

$$\frac{\text{Oscillator Frequency}}{n \times (65536 - \text{RCAP2H, RCAP2L})}$$

$$n = \quad 2 \text{ (in 6 clock mode)}$$
$$4 \text{ (in 12 clock mode)}$$

Where (RCAP2H, RCAP2L) = the contents of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

In the Clock-Out mode, Timer 2 roll-overs will not generate an interrupt. This is similar to when it is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and the Clock-Out frequency will not be the same.

6.0 SERIAL I/O

6.1 Full-Duplex, Enhanced UART

The device serial I/O port is a full-duplex port that allows data to be transmitted and received simultaneously in hardware by the transmit and receive registers, respectively, while the software is performing other tasks. The transmit and receive registers are both located in the Serial Data Buffer (SBUF) special function register. Writing to the SBUF register loads the transmit register, and reading from the SBUF register obtains the contents of the receive register.

The UART has four modes of operation which are selected by the Serial Port Mode Specifier (SM0 and SM1) bits of the Serial Port Control (SCON) special function register. In all four modes, transmission is initiated by any instruction that uses the SBUF register as a destination register. Reception is initiated in mode 0 when the Receive Interrupt (RI) flag bit of the Serial Port Control (SCON) SFR is cleared and the Reception Enable/ Disable (REN) bit of the SCON register is set. Reception is initiated in the other modes by the incoming start bit if the REN bit of the SCON register is set.

6.1.1 Framing Error Detection

Framing Error Detection is a feature, which allows the receiving controller to check for valid stop bits in modes 1, 2, or 3. Missing stops bits can be caused by noise in serial lines or from simultaneous transmission by two CPUs.

Framing Error Detection is selected by going to the PCON register and changing SMOD0 = 1 (see Figure 6-1). If a stop bit is missing, the Framing Error bit (FE) will be set. Software may examine the FE bit after each reception to check for data errors. After the FE bit has been set, it can only be cleared by software. Valid stop bits do not clear FE. When FE is enabled, RI rises on the stop bit, instead of the last data bit (see Figure 6-2 and Figure 6-3).
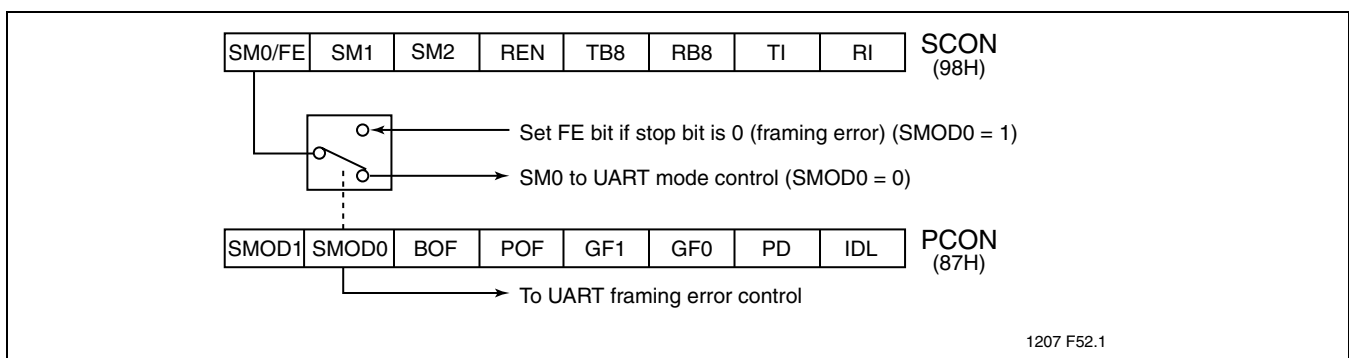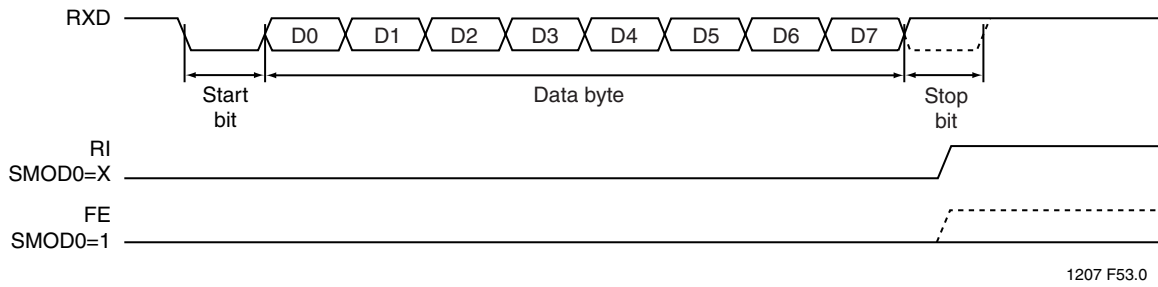

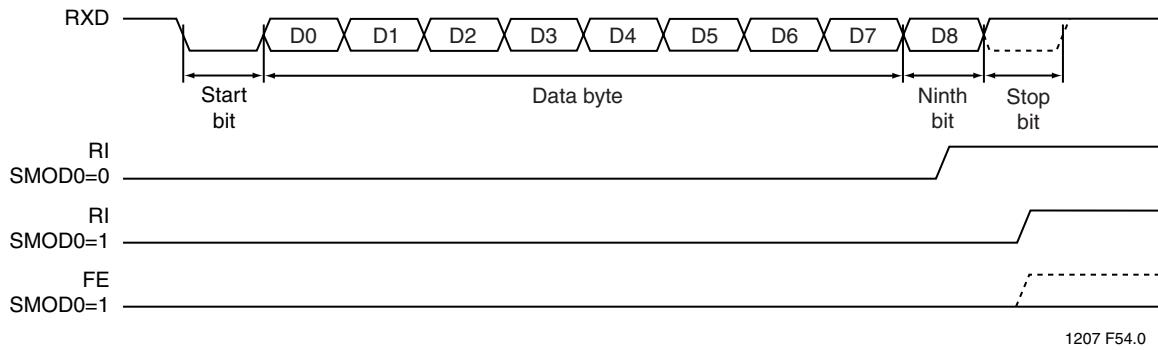**FIGURE   6-1: FRAMING ERROR BLOCK DIAGRAM**

RXD

| | D0 | D1 | D2 | D3 | D4 | D5 | D6 | D7 | |

Start
bit

Data byte

Stop
bit

RI
SMOD0=X

FE
SMOD0=1

1207 F53.0

FIGURE   6-2: UART TIMINGS IN MODE 1

RXD

| | D0 | D1 | D2 | D3 | D4 | D5 | D6 | D7 | D8 | |

Start
bit

Data byte

Ninth
bit

Stop
bit

RI
SMOD0=0

RI
SMOD0=1

FE
SMOD0=1

1207 F54.0

FIGURE   6-3: UART TIMINGS IN MODES 2 AND 3

45

EOL Data Sheet

6.1.2 Automatic Address Recognition

Automatic Address Recognition helps to reduce the MCU time and power required to talk to multiple serial devices. Each device is hooked together sharing the same serial link with its own address. In this configuration, a device is only interrupted when it receives its own address, thus eliminating the software overhead to compare addresses.

This same feature helps to save power because it can be used in conjunction with idle mode to reduce the system's overall power consumption. Since there may be multiple slaves hooked up serial to one master, only one slave would have to be interrupted from idle mode to respond to the master's transmission. Automatic Address Recognition (AAR) allows the other slaves to remain in idle mode while only one is interrupted. By limiting the number of interruptions, the total current draw on the system is reduced.

There are two ways to communicate with slaves: a group of them at once, or all of them at once. To communicate with a group of slaves, the master sends out an address called the given address. To communicate with all the slaves, the master sends out an address called the "broadcast" address.

AAR can be configured as mode 2 or 3 (9-bit modes) and setting the SM2 bit in SCON. Each slave has its own SM2 bit set waiting for an address byte (9th bit = 1). The Receive Interrupt (RI) flag will only be set when the received byte matches either the given address or the broadcast address. Next, the slave then clears its SM2 bit to enable reception of the data bytes (9th bit = 0) from the master. When the 9th bit = 1, the master is sending an address. When the 9th bit = 0, the master is sending actual data.

If mode 1 is used, the stop bit takes the place of the 9th bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit. Note that mode 0 cannot be used. Setting SM2 bit in the SCON register in mode 0 will have no effect.

Each slave's individual address is specified by SFR SADDR. SFR SADEN is a mask byte that defines "don't care" bits to form the given address when combined with SADDR. See the example below:

Slave 1

SADDR = 1111 0001

SADEN = 1111 1010

 GIVEN = 1111 0X0X

Slave 2

SADDR = 1111 0011

SADEN = 1111 1001

 GIVEN = 1111 0XX1

6.1.2.1 Using the Given Address to Select Slaves

Any bits masked off by a 0 from SADEN become a "don't care" bit for the given address. Any bit masked off by a 1, becomes ANDED with SADDR. The "don't cares" provide flexibility in the user-defined addresses to address more slaves when using the given address.

Shown in the example above, Slave 1 has been given an address of 1111 0001 (SADDR). The SADEN byte has been used to mask off bits to a given address to allow more combinations of selecting Slave 1 and Slave 2. In this case for the given addresses, the last bit (LSB) of Slave 1 is a "don't care" and the last bit of Slave 2 is a 1. To communicate with Slave 1 and Slave 2, the master would need to send an address with the last bit equal to 1 (e.g. 1111 0001) since Slave 1's last bit is a don't care and Slave 2's last bit has to be a 1. To communicate with Slave 1 alone, the master would send an address with the last bit equal to 0 (e.g. 1111 0000), since Slave 2's last bit is a 1. See the table below for other possible combinations.

Select Slave 1 Only		
Slave 1	**Given Address**	**Possible Addresses**
	1111 0X0X	1111 0000 1111 0100

Select Slave 2 Only		
Slave 2	**Given Address**	**Possible Addresses**
	1111 0XX1	1111 0111 1111 0011

Select Slaves 1 & 2	
Slaves 1 & 2	**Possible Addresses**
	1111 0001 1111 0101

If the user added a third slave such as the example below:

Slave 3

SADDR = 1111 1001

SADEN = 1111 0101

 GIVEN = 1111 X0X1

Select Slave 3 Only		
Slave 2	Given Address	Possible Addresses
	1111 X0X1	1111 1011
		1111 1001

The user could use the possible addresses above to select slave 3 only. Another combination could be to select slave 2 and 3 only as shown below.

Select Slaves 2 & 3 Only	
Slaves 2 & 3	Possible Addresses
	1111 0011

More than one slave may have the same SADDR address as well, and a given address could be used to modify the address so that it is unique.

6.1.2.2 Using the Broadcast Address to Select Slaves

Using the broadcast address, the master can communicate with all the slaves at once. It is formed by performing a logical OR of SADDR and SADEN with 0s in the result treated as "don't cares".

Slave 1

$$
\begin{array}{rcl}
1111\ 0001 & = & \text{SADDR} \\
+1111\ 1010 & = & \text{SADEN} \\
\hline
1111\ 1X11 & = & \text{Broadcast}
\end{array}
$$

"Don't cares" allow for a wider range in defining the broadcast address, but in most cases, the broadcast address will be FFH.

On reset, SADDR and SADEN are "0". This produces an given address of all "don't cares" as well as a broadcast address of all "don't cares." This effectively disables Automatic Addressing mode and allows the microcontroller to function as a standard 8051, which does not make use of this feature.

6.2 Serial Peripheral Interface

6.2.1 SPI Features

- Master or slave operation
- 10 MHz bit frequency (max)
- LSB first or MSB first data transfer
- Four programmable bit rates
- End of transmission (SPIF)
- Write collision flag protection (WCOL)
- Wake up from idle mode (slave mode only)

6.2.2 SPI Description

The serial peripheral interface (SPI) allows high-speed synchronous data transfer between the SST89E/V564RD / SST89E/V554RC and peripheral devices or between several SST89E/V564RD / SST89E/V554RC devices.

Figure 6-4 shows the correspondence between master and slave SPI devices. The SCK pin is the clock output and input for the master and slave modes, respectively. The SPI clock generator will start following a write to the master devices SPI data register. The written data is then shifted out of the MOSI pin on the master device into the MOSI pin of the slave device. Following a complete transmission of one byte of data, the SPI clock generator is stopped and the SPIF flag is set. An SPI interrupt request will be generated if the SPI Interrupt Enable bit (SPIE) and the Serial Port Interrupt Enable bit (ES) are both set.

An external master drives the Slave Select input pin, SS#/ P1[4], low to select the SPI module as a slave. If SS#/P1[4] has not been driven low, then the slave SPI unit is not active and the MOSI/P1[5] port can also be used as an input port pin.

CPHA and CPOL control the phase and polarity of the SPI clock. Figures 6-5 and 6-6 show the four possible combinations of these two bits.
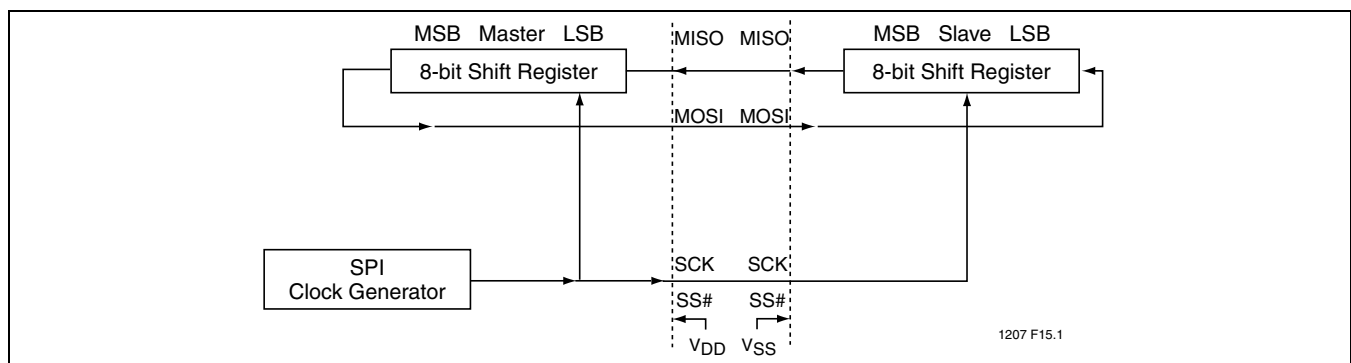

FIGURE   6-4: SPI MASTER-SLAVE INTERCONNECTION
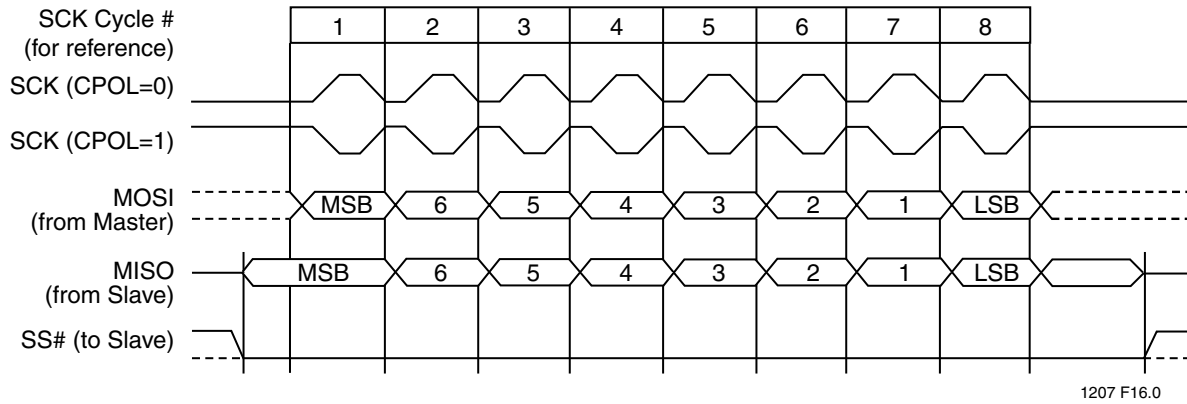
6.2.3 SPI Transfer Formats

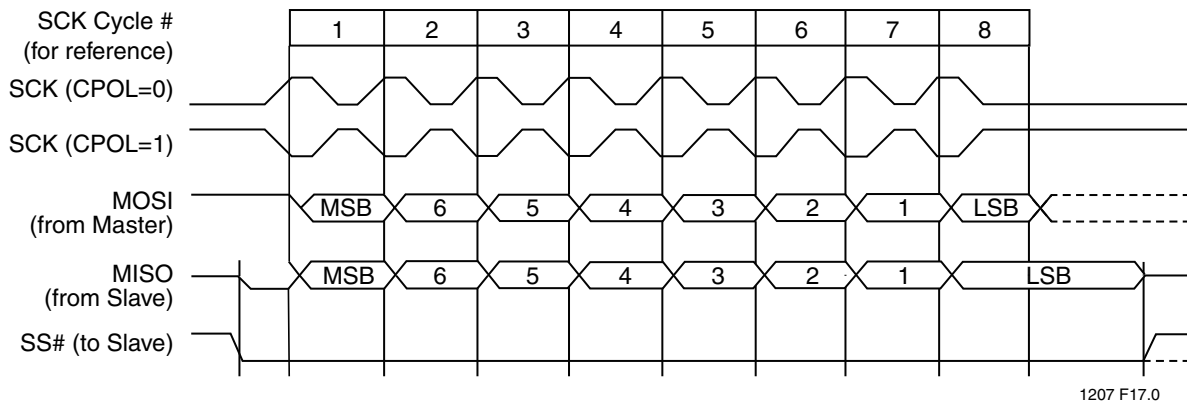**FIGURE   6-5: SPI Transfer Format with CPHA = 0**

FIGURE   6-6: SPI Transfer Format with CPHA = 1

7.0 WATCHDOG TIMER

The device offers a programmable Watchdog Timer (WDT) for fail safe protection against software deadlock and automatic recovery.

To protect the system against software deadlock, the user software must refresh the WDT within a user-defined time period. If the software fails to do this periodical refresh, an internal hardware reset will be initiated if enabled (WDRE= 1). The software can be designed such that the WDT times out if the program does not work properly.

The WDT in the device uses the system clock (XTAL1) as its time base. So strictly speaking, it is a watchdog counter rather than a watchdog timer. The WDT register will increment every 344,064 crystal clocks. The upper 8-bits of the time base register (WDTD) are used as the reload register of the WDT.

The WDTS flag bit is set by WDT overflow and is not changed by WDT reset. User software can clear WDTS by writing "1" to it.

Figure 7-1 provides a block diagram of the WDT. Two SFRs (WDTC and WDTD) control watchdog timer operation. During idle mode, WDT operation is temporarily suspended, and resumes upon an interrupt exit from idle.

The time-out period of the WDT is calculated as follows:

$$\text{Period} = (255 - \text{WDTD}) * 344064 * 1/f_{\text{CLK (XTAL1)}}$$

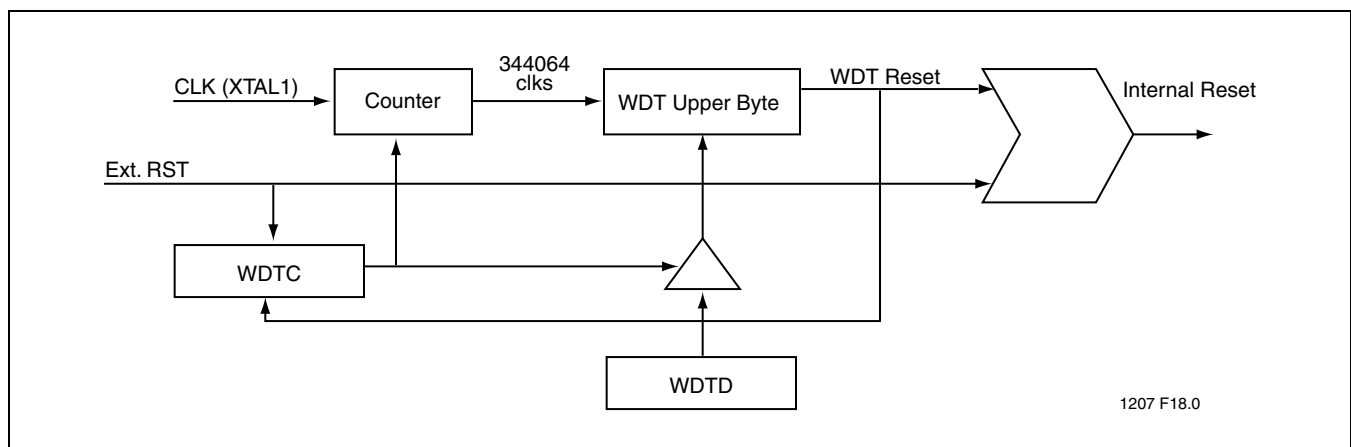where WDTD is the value loaded into the WDTD register and f_{OSC} is the oscillator frequency.

FIGURE   7-1: BLOCK DIAGRAM OF PROGRAMMABLE WATCHDOG TIMER

EOL Data Sheet

8.0 PROGRAMMABLE COUNTER ARRAY

The Programmable Counter Array (PCA) present on the SST89E/V554RC and SST89E/V564RD is a special 16-bit timer that has five 16-bit capture/compare modules. Each of the modules can be programmed to operate in one of four modes: rising and/or falling edge capture, software timer, high-speed output, or pulse width modulator. The 5th module can be programmed as a Watchdog Timer in addition to the other four modes. Each module has a pin associated with it in port 1. Module 0 is connected to P1.3 (CEX0), module 1 to P1[4] (CEX1), module 2 to P1[5] (CEX2), module 3 to P1[6] (CEX3), and module 4 to P1[7] (CEX4). PCA configuration is shown in Figure 8-1.

8.1 PCA Overview

PCA provides more timing capabilities with less CPU intervention than the standard timer/counter. Its advantages include reduced software overhead and improved accuracy.

The PCA consists of a dedicated timer/counter which serves as the time base for an array of five compare/capture modules. Figure 8-1 shows a block diagram of the PCA.

PCA. External events associated with modules are shared with corresponding Port 1 pins. Modules not using the port pins can still be used for standard I/O.

Each of the five modules can be programmed in any of the following modes:

- Rising and/or falling edge capture
- Software timer
- High speed output
- Watchdog Timer (Module 4 only)
- Pulse Width Modulator (PWM)

8.2 PCA Timer/Counter

The PCA timer is a free-running 16-bit timer consisting of registers CH and CL (the high and low bytes of the count values). The PCA timer is common time base for all five modules and can be programmed to run at: 1/6 the oscillator frequency, 1/2 the oscillator frequency, Timer 0 overflow, or the input on the ECI pin (P1.2). The timer/counter source is determined from the CPS1 and CPS0 bits in the CMOD SFR as follows (see "PCA Timer/Counter Mode Register (CMOD)" on page 28):

TABLE 8-1: PCA TIMER/COUNTER SOURCE

CPS1	CPS0	12 Clock Mode	6 Clock Mode
0	0	f_{OSC} /12	f_{OSC} /6
0	1	f_{OSC} /4	f_{OSC} /2
1	0	Timer 0 overflow	Timer 0 overflow
1	1	External clock at ECI pin (maximum rate = f_{OSC} /8)	External clock at ECI pin (maximum rate = f_{OSC} /4)

T8-1.0 1207
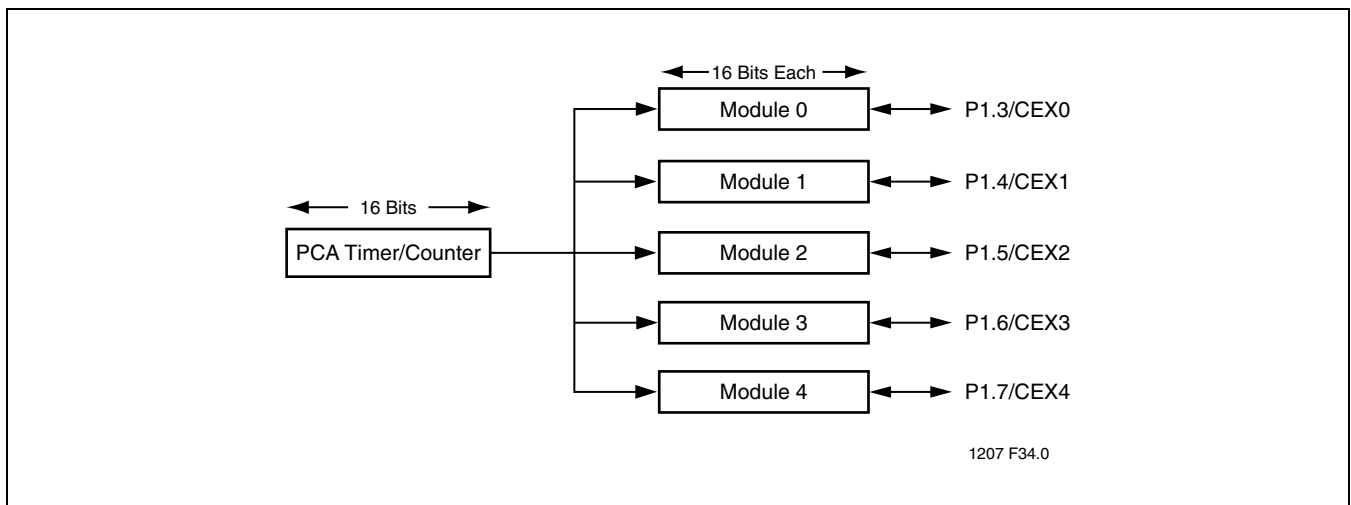
1207 F34.0

FIGURE   8-1: PCA TIMER/COUNTER AND COMPARE/CAPTURE MODULES

The table below summarizes various clock inputs at two common frequencies.

TABLE   8-2: PCA TIMER/COUNTER INPUTS

	Clock Increments	
PCA Timer/Counter Mode	**12 MHz**	**16 MHz**
Mode 0: f_{OSC}/12	1 µsec	0.75 µsec
Mode 1:	330 nsec	250 nsec
Mode 2: Timer 0 Overflows[1]		
Timer 0 programmed in:		
8-bit mode	256 µsec	192 µsec
16-bit mode	65 msec	49 µsec
8-bit auto-reload	1 to 255 µsec	0.75 to 191 µsec
Mode 3: External Input MAX	0.66 µsec	0.50 µsec

T8-2.0 1207

1. In Mode 2, the overflow interrupt for Timer 0 does not need to be enabled.

CMOD's four possible timer modes with and without the overflow interrupt enabled are shown below. This list assumes that PCA will be left running during idle mode.

TABLE   8-3: CMOD VALUES

	CMOD Value	
PCA Count Pulse Selected	**Without Interrupt Enabled**	**With Interrupt Enabled**
Internal clock, f_{OSC}/12	00H	01H
Internal clock, f_{OSC}/4	02H	03H
Timer 0 overflow	04H	05H
External clock at P1.2	06H	07H

T8-3.0 1207

The CCON register is associated with all PCA timer functions. It contains run control bits and flags for the PCA timer (CF) and all modules. To run the PCA the CR bit (CCON.6) must be set by software. Clearing the bit, will turn off PCA. When the PCA counter overflows, the CF (CCON.7) will be set, and an interrupt will be generated if the ECF bit in the CMOD register is set. The CF bit can only be cleared by software. Each module has its own timer interrupt or capture interrupt flag (CCF0 for module 0, CCF4 for module 4, etc.). They are set when either a match or capture occurs. These flags can only be cleared by software. (See "PCA Timer/Counter Control Register (CCON)" on page 27.)

EOL Data Sheet

8.3 Compare/Capture Modules

Each PCA module has an associated SFR with it. These registers are: CCAPM0 for module 0, CCAPM1 for module 1, etc. Refer to "PCA Compare/Capture Module Mode Register (CCAPMn)" on page 29 for details. The registers each contain 7 bits which are used to control the mode each module will operate in. The ECCF bit (CCAPMn.0 where n = 0, 1, 2, 3, or 4 depending on module) will enable the CCF flag in the CCON SFR to generate an interrupt when a match or compare occurs. PWM (CCAPMn.1) enables the pulse width modulation mode. The TOG bit (CCAPMn.2) when set, causes the CEX output associated with the module to toggle when there is a match between the PCA counter and the module's capture/compare register. When there is a match between the PCA counter and the module's capture/compare register, the MATn (CCAPMn.3) and the CCFn bit in the CCON register to be set.

Bits CAPN (CCAPMn.4) and CAPP (CCAPMn.5) determine whether the capture input will be active on a positive edge or negative edge. The CAPN bit enables the negative edge that a capture input will be active on, and the CAPP bit enables the positive edge. When both bits are set, both edges will be enabled and a capture will occur for either transition. The last bit in the register ECOM (CCAPMn.6) when set, enables the comparator function. Table 8-5 shows the CCAPMn settings for the various PCA functions.

There are two additional register associated with each of the PCA modules: CCAPnH and CCAPnL. They are registers that hold the 16-bit count value when a capture occurs or a compare occurs. When a module is used in PWM mode, these registers are used to control the duty cycle of the output. See Figure 8-1.

TABLE 8-4: PCA HIGH AND LOW REGISTER COMPARE/CAPTURE MODULES

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function		RESET Value
			MSB	LSB	
CCAP0H	PCA Module 0 Compare/Capture Registers	FAH	CCAP0H[7:0]		00H
CCAP0L		EAH	CCAP0L[7:0]		00H
CCAP1H	PCA Module 1 Compare/Capture Registers	FBH	CCAP1H[7:0]		00H
CCAP1L		EBH	CCAP1L[7:0]		00H
CCAP2H	PCA Module 2 Compare/Capture Registers	FCH	CCAP2H[7:0]		00H
CCAP2L		ECH	CCAP2L[7:0]		00H
CCAP3H	PCA Module 3 Compare/Capture Registers	FDH	CCAP3H[7:0]		00H
CCAP3L		EDH	CCAP3L[7:0]		00H
CCAP4H	PCA Module 4 Compare/Capture Registers	FEH	CCAP4H[7:0]		00H
CCAP4L		EEH	CCAP4L[7:0]		00H

T8-4.0 1207

TABLE 8-5: PCA MODULE MODES

-[1]	ECOMy[2]	CAPPy[2]	CAPNy[2]	MATy[2]	TOGy[2]	PWMy[2]	ECCFy[2]	Module Code
Without Interrupt enabled								
-	0	0	0	0	0	0	0	No Operation
-	0	1	0	0	0	0	0	16-bit capture on positive-edge trigger at CEX[4:0]
-	0	0	1	0	0	0	0	16-bit capture on negative-edge trigger at CEX[4:0]
-	0	1	1	0	0	0	0	16-bit capture on positive/negative-edge trigger at CEX[4:0]
-	1	0	0	1	0	0	0	Compare: software timer
-	1	0	0	1	1	0	0	Compare: high-speed output
-	1	0	0	0	0	1	0	Compare: 8-bit PWM
-	1	0	0	1	0 or 1[3]	0	0	Compare: PCA WDT (CCAPM4 only)[4]

T8-5.0 1207

1. User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.
2. y = 0, 1, 2, 3, 4
3. A 0 disables toggle function. A 1 enables toggle function on CEX[4:0] pin.
4. For PCA WDT mode, also set the WDTE bit in the CMOD register to enable the reset output signal.

TABLE 8-6: PCA MODULE MODES

-[1]	ECOMy[2]	CAPPy[2]	CAPNy[2]	MATy[2]	TOGy[2]	PWMy[2]	ECCFy[2]	Module Code
With Interrupt enabled								
-	0	1	0	0	0	0	1	16-bit capture on positive-edge trigger at CEX[4:0]
-	0	0	1	0	0	0	1	16-bit capture on negative-edge trigger at CEX[4:0]
-	0	1	1	0	0	0	1	16-bit capture on positive/negative-edge trigger at CEX[4:0]
-	1	0	0	1	0	0	1	Compare: software timer
-	1	0	0	1	1	0	1	Compare: high-speed output
-	1	0	0	0	0	1	X[3]	Compare: 8-bit PWM
-	1	0	0	1	0 or 1[4]	0	X[5]	Compare: PCA WDT (CCAPM4 only)[6]

T8-6.0 1207

1. User should not write '1's to reserved bits. The value read from a reserved bit is indeterminate.
2. y = 0, 1, 2, 3, 4
3. No PCA interrupt is needed to generate the PWM.
4. A 0 disables toggle function. A 1 enables toggle function on CEX[4:0] pin.
5. Enabling an interrupt for the Watchdog Timer would defeat the purpose of the Watchdog Timer.
6. For PCA WDT mode, also set the WDTE bit in the CMOD register to enable the reset output signal.

EOL Data Sheet

8.3.1 Capture Mode

Capture mode is used to capture the PCA timer/counter value into a module's capture registers (CCAPnH and CCAPnL). The capture will occur on a positive edge, negative edge, or both on the corresponding module's pin. To use one of the PCA modules in the capture mode, either one or both the CCAPM bits CAPN and CAPP for that module must be set. When a valid transition occurs on the CEX pin corresponding to the module used, the PCA hardware loads the 16-bit value of the PCA counter register (CH and CL) into the module's capture registers (CCAPnL and CCAPnH). If the CCFn bit for the module in the CCON SFR and the ECCFn bit in the CCAPMn SFR are set, then an interrupt will be generated. In the interrupt service routine, the 16-bit capture value must be saved in RAM before the next event capture occurs. If a subsequent capture occurred, the original capture values would be lost. After flag event flag has been set by hardware, the user must clear the flag in software. (See Figure 8-2)
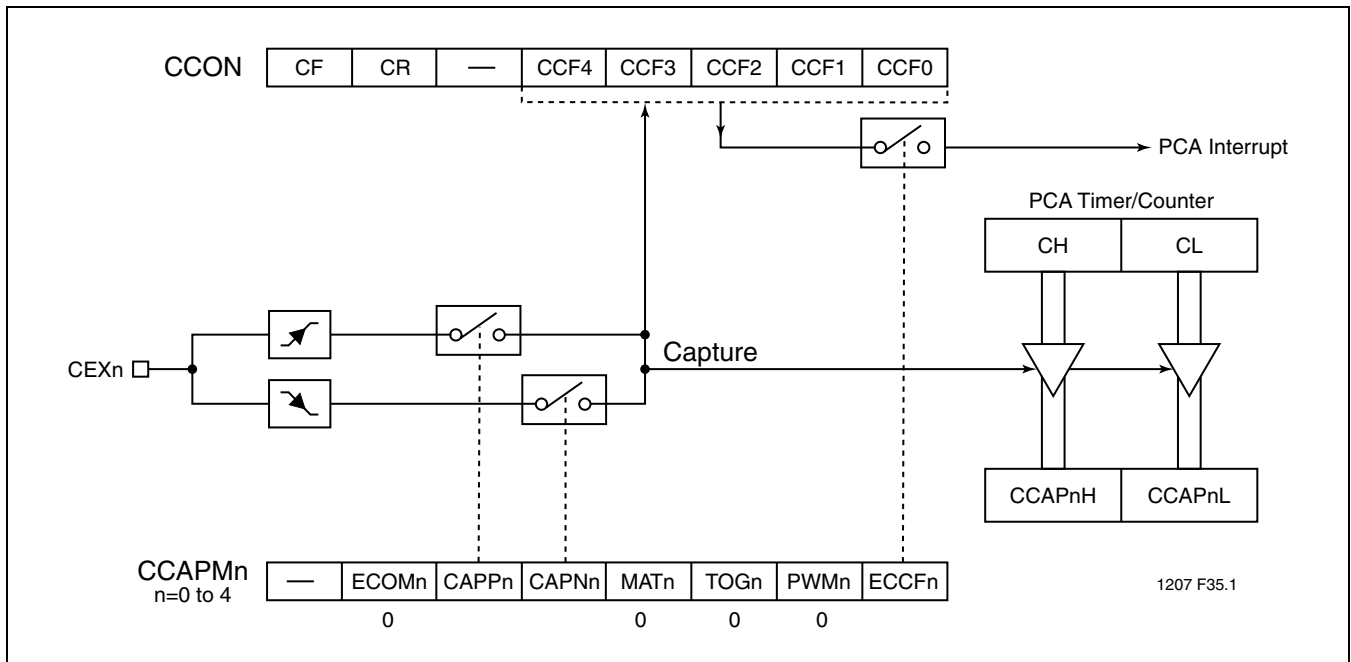

FIGURE   8-2: PCA CAPTURE MODE

8.3.2 16-Bit Software Timer Mode

The 16-bit software timer mode is used to trigger interrupt routines, which must occur at periodic intervals. It is setup by setting both the ECOM and MAT bits in the module's CCAPMn register. The PCA timer will be compared to the module's capture registers (CCAPnL and CCAPnH) and when a match occurs, an interrupt will occur, if the CCFn (CCON SFR) and the ECCFn (CCAPMn SFR) bits for the module are both set.

If necessary, a new 16-bit compare value can be loaded into CCAPnH and CCAPnL during the interrupt routine. The user should be aware that the hardware temporarily disables the comparator function while these registers are being updated so that an invalid match will not occur. Thus, it is recommended that the user write to the low byte first (CCAPnL) to disable the comparator, then write to the high byte (CCAPnH) to re-enable it. If any updates to the registers are done, the user may want to hold off any interrupts from occurring by clearing the EA bit. (See Figure 8-3)
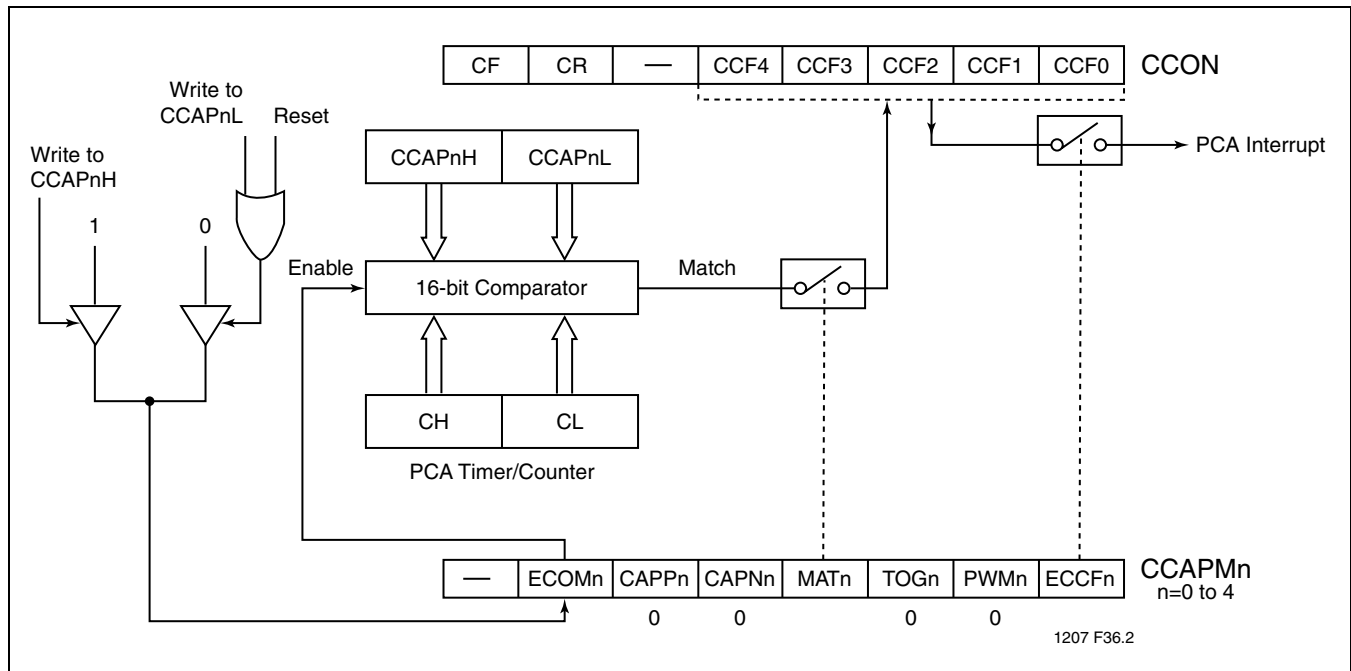

FIGURE   8-3: PCA COMPARE MODE (SOFTWARE TIMER)

8.3.3 High Speed Output Mode

The high speed output mode is used to toggle a port pin when a match occurs between the PCA timer and the pre-loaded value in the compare registers. In this mode, the CEX output pin (on port 1) associated with the PCA module will toggle every time there is a match between the PCA counter (CH and CL) and the capture registers (CCAPnH and CCAPnL). To activate this mode, the user must set TOG, MAT, and ECOM bits in the module's CCAPMn SFR.

High speed output mode is much more accurate than toggling pins since the toggle occurs before branching to an interrupt. In this case, interrupt latency will not affect the accuracy of the output. When using high speed output, using an interrupt is optional. Only if the user wishes to change the time for the next toggle is it necessary to update the compare registers. Otherwise, the next toggle will occur when the PCA timer rolls over and matches the last compare value. (See Figure 8-4)
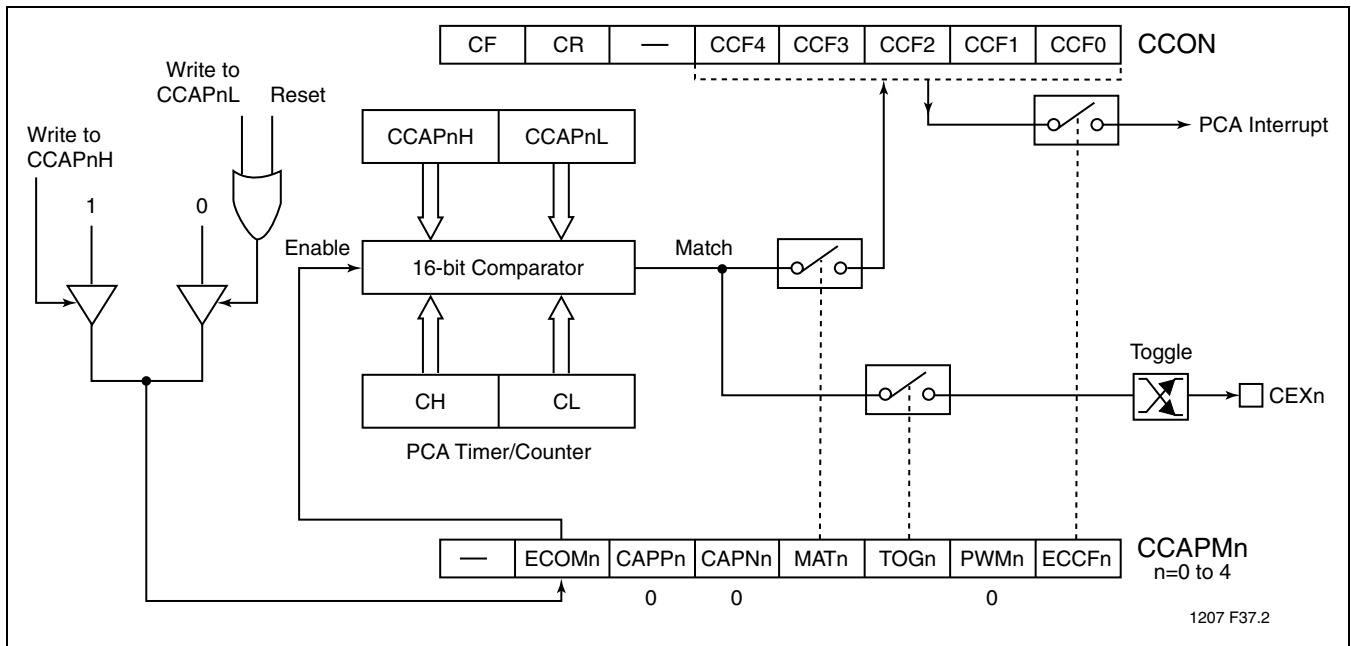

FIGURE   8-4: PCA HIGH SPEED OUTPUT MODE

8.3.4 Pulse Width Modulator

The Pulse Width Modulator (PWM) mode is used to generate 8-bit PWMs by comparing the low byte of the PCA timer (CL) with the low byte of the compare register (CCAPnL). When CL < CCAPnL the output is low. When CL ≥ CCAPnL the output is high. To activate this mode, the user must set the PWM and ECOM bits in the module's CCAPMn SFR. (See Figure 8-5 and Table 8-7)

In PWM mode, the frequency of the output depends on the source for the PCA timer. Since there is only one set of CH and CL registers, all modules share the PCA timer and frequency. Duty cycle of the output is controlled by the value loaded into the high byte (CCAPnH). Since writes to the CCAPnH register are asynchronous, a new value written to the high byte will not be shifted into CCAPnL for comparison until the next period of the output (when CL rolls over from 255 to 00).

To calculate values for CCAPnH for any duty cycle, use the following equation:

$$CCAPnH = 256(1 - Duty\ Cycle)$$

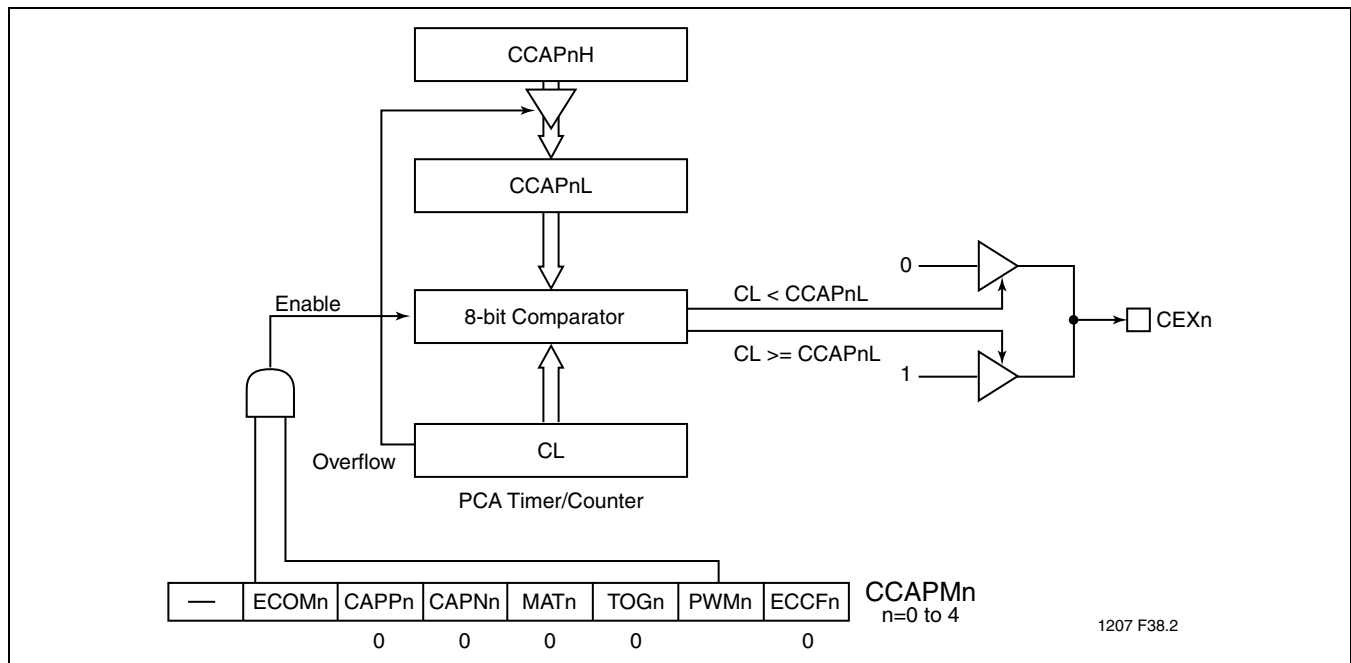where CCAPnH is an 8-bit integer and Duty Cycle is a fraction.

FIGURE   8-5: PCA PULSE WIDTH MODULATOR MODE

TABLE   8-7: PULSE WIDTH MODULATOR FREQUENCIES

	PWM Frequency	
PCA Timer Mode	**12 MHz**	**16 MHz**
1/12 Oscillator Frequency	3.9 KHz	5.2 KHz
1/4 Oscillator Frequency	11.8 KHz	15.6 KHz
Timer 0 Overflow:		
8-bit	15.5 Hz	20.3 Hz
16-bit	0.06 Hz	0.08 Hz
8-bit Auto-Reload	3.9 KHz to 15.3 Hz	5.2 KHz to 20.3 Hz
External Input (Max)	5.9 KHz	7.8 KHz

T8-7.0 1207

S71207-07-EOL   12/06

8.3.5 Watchdog Timer

The Watchdog Timer mode is used to improve reliability in the system without increasing chip count (See Figure 8-6). Watchdog Timers are useful for systems that are susceptible to noise, power glitches, or electrostatic discharge. It can also be used to prevent a software deadlock. If during the execution of the user's code, there is a deadlock, the Watchdog Timer will time out and an internal reset will occur. Only module 4 can be programmed as a Watchdog Timer (but still can be programmed to other modes if the Watchdog Timer is not used).

To use the Watchdog Timer, the user pre-loads a 16-bit value in the compare register. Just like the other compare modes, this 16-bit value is compared to the PCA timer value. If a match is allowed to occur, an internal reset will be generated. This will not cause the RST pin to be driven high.

In order to hold off the reset, the user has three options:

1. periodically change the compare value so it will never match the PCA timer,

2. periodically change the PCA timer value so it will never match the compare values, or

3. disable the watchdog timer by clearing the WDTE bit before a match occurs and then re-enable it.

The first two options are more reliable because the Watchdog Timer is never disabled as in option #3. If the program counter ever goes astray, a match will eventually occur and cause an internal reset. The second option is also not recommended if other PCA modules are being used. Remember, the PCA timer is the time base for all modules; changing the time base for other modules would not be a good idea. Thus, in most application the first solution is the best option.

Use the code below to initialize the Watchdog Timer. Module 4 can be configured in either compare mode, and the WDTE bit in CMOD must also be set. The user's software then must periodically change (CCAP4H, CCAP4L) to keep a match from occurring with the PCA timer (CH, CL). This code is given in the Watchdog routine below.

```
;==========================================

Init_Watchdog:

    MOV    CCAPM4, #4CH; Module 4 in compare mode

    MOV    CCAP4L, #0FFH; Write to low byte first

    MOV    CCAP4H, #0FFH; Before PCA timer counts up
                ; to FFFF Hex, these compare
                ; values must be changed.

    ORL    CMOD, #40H; Set the WDTE bit to enable the
                ; watchdog timer without
                ; changing the other bits in
                ; CMOD

;==========================================

;Main program goes here, but call WATCHDOG periodically.

;==========================================

WATCHDOG:

    CLR    EA; Hold off interrupts

    MOV    CCAP4L, #00; Next compare value is within

    MOV    CCAP4H, CH; 65,535 counts of the
                ; current PCA

    SETB   EA; timer value

    RET

;==========================================
```

This routine should not be part of an interrupt service routine. If the program counter goes astray and gets stuck in an infinite loop, interrupts will still be serviced and the watchdog will keep getting reset. Thus, the purpose of the watchdog would be defeated. Instead, call this subroutine from the main program of the PCA timer.
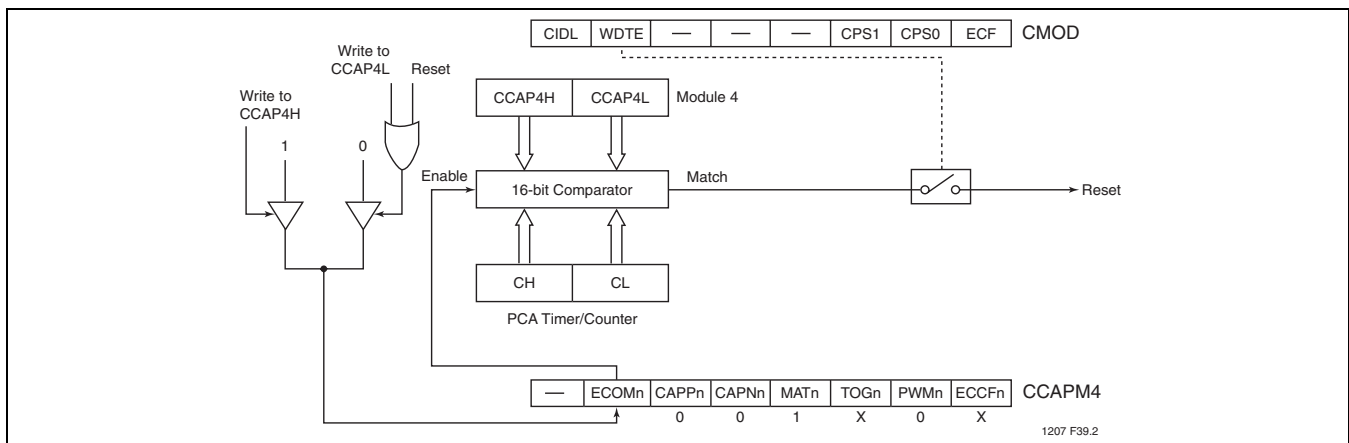

FIGURE   8-6: PCA WATCHDOG TIMER (MODULE 4 ONLY)

9.0 SECURITY LOCK

The security lock protects against software piracy and prevents the contents of the flash from being read by unauthorized parties. It also protects against code corruption resulting from accidental erasing and programming to the internal flash memory. There are two different types of security locks in the device security lock system: hard lock and SoftLock.

9.1 Hard Lock

When hard lock is activated, MOVC or IAP instructions executed from an unlocked or soft locked program address space, are disabled from reading code bytes in hard locked memory blocks (See Table 9-2). Hard lock can either lock both flash memory blocks or just lock the 8 KByte flash memory block (Block 1). All external host and IAP commands except for Chip-Erase are ignored for memory blocks that are hard locked.

9.2 SoftLock

SoftLock allows flash contents to be altered under a secure environment. This lock option allows the user to update program code in the soft locked memory block through in-application programming mode under a predetermined secure environment. For example, if Block 1 (8K) memory block is locked (hard locked or soft locked), and Block 0 (64K for SST89E564RD/SST89V564RD) memory block is soft locked, code residing in Block 1 can program Block 0. The following IAP mode commands issued through the

command mailbox register, SFCM, executed from a Locked (hard locked or soft locked) block, can be operated on a soft locked block: Block-Erase, Sector-Erase, Byte-Program and Byte-Verify.

In external host mode, SoftLock behaves the same as a hard lock.

9.3 Security Lock Status

The three bits that indicate the device security lock status are located in SFST[7:5]. As shown in Figure 9-1 and Table 9-1, the three security lock bits control the lock status of the primary and secondary blocks of memory. There are four distinct levels of security lock status. In the first level, none of the security lock bits are programmed and both blocks are unlocked. In the second level, although both blocks are now locked and cannot be programmed, they are available for read operation via Byte-Verify. In the third level, three different options are available: Block 1 hard lock / Block 0 SoftLock, SoftLock on both blocks, and hard lock on both blocks. Locking both blocks is the same as Level 2, Block 1 except read operation isn't available. The fourth level of security is the most secure level. It doesn't allow read/program of internal memory or boot from external memory. For details on how to program the security lock bits refer to the external host mode and in-application programming sections.
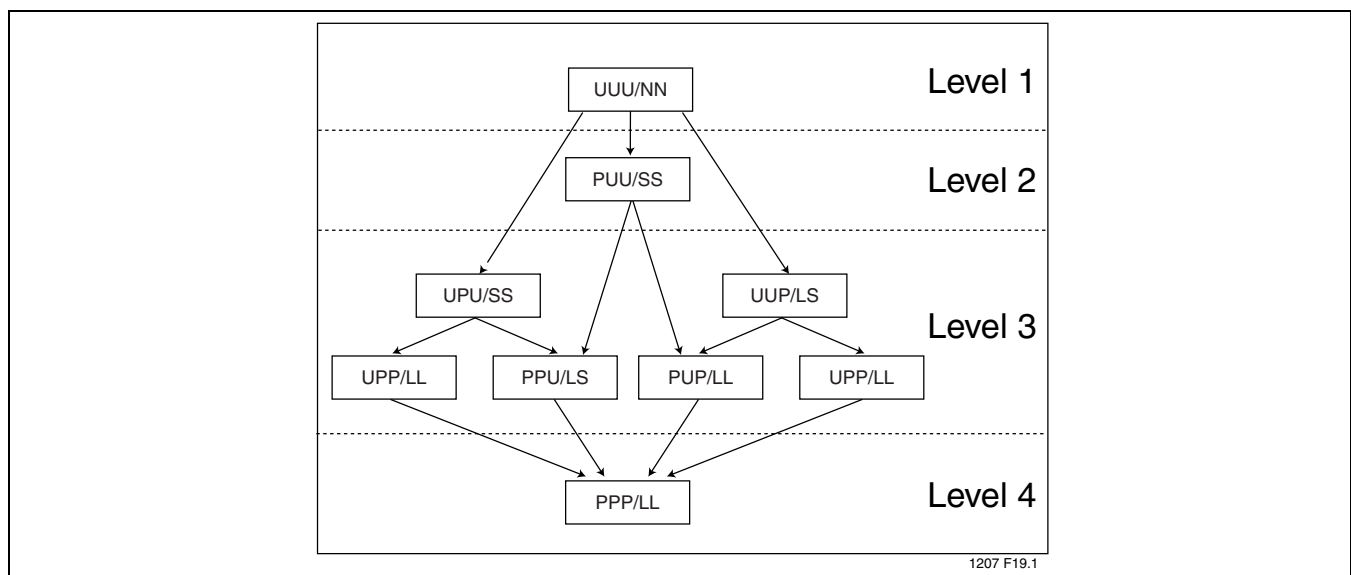

FIGURE 9-1: SECURITY LOCK LEVELS

Note: P = Programmed (Bit logic state = 0), U = Unprogrammed (Bit logic state = 1), N = Not Locked, L = Hard locked, S = Soft locked

EOL Data Sheet

TABLE 9-1: SECURITY LOCK OPTIONS

Level	SFST[7:5]	SB1	SB2[1]	SB3[1]	Block 1	Block 0	Security Type
	Security Lock Bits[1,2]				**Security Status of:**		
					Block 1	Block 0	Security Type
1	000	U	U	U	Unlock	Unlock	No Security Features are Enabled.
2	100	P	U	U	SoftLock	SoftLock	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, EA# is sampled and latched on Reset, and further programming of the flash is disabled.
3	011 101	U P	P U	P P	Hard Lock	Hard Lock	Level 2 plus Verify disabled, both blocks locked.
	010	U	P	U	SoftLock	SoftLock	Level 2 plus Verify disabled. Code in Block 1 may program Block 0 and vice versa.
	110 001	P U	P U	U P	Hard Lock	SoftLock	Level 2 plus Verify disabled. Code in Block 1 may program Block 0.
4	111	P	P	P	Hard Lock	Hard Lock	Same as Level 3 hard lock/hard lock, but MCU will start code execution from the internal memory regardless of EA#.

T9-1.3 1207

1. P = Programmed (Bit logic state = 0), U = Unprogrammed (Bit logic state = 1).
2. SFST[7:5] = Security Lock Status Bits (SB1_i, SB2_i, SB3_i)

9.4 Read Operation Under Lock Condition

The status of security bits SB1, SB2, and SB3 can be read when the read command is disabled by security lock. There are three ways to read the status.

1. External host mode: Read-back = 00H (locked)

2. IAP command: Read-back = previous SFDT data

3. MOVC: Read-back = FFH (blank)

TABLE   9-2: SECURITY LOCK ACCESS TABLE

Level	SFST[7:5]	Source Address[1]	Target Address[2]	Byte-Verify Allowed		MOVC Allowed	
				External Host[3]	IAP	564RD	554RC
4	111b (hard lock on both blocks)	Block 0/1	Block 0/1	N	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	N	N	N	N
			External	N/A	N/A	N	Y
3	011b/101b (hard lock on both blocks)	Block 0/1	Block 0/1	N	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	N	N	N	N
			External	N/A	N/A	Y	Y
	001b/110b (Block 0 = SoftLock, Block 1 = hard lock)	Block 0	Block 0	N	N	Y	Y
			Block 1	N	N	N	N
			External	N/A	N/A	N	Y
		Block 1	Block 0	N	Y	Y	Y
			Block 1	N	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	N	N	N	N
			External	N/A	N/A	Y	Y
	010b (SoftLock on both blocks)	Block 0	Block 0	N	N	Y	Y
			Block 1	N	Y	Y	Y
			External	N/A	N/A	N	Y
		Block 1	Block 0	N	Y	Y	Y
			Block 1	N	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	N	N	N	N
			External	N/A	N/A	Y	Y
2	100b (SoftLock on both blocks)	Block 0	Block 0	Y	N	Y	Y
			Block 1	Y	Y	Y	Y
			External	N/A	N/A	N	Y
		Block 1	Block 0	Y	Y	Y	Y
			Block 1	Y	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	Y	N	N	N
			External	N/A	N/A	Y	Y
1	000b (unlock)	Block 0	Block 0	Y	N	Y	Y
			Block 1	Y	Y	Y	Y
			External	N/A	N/A	N	Y
		Block 1	Block 0	Y	Y	Y	Y
			Block 1	Y	N	Y	Y
			External	N/A	N/A	N	Y
		External	Block 0/1	Y	Y	N	Y
			External	N/A	N/A	Y	Y

T9-2.1 1207

1. Location of MOVC or IAP instruction
2. Target address is the location of the byte being read
3. External host Byte-Verify access does not depend on a source address.

10.0 RESET

A system reset initializes the MCU and begins program execution at program memory location 0000H. The reset input for the device is the RST pin. In order to reset the device, a logic level high must be applied to the RST pin for at least two machine cycles (24 clocks), after the oscillator becomes stable. ALE, PSEN# are weakly pulled high during reset. During reset, ALE and PSEN# output a high level in order to perform a proper reset. This level must not be affected by external element. A system reset will not affect the 1 KByte of on-chip RAM while the device is running, however, the contents of the on-chip RAM during power up are indeterminate. Following reset, all Special Function Registers (SFR) return to their reset values outlined in Tables 3-7 to 3-11.

10.1 Power-on Reset

At initial power up, the port pins will be in a random state until the oscillator has started and the internal reset algorithm has weakly pulled all pins high. **Powering up the device without a valid reset could cause the MCU to start executing instructions from an indeterminate location. Such undefined states may inadvertently corrupt the code in the flash.**

When power is applied to the device, the RST pin must be held high long enough for the oscillator to start up (usually several milliseconds for a low frequency crystal), in addition to two machine cycles for a valid power-on reset. An example of a method to extend the RST signal is to implement a RC circuit by connecting the RST pin to V_{DD} through a 10 μF capacitor and to V_{SS} through an 8.2KΩ resistor as shown in Figure 10-1. Note that if an RC circuit is being used, provisions should be made to ensure the V_{DD} rise time does not exceed 1 millisecond and the oscillator start-up time does not exceed 10 milliseconds.

For a low frequency oscillator with slow start-up time the reset signal must be extended in order to account for the slow start-up time. This method maintains the necessary relationship between V_{DD} and RST to avoid programming at an indeterminate location, which may cause corruption in the code of the flash. The power-on detection is designed to work as power up initially, before the voltage reaches the brown-out detection level. The POF flag in the PCON register is set to indicate an initial power up condition. The POF flag will remain active until cleared by software. Please refer to Section 3.5, PCON register definition for detail information.

For more information on system level design techniques, please review the *Design Considerations for the SST FlashFlex51 Family Microcontroller* application note.
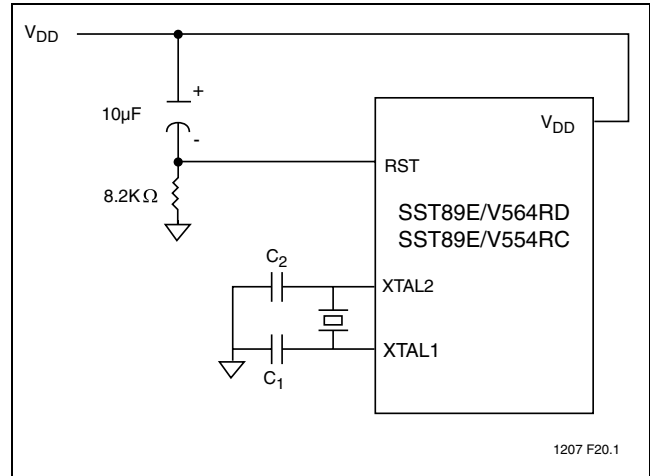

FIGURE   10-1: POWER-ON RESET CIRCUIT

10.2 Software Reset

The software reset is executed by changing SFCF[1] (SWR) from "0" to "1". A software reset will reset the program counter to address 0000H. All SFR registers will be set to their reset values, except SFCF[1] (SWR), WDTC[2] (WDTS), and RAM data will not be altered.

10.3 Brown-out Detection Reset

The device includes a brown-out detection circuit to protect the system from severed supplied voltage V_{DD} fluctuations. SST89E564's internal brown-out detection threshold is 3.85V, SST89V564's brown-out detection threshold is 2.35V. For brown-out voltage parameters, please refer to Tables 13-6 and 13-7.

When V_{DD} drops below this voltage threshold, the brown-out detector triggers the circuit to generate a brown-out interrupt but the CPU still runs until the supplied voltage returns to the brown-out detection voltage V_{BOD}. The default operation for a brown-out detection is to cause a processor reset.

V_{DD} must stay below V_{BOD} at least four oscillator clock periods before the brown-out detection circuit will respond.

Brown-out interrupt can be enabled by setting the EBO bit in IEA register (address E8H, bit 3). If EBO bit is set and a brown-out condition occurs, a brown-out interrupt will be generated to execute the program at location 004BH. It is required that the EBO bit be cleared by software after the brown-out interrupt is serviced. Clearing EBO bit when the brown-out condition is active will properly reset the device. If brown-out interrupt is not enabled, a brown-out condition will reset the program to resume execution at location 0000H.

10.4 Interrupt Priority and Polling Sequence

The device supports eight interrupt sources under a four level priority scheme. Table 10-1 summarizes the polling sequence of the supported interrupts. Note that the SPI serial interface and the UART share the same interrupt vector. (See Figure 10-2)

TABLE   10-1: INTERRUPT POLLING SEQUENCE

| Description	Interrupt Flag	Vector Address	Interrupt Enable	Interrupt Priority	Service Priority	Wake-Up Power-down
Ext. Int0	IE0	0003H	EX0	PX0/H	1(highest)	yes
Brown-out	-	004BH	EBO	PBO/H	2	no
T0	TF0	000BH	ET0	PT0/H	3	no
Ext. Int1	IE1	0013H	EX1	PX1/H	4	yes
T1	TF1	001BH	ET1	PT1/H	5	no
PCA	CF/CCFn	0033H	EC	PPCH	6	no
UART/SPI	TI/RI/SPIF	0023H	ES	PS/H	7	no
T2	TF2, EXF2	002BH	ET2	PT2/H	8	no

T10-1.2 1207
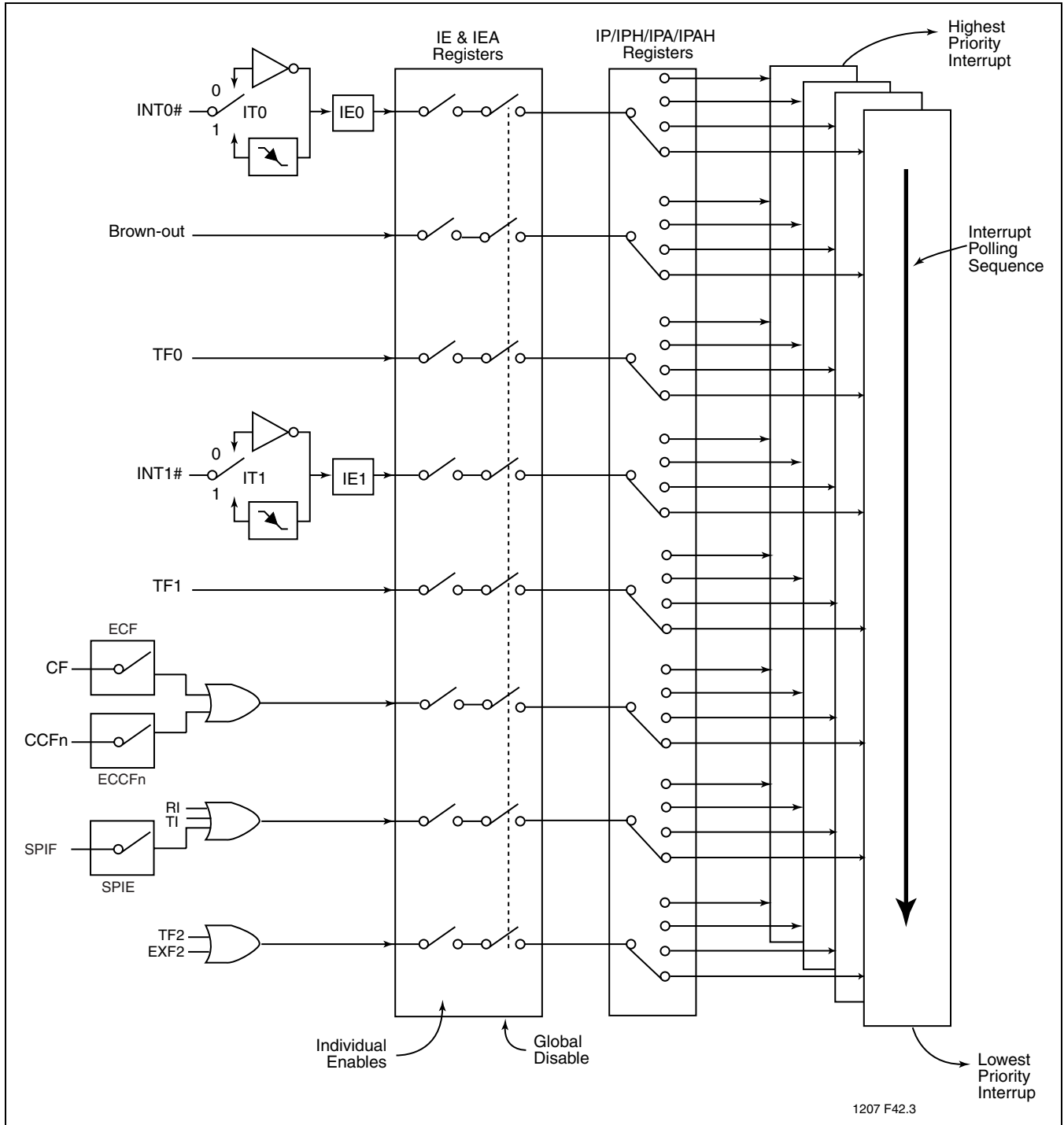
FIGURE 10-2: INTERRUPT STRUCTURE

11.0 POWER-SAVING MODES

The device provides two power saving modes of operation for applications where power consumption is critical. The two modes are idle and power-down, see Table 11-1.

11.1 Idle Mode

Idle mode is entered setting the IDL bit in the PCON register. In idle mode, the program counter (PC) is stopped. The system clock continues to run and all interrupts and peripherals remain active. The on-chip RAM and the special function registers hold their data during this mode.

The device exits idle mode through either a system interrupt or a hardware reset. Exiting idle mode via system interrupt, the start of the interrupt clears the IDL bit and exits idle mode. After exit the Interrupt Service Routine, the interrupted program resumes execution beginning at the instruction immediately following the instruction which invoked the idle mode. A hardware reset starts the device similar to a power-on reset.

11.2 Power-down Mode

The power-down mode is entered by setting the PD bit in the PCON register. In the power-down mode, the clock is stopped and external interrupts are active for level sensitive interrupts only. SRAM contents are retained during power-down, the minimum V_{DD} level is 2.0V.

The device exits power-down mode through either an enabled external level sensitive interrupt or a hardware reset. The start of the interrupt clears the PD bit and exits power-down. Holding the external interrupt pin low restarts the oscillator, the signal must hold low at least 1024 clock cycles before bringing back high to complete the exit. Upon interrupt signal restored to logic $V_{IH,}$ the interrupt service routine program execution resumes beginning at the instruction immediately following the instruction which invoked power-down mode. A hardware reset starts the device similar to power-on reset.

To exit properly out of power-down, the reset or external interrupt should not be executed before the V_{DD} line is restored to its normal operating voltage. Be sure to hold V_{DD} voltage long enough at its normal operating level for the oscillator to restart and stabilize (normally less than 10 ms).

TABLE   11-1: POWER SAVING MODES

Mode	Initiated by	State of MCU	Exited by
Idle Mode	Software (Set IDL bit in PCON) MOV PCON, #01H;	CLK is running. Interrupts, serial port and timers/counters are active. Program Counter is stopped. ALE and PSEN# signals at a HIGH level during Idle. All registers remain unchanged.	Enabled interrupt or hardware reset. Start of interrupt clears IDL bit and exits idle mode, after the ISR RETI instruction, program resumes execution beginning at the instruction following the one that invoked idle mode. A user could consider placing two or three NOP instructions after the instruction that invokes idle mode to eliminate any problems. A hardware reset restarts the device similar to a power-on reset.
Power-down Mode	Software (Set PD bit in PCON) MOV PCON, #02H;	CLK is stopped. On-chip SRAM and SFR data is maintained. ALE and PSEN# signals at a LOW level during power-down. External Interrupts are only active for level sensitive interrupts, if enabled.	Enabled external level sensitive interrupt or hardware reset. Start of interrupt clears PD bit and exits power-down mode, after the ISR RETI instruction program resumes execution beginning at the instruction following the one that invoked power-down mode. A user could consider placing two or three NOP instructions after the instruction that invokes power-down mode to eliminate any problems. A hardware reset restarts the device similar to a power-on reset.

T11-1.1 1207

12.0 SYSTEM CLOCK AND CLOCK OPTIONS

12.1 Clock Input Options and Recommended Capacitor Values for Oscillator

Shown in Figure 12-1 are the input and output of an internal inverting amplifier (XTAL1, XTAL2), which can be configured for use as an on-chip oscillator.

When driving the device from an external clock source, XTAL2 should be left disconnected and XTAL1 should be driven.

At start-up, the external oscillator may encounter a higher capacitive load at XTAL1 due to interaction between the amplifier and its feedback capacitance. However, the capacitance will not exceed 15 pF once the external signal meets the V_{IL} and V_{IH} specifications.

Crystal manufacturer, supply voltage, and other factors may cause circuit performance to differ from one application to another. C1 and C2 should be adjusted appropriately for each design. Table 12-1, shows the typical values for C1 and C2 vs. crystal type for various frequencies

TABLE 12-1: RECOMMENDED VALUES FOR C1 AND C2 BY CRYSTAL TYPE

Crystal	C1 = C2
Quartz	20-30pF
Ceramic	40-50pF

T12-1.1 1207

More specific information about on-chip oscillator design can be found in the *FlashFlex51 Oscillator Circuit Design Considerations* application note.

12.2 Clock Doubling Option

By default, the device runs at 12 clocks per machine cycle (x1 mode). The device has a clock doubling option to speed up to 6 clocks per machine cycle. Please refer to Table 12-2 for detail.

Clock double mode can be enabled either via the external host mode or the IAP mode. Please refer to Table 4-1 and Table 4-2 for the external host mode enabling command and to Tables 4-6 and 4-7 for the IAP mode enabling command (When set, the EDC# bit in SFST register will indicate 6 clock mode.).

The clock double mode is only for doubling the internal system clock and the internal flash memory, i.e. EA#=1. To access the external memory and the peripheral devices, careful consideration must be taken. Also note that the crystal output (XTAL2) will not be doubled.
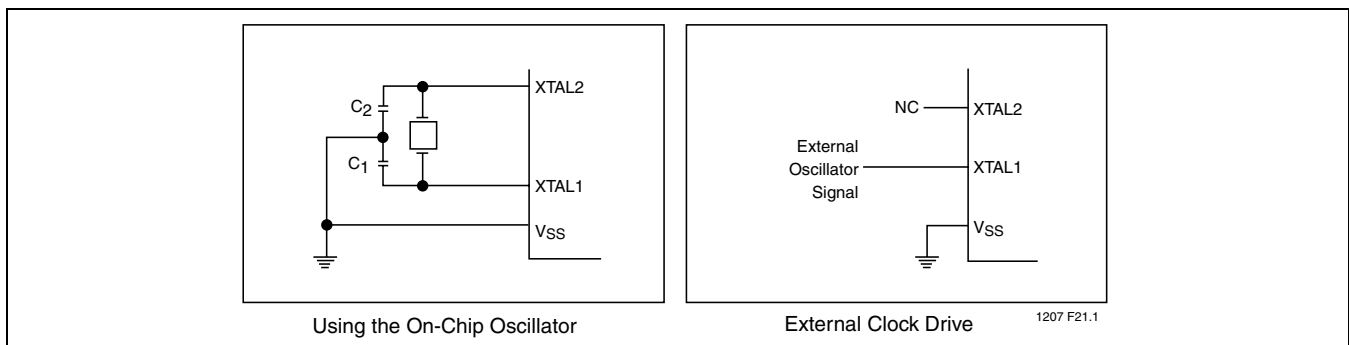
FIGURE 12-1: OSCILLATOR CHARACTERISTICS

TABLE 12-2: CLOCK DOUBLING FEATURES

Device	Standard Mode (x1)		Clock Double Mode (x2)	
	Clocks per Machine Cycle	Max. External Clock Frequency (MHz)	Clocks per Machine Cycle	Max. External Clock Frequency (MHz)
SST89E564RD/554RC	12	40	6	20
SST89V564RD/554RC	12	33	6	16

T12-2.3 1207

13.0 ELECTRICAL SPECIFICATION

Absolute Maximum Stress Ratings (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Ambient Temperature Under Bias . . . . -55°C to +125°C

Storage Temperature . . . . -65°C to +150°C

Voltage on EA# Pin to V_{SS} . . . . -0.5V to +14.0V

D.C. Voltage on Any Pin to Ground Potential . . . . -0.5V to V_{DD}+0.5V

Transient Voltage (<20ns) on Any Other Pin to V_{SS} . . . . -1.0V to V_{DD}+1.0V

Maximum I_{OL} per I/O Pins P1.5, P1.6, P1.7 . . . . 20mA

Maximum I_{OL} per I/O for All Other Pins 15mA

Package Power Dissipation Capability (T_A = 25°C) 1.5W

Through Hole Lead Soldering Temperature (10 Seconds). . . . . 300°C

Surface Mount Solder Reflow Temperature: . . . . "with-Pb" units[1]: 240°C for 3 seconds

. . . . "non-Pb" units: 260°C for 3 seconds

Output Short Circuit Current[2] . . . . 50 mA

1. Certain "with-Pb" package types are capable of 260°C for 3 seconds; please consult the factory for the latest information.
2. Outputs shorted for no more than one second. No more than one output shorted at a time.
   (Based on package heat transfer limitations, not device power consumption.

Note: This specification contains preliminary information on new products in production.
The specifications are subject to change without notice.

TABLE 13-1: OPERATING RANGE

Symbol	Description	Min.	Max	Unit
T_A	Ambient Temperature Under Bias			
	Standard	0	+70	°C
	Industrial	-40	+85	°C
V_{DD}	Supply Voltage			
	SST89E5x4Rx	4.5	5.5	V
	SST89V5x4Rx	2.7	3.6	V
f_{OSC}	Oscillator Frequency			
	SST89E5x4Rx	0	40	MHz
	SST89V5x4Rx	0	33	MHz
	Oscillator Frequency for in-application programming			
	SST89E5x4Rx	.25	40	MHz
	SST89V5x4Rx	.25	33	MHz

T13-1.1 1207

TABLE 13-2: RELIABILITY CHARACTERISTICS

Symbol	Parameter	Minimum Specification	Units	Test Method
N_{END}[1]	Endurance	10,000	Cycles	JEDEC Standard A117
T_{DR}[1]	Data Retention	100	Years	JEDEC Standard A103
I_{LTH}[1]	Latch Up	100 + I_{DD}	mA	JEDEC Standard 78

T13-2.0 1207

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

EOL Data Sheet

TABLE 13-3: AC CONDITIONS OF TEST

Input Rise/Fall Time . . . . 10 ns
Output Load . . . . C_L = 100 pF
See Figures 13-8 and 13-10

T13-3.0 1207

TABLE 13-4: RECOMMENDED SYSTEM POWER-UP TIMINGS

Symbol	Parameter	Minimum	Units
$T_{PU-READ}$[1]	Power-up to Read Operation	100	µs
$T_{PU-WRITE}$[1]	Power-up to Write Operation	100	µs

T13-4.2 1207

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter

TABLE 13-5: PIN IMPEDANCE (V_{DD}=3.3V, Ta=25 °C, f=1 Mhz, other pins open)

Parameter	Description	Test Condition	Maximum
$C_{I/O}$[1]	I/O Pin Capacitance	$V_{I/O}$ = 0V	15 pF
C_{IN}[1]	Input Capacitance	V_{IN} = 0V	12 pF
L_{PIN}[2]	Pin Inductance		20 nH

T13-5.4 1207

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.
2. Refer to PCI spec.

13.1 DC Electrical Characteristics

TABLE 13-6: DC ELECTRICAL CHARACTERISTICS FOR SST89E564RD/554RC
T_A = -40°C TO +85°C; V_{DD} = 4.5-5.5V; V_{SS} = 0V

Symbol	Parameter	Test Conditions	Min	Max	Units
V_{IL}	Input Low Voltage	$4.5 < V_{DD} < 5.5$	-0.5	$0.2V_{DD}$ - 0.1	V
V_{IH}	Input High Voltage	$4.5 < V_{DD} < 5.5$	$0.2V_{DD}$ + 0.9	V_{DD} + 0.5	V
V_{IH1}	Input High Voltage (XTAL1, RST)	$4.5 < V_{DD} < 5.5$	$0.7V_{DD}$	V_{DD} + 0.5	V
V_{OL}	Output Low Voltage (Ports 1.5, 1.6, 1.7)	V_{DD} = 4.5V			
		I_{OL} = 16mA		1.0	V
V_{OL}	Output Low Voltage (Ports 1, 2, 3)[1]	V_{DD} = 4.5V			
		I_{OL} = 100µA[2]		0.3	V
		I_{OL} = 1.6mA[2]		0.45	V
		I_{OL} = 3.5mA[2]		1.0	V
V_{OL1}	Output Low Voltage (Port 0, ALE, PSEN#)[1,3]	V_{DD} = 4.5V			
		I_{OL} = 200µA[2]		0.3	V
		I_{OL} = 3.2mA[2]		0.45	V
V_{OH}	Output High Voltage (Ports 1, 2, 3, ALE, PSEN#)[4]	V_{DD} = 4.5V			
		I_{OH} = -10µA	V_{DD} - 0.3		V
		I_{OH} = -30µA	V_{DD} - 0.7		V
		I_{OH} = -60µA	V_{DD} - 1.5		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)[4]	V_{DD} = 4.5V			
		I_{OH} = -200µA	V_{DD} - 0.3		V
		I_{OH} = -3.2mA	V_{DD} - 0.7		V
V_{BOD}	Brown-out Detection Voltage		3.85	4.15	V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V_{IN} = 0.4V		-75	µA
I_{TL}	Logical 1-to-0 Transition Current (Ports 1, 2, 3)[5]	V_{IN} = 2V		-650	µA
I_{LI}	Input Leakage Current (Port 0)	$0.45 < V_{IN} < V_{DD}$-0.3		±10	µA
R_{RST}	RST Pull-down Resistor		40	225	KΩ
C_{IO}	Pin Capacitance[6]	@ 1 MHz, 25°C		15	pF
I_{DD}	Power Supply Current				
	IAP Mode				
	@ 12 MHz			70	mA
	@ 40 MHz			88	mA
	Active Mode				
	@ 12 MHz			23	mA
	@ 40 MHz			50	mA
	Idle Mode				
	@ 12 MHz			20	mA
	@ 40 MHz			42	mA
	Power-down Mode (min. V_{DD} = 2V)	T_a = 0°C to +70°C		80	µA
		T_a = -40°C to +85°C		90	µA

T13-6.4 1207

EOL Data Sheet

1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15mA
   Maximum I_{OL} per 8-bit port:26mA
   Maximum I_{OL} total for all outputs:71mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification.
   Pins are not guaranteed to sink current greater than the listed test conditions.
2. Capacitive loading on Ports 0 & 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and Ports 1 & 3. The noise due to external bus capacitance discharging into the Port 0 & 2 pins when the pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.
3. Load capacitance for Port 0, ALE & PSEN#= 100pF, load capacitance for all other outputs = 80pF.
4. Capacitive loading on Ports 0 & 2 may cause the V_{OH} on ALE and PSEN# to momentarily fall below the V_{DD} - 0.7 specification when the address bits are stabilizing.
5. Pins of Ports 1, 2 & 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
6. Pin capacitance is characterized but not tested. EA# is 25pF (max).

TABLE   13-7: DC ELECTRICAL CHARACTERISTICS FOR SST89V564RD/554RC
T_A = -40°C TO +85°C; V_{DD} = 2.7-3.6V; V_{SS} = 0V (1 OF 2)

Symbol	Parameter	Test Conditions	Min	Max	Units
V_{IL}	Input Low Voltage	2.7 < V_{DD} < 3.6	-0.5	0.7	V
V_{IH}	Input High Voltage	2.7 < V_{DD} < 3.6	$0.2V_{DD}$ + 0.9	V_{DD} + 0.5	V
V_{IH1}	Input High Voltage (XTAL1, RST)	2.7 < V_{DD} < 3.6	$0.7V_{DD}$	V_{DD} + 0.5	V
V_{OL}	Output Low Voltage (Ports 1.5, 1.6, 1.7)	V_{DD} = 2.7V			
		I_{OL} = 16mA		1.0	V
V_{OL}	Output Low Voltage (Ports 1, 2, 3)[1]	V_{DD} = 2.7V			
		I_{OL} = 100µA[2]		0.3	V
		I_{OL} = 1.6mA[2]		0.45	V
		I_{OL} = 3.5mA[2]		1.0	V
V_{OL1}	Output Low Voltage (Port 0, ALE, PSEN#)[1,3]	V_{DD} = 2.7V			
		I_{OL} = 200µA[2]		0.3	V
		I_{OL} = 3.2mA[2]		0.45	V
V_{OH}	Output High Voltage (Ports 1, 2, 3, ALE, PSEN#)[4]	V_{DD} = 2.7V			
		I_{OH} = -10µA	V_{DD} - 0.3		V
		I_{OH} = -30µA	V_{DD} - 0.7		V
		I_{OH} = -60µA	V_{DD} - 1.5		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)[4]	V_{DD} = 2.7V			
		I_{OH} = -200µA	V_{DD} - 0.3		V
		I_{OH} = -3.2mA	V_{DD} - 0.7		V
V_{BOD}	Brown-out Detection Voltage		2.35	2.55	V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V_{IN} = 0.4V		-75	µA
I_{TL}	Logical 1-to-0 Transition Current (Ports 1, 2, 3)[5]	V_{IN} = 2V		-650	µA
I_{LI}	Input Leakage Current (Port 0)	0.45 < V_{IN} < V_{DD}-0.3		±10	µA
R_{RST}	RST Pull-down Resistor			225	KΩ
C_{IO}	Pin Capacitance[6]	@ 1 MHz, 25°C		15	pF

TABLE 13-7: DC ELECTRICAL CHARACTERISTICS FOR SST89V564RD/554RC
T$_A$ = -40°C TO +85°C; V$_{DD}$ = 2.7-3.6V; V$_{SS}$ = 0V (CONTINUED) (2 OF 2)

Symbol	Parameter	Test Conditions	Min	Max	Units
I$_{DD}$	Power Supply Current				
	IAP Mode				
	@ 12 MHz			40	mA
	@ 33 MHz			47	mA
	Active Mode				
	@ 12 MHz			11.5	mA
	@ 33 MHz			30	mA
	Idle Mode				
	@ 12 MHz			8.5	mA
	@ 33 MHz			21	mA
	Power-down Mode (min. V$_{DD}$ = 2V)	T$_a$ = 0°C to +70°C		45	µA
		T$_a$ = -40°C to +85°C		55	µA

T13-7.6 1207

1. Under steady state (non-transient) conditions, I$_{OL}$ must be externally limited as follows:
   Maximum I$_{OL}$ per port pin: 15mA
   Maximum I$_{OL}$ per 8-bit port: 26mA
   Maximum I$_{OL}$ total for all outputs: 71mA
   If I$_{OL}$ exceeds the test condition, V$_{OL}$ may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Capacitive loading on Ports 0 & 2 may cause spurious noise to be superimposed on the V$_{OL}$s of ALE and Ports 1 & 3. The noise due to external bus capacitance discharging into the Port 0 & 2 pins when the pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.
3. Load capacitance for Port 0, ALE & PSEN#= 100pF, load capacitance for all other outputs = 80pF.
4. Capacitive loading on Ports 0 & 2 may cause the V$_{OH}$ on ALE and PSEN# to momentarily fall below the V$_{DD}$ - 0.7 specification when the address bits are stabilizing.
5. Pins of Ports 1, 2 & 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V$_{IN}$ is approximately 2V.
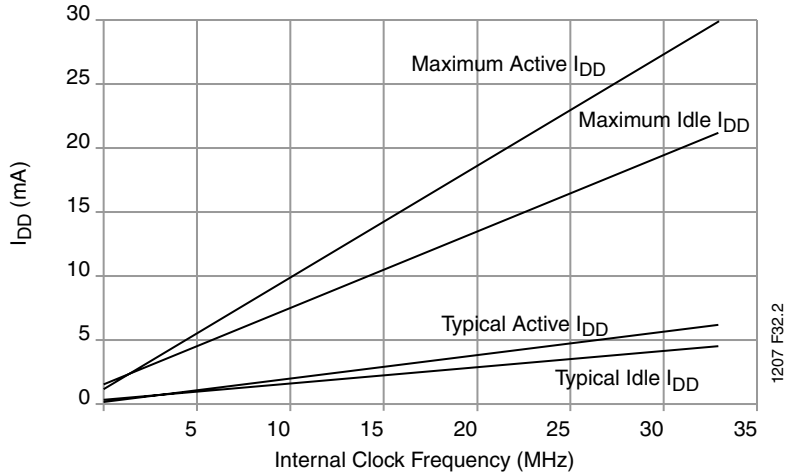6. Pin capacitance is characterized but not tested. EA# is 25pF (max).

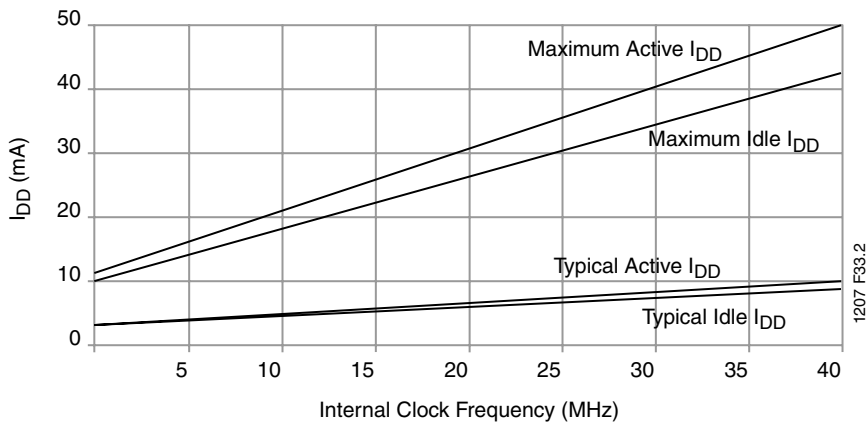**FIGURE 13-1: I$_{DD}$ VS. FREQUENCY (SST89V564RD/554RC)**

FIGURE 13-2: I$_{DD}$ VS. FREQUENCY (SST89E564RD/554RC)

13.2 AC Electrical Characteristics

AC Characteristics: (Over Operating Conditions: Load Capacitance for Port 0, ALE#, and PSEN# = 100pF; Load Capacitance for All Other Outputs = 80pF)

TABLE 13-8: AC ELECTRICAL CHARACTERISTICS (1 OF 2)
T_A = -40°C TO +85°C, V_{DD} = 2.7-3.6V@33MHz, 4.5-5.5V@40MHz, V_{SS} = 0V

Symbol	Parameter	Oscillator 33 MHz (x1 Mode) 16 MHz (x2 Mode)[1] Min	Max	40 MHz (x1 Mode) 20 MHz (x2 Mode)[1] Min	Max	Variable Min	Max	Units
$1/T_{CLCL}$	x1 Mode Oscillator Frequency	0	33	0	40	0	40	MHz
$1/2T_{CLCL}$	x2 Mode Oscillator Frequency	0	16	0	20	0	20	MHz
T_{LHLL}	ALE Pulse Width	46		35		$2T_{CLCL}$ - 15		ns
T_{AVLL}	Address Valid to ALE Low	5				T_{CLCL} - 25 (3V)		ns
				10		T_{CLCL} - 15 (5V)		ns
T_{LLAX}	Address Hold After ALE Low	5				T_{CLCL} - 25 (3V)		ns
				10		T_{CLCL} - 15 (5V)		ns
T_{LLIV}	ALE Low to Valid Instr In		56				$4T_{CLCL}$ - 65 (3V)	ns
					55		$4T_{CLCL}$ - 45 (5V)	ns
T_{LLPL}	ALE Low to PSEN# Low	5				T_{CLCL} - 25 (3V)		ns
				10		T_{CLCL} - 15 (5V)		ns
T_{PLPH}	PSEN# Pulse Width	66				$3T_{CLCL}$ - 25 (3V)		ns
				60		$3T_{CLCL}$ - 15 (5V)		
T_{PLIV}	PSEN# Low to Valid Instr In		35				$3T_{CLCL}$ - 55 (3V)	ns
					25		$3T_{CLCL}$ - 50 (5V)	ns
T_{PXIX}	Input Instr Hold After PSEN#					0		ns
T_{PXIZ}	Input Instr Float After PSEN#		25				T_{CLCL} - 5 (3V)	ns
					10		T_{CLCL} - 15 (5V)	ns
T_{PXAV}	PSEN# to Address valid	22		17		T_{CLCL} - 8		ns
T_{AVIV}	Address to Valid Instr In		72				$5T_{CLCL}$ - 80 (3V)	ns
					65		$5T_{CLCL}$ - 60 (5V)	ns
T_{PLAZ}	PSEN# Low to Address Float		10		10		10	ns
T_{RLRH}	RD# Pulse Width	142				$6T_{CLCL}$ - 40 (3V)		ns
				120		$6T_{CLCL}$ - 30 (5V)		
T_{WLWH}	Write Pulse Width (WE#)	142				$6T_{CLCL}$ - 40 (3V)		ns
				120		$6T_{CLCL}$ - 30 (5V)		
T_{RLDV}	RD# Low to Valid Data In		62				$5T_{CLCL}$ - 90 (3V)	ns
					75		$5T_{CLCL}$ - 50 (5V)	ns
T_{RHDX}	Data Hold After RD#	0		0		0		ns
T_{RHDZ}	Data Float After RD#		36				$2T_{CLCL}$ - 25 (3V)	ns
					38		$2T_{CLCL}$ - 12 (5V)	ns
T_{LLDV}	ALE Low to Valid Data In		152				$8T_{CLCL}$ - 90 (3V)	ns
					150		$8T_{CLCL}$ - 50 (5V)	ns
T_{AVDV}	Address to Valid Data In		183				$9T_{CLCL}$ - 90 (3V)	ns
					150		$9T_{CLCL}$ - 75 (5V)	ns
T_{LLWL}	ALE Low to RD# or WR# Low	66	116			$3T_{CLCL}$ - 25 (3V)	$3T_{CLCL}$ + 25 (3V)	ns
				60	90	$3T_{CLCL}$ - 15 (5V)	$3T_{CLCL}$ + 15 (5V)	ns
T_{AVWL}	Address to RD# or WR# Low	46				$4T_{CLCL}$ - 75 (3V)		ns
				70		$4T_{CLCL}$ - 30 (5V)		ns

EOL Data Sheet

TABLE 13-8: AC ELECTRICAL CHARACTERISTICS (CONTINUED) (2 OF 2)
T_A = -40°C TO +85°C, V_{DD} = 2.7-3.6V@33MHz, 4.5-5.5V@40MHz, V_{SS} = 0V

| Symbol | Parameter | Oscillator | | | | | | Units |
| | | 33 MHz (x1 Mode) 16 MHz (x2 Mode)[1] | | 40 MHz (x1 Mode) 20 MHz (x2 Mode)[1] | | Variable | | |
		Min	Max	Min	Max	Min	Max	
T_{QVWX}	Data Valid to WR# High to Low Transition		10		5	T_{CLCL} - 20		ns
T_{WHQX}	Data Hold After WR#	3				T_{CLCL} - 27 (3V)		ns
				5		T_{CLCL} - 20 (5V)		ns
T_{QVWH}	Data Valid to WR# High	142				$7T_{CLCL}$ - 70 (3V)		ns
				125		$7T_{CLCL}$ - 50 (5V)		ns
T_{RLAZ}	RD# Low to Address Float		0		0		0	ns
T_{WHLH}	RD# to WR# High to ALE High	5	55			T_{CLCL} - 25 (3V)	T_{CLCL} + 25 (3V)	ns
				10	40	T_{CLCL} - 15 (5V)	T_{CLCL} + 15 (5V)	ns

T13-8.6 1207

1. Calculated values are for x1 Mode only

Explanation of Symbols Each timing symbol has 5 characters. The first character is always a 'T' (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

A: Address
C: Clock
D: Input data
H: Logic level HIGH
I: Instruction (program memory contents)
L: Logic level LOW or ALE
P: PSEN#

Q: Output data
R: RD# signal
T: Time
V: Valid
W: WR# signal
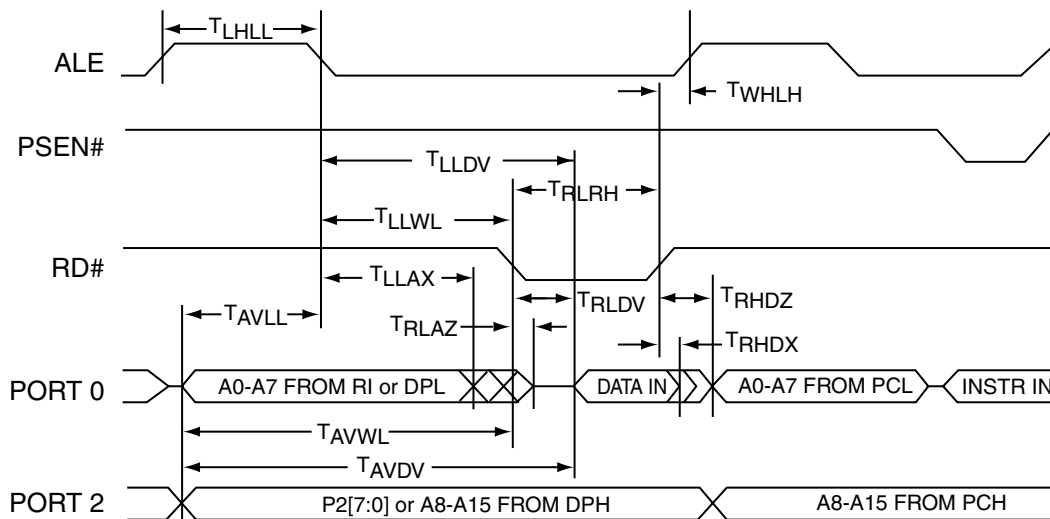X: No longer a valid logic level
Z: High Impedance (Float)

For example:

T_{AVLL} = Time from Address Valid to ALE Low

T_{LLPL} = Time from ALE Low to PSEN# Low
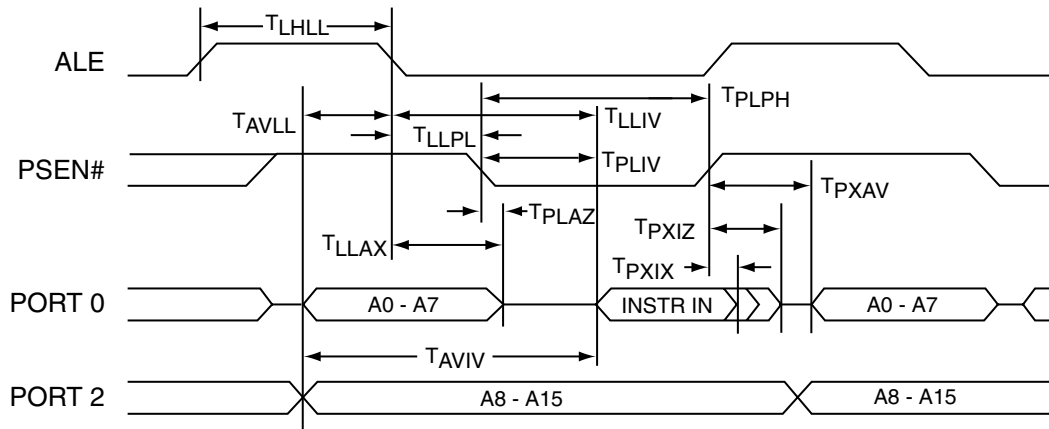
FIGURE   13-3: EXTERNAL PROGRAM MEMORY READ CYCLE

FIGURE   13-4: EXTERNAL DATA MEMORY READ CYCLE

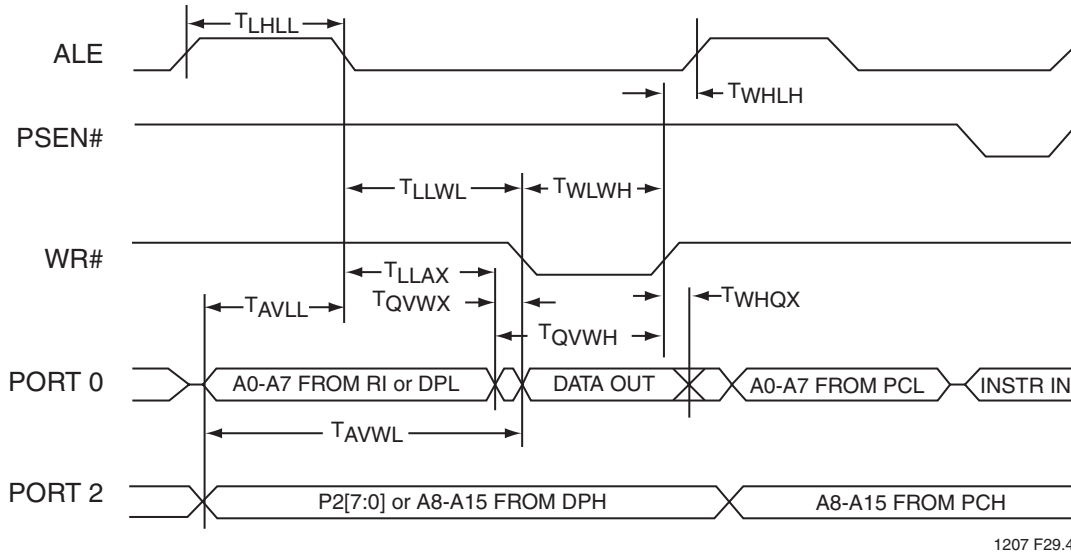1207 F29.4

FIGURE 13-5: EXTERNAL DATA MEMORY WRITE CYCLE

TABLE 13-9: EXTERNAL CLOCK DRIVE

		Oscillator						
		12MHz		40MHz		Variable		
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
$1/T_{CLCL}$	Oscillator Frequency					0	40	MHz
T_{CLCL}		83		25				ns
T_{CHCX}	High Time			8.75		$0.35T_{CLCL}$	$0.65T_{CLCL}$	ns
T_{CLCX}	Low Time			8.75		$0.35T_{CLCL}$	$0.65T_{CLCL}$	ns
T_{CLCH}	Rise Time		20		10			ns
T_{CHCL}	Fall Time		20		10			ns

T13-9.2 1207

1207 F30.2
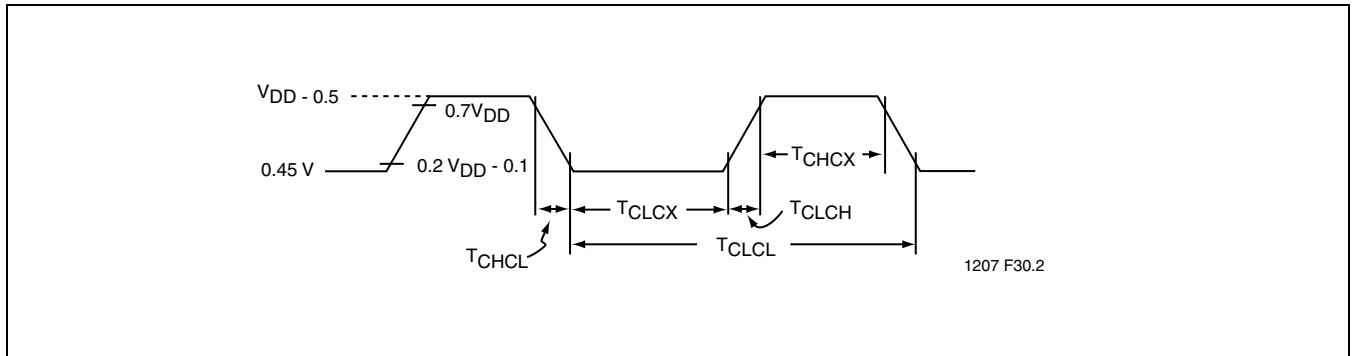
FIGURE 13-6: EXTERNAL CLOCK DRIVE WAVEFORM

S71207-07-EOL   12/06

TABLE 13-10: SERIAL PORT TIMING

Symbol	Parameter	12MHz Min	12MHz Max	40MHz Min	40MHz Max	Variable Min	Variable Max	Units
		Oscillator						
		12MHz		**40MHz**		**Variable**		
		Min	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	Serial Port Clock Cycle Time	1.0		0.3		$12T_{CLCL}$		µs
T_{QVXH}	Output Data Setup to Clock Rising Edge	700		117		$10T_{CLCL} - 133$		ns
T_{XHQX}	Output Data Hold After Clock Rising Edge	50				$2T_{CLCL} - 117$		ns
				0		$2T_{CLCL} - 50$		ns
T_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		0		ns
T_{XHDV}	Clock Rising Edge to Input Data Valid		700		117		$10T_{CLCL} - 133$	ns

T13-10.2 1207
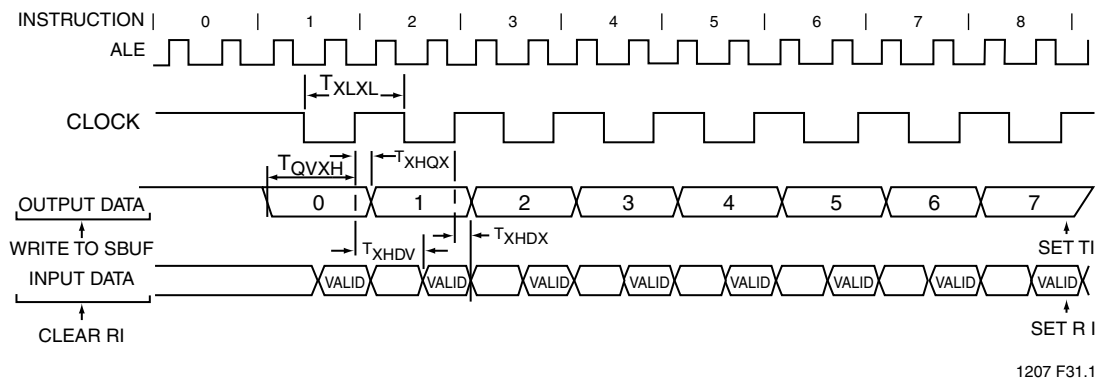
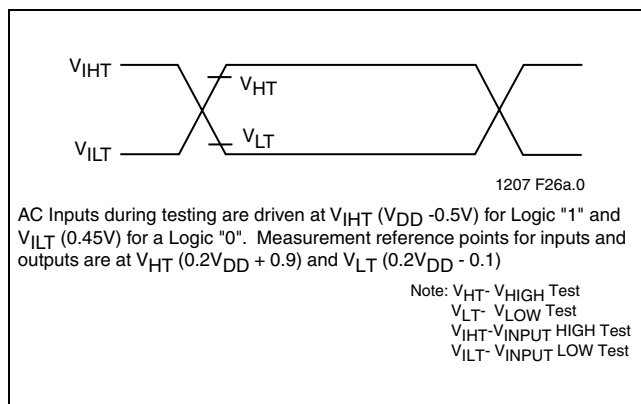1207 F31.1

FIGURE 13-7: SHIFT REGISTER MODE TIMING WAVEFORMS

1207 F26a.0

AC Inputs during testing are driven at V_{IHT} (V_{DD} -0.5V) for Logic "1" and V_{ILT} (0.45V) for a Logic "0". Measurement reference points for inputs and outputs are at V_{HT} ($0.2V_{DD}$ + 0.9) and V_{LT} ($0.2V_{DD}$ - 0.1)

Note: V_{HT}- V_{HIGH} Test
V_{LT}- V_{LOW} Test
V_{IHT}-V_{INPUT} HIGH Test
V_{ILT}- V_{INPUT} LOW Test

FIGURE 13-8: AC TESTING INPUT/OUTPUT TEST WAVEFORM

1207 F26b.0

For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs, and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} = \pm 20mA$.
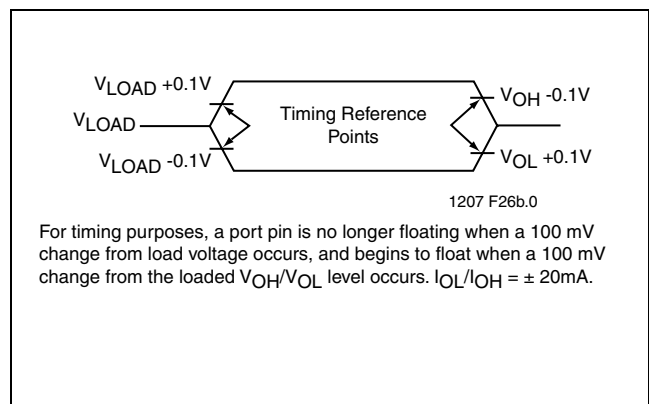
FIGURE 13-9: FLOAT WAVEFORM
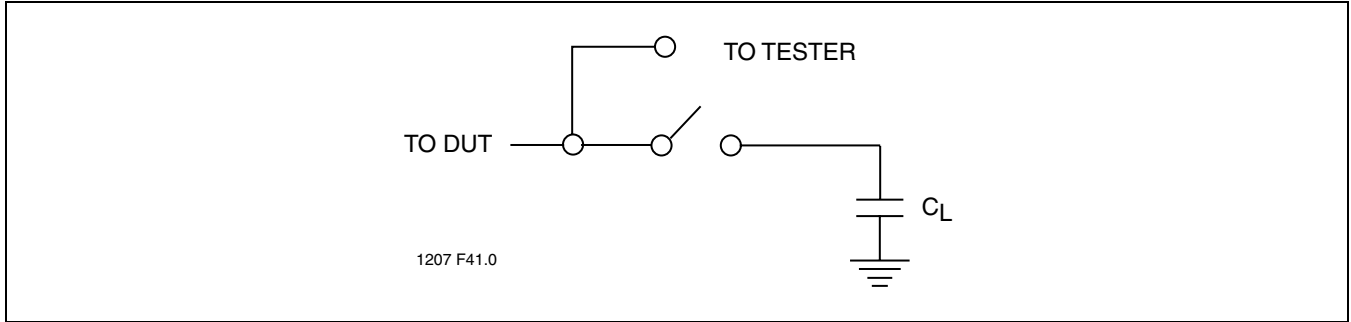
S71207-07-EOL   12/06
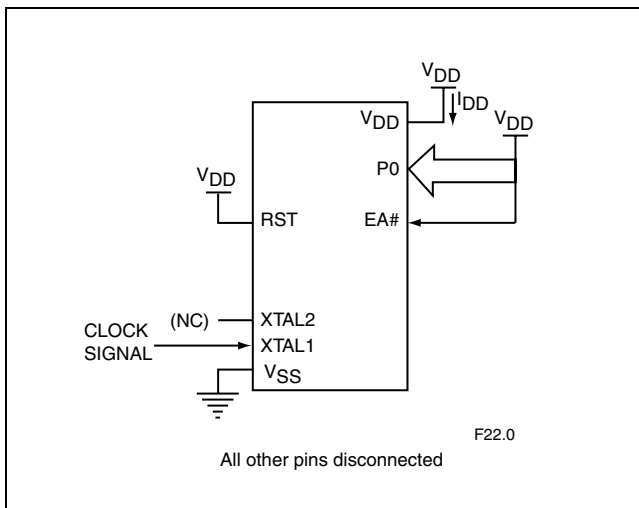
FIGURE 13-10: A TEST LOAD EXAMPLE

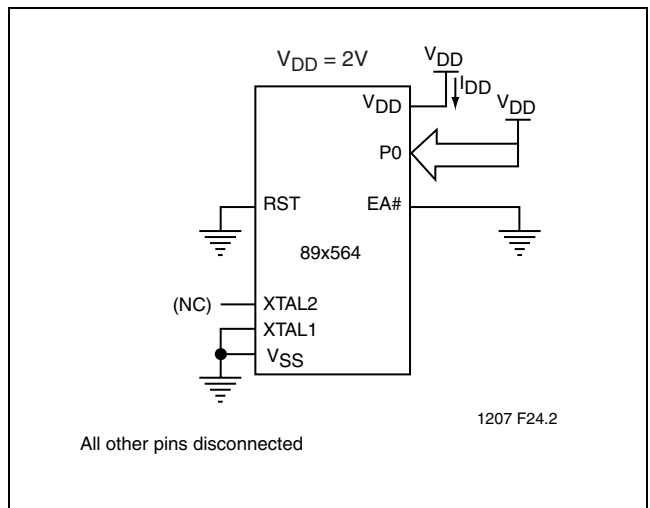**FIGURE 13-11: I$_{DD}$ TEST CONDITION, ACTIVE MODE**
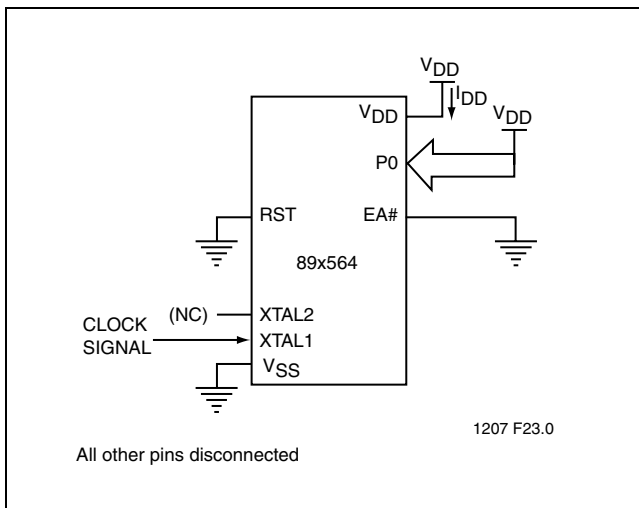

FIGURE 13-13: I$_{DD}$ TEST CONDITION, POWER-DOWN MODE

FIGURE 13-12: I$_{DD}$ TEST CONDITION, IDLE MODE

TABLE 13-11: EXTERNAL MODE FLASH MEMORY PROGRAMMING/VERIFICATION PARAMETERS[1]

Parameter[2,3]	Symbol	Min	Max	Units
Reset Setup Time	T_{SU}	3		µs
Read-ID Command Width	T_{RD}	1		µs
PSEN# Setup Time	T_{ES}	40		µs
Address, Command, Data Setup Time	T_{ADS}	0		ns
Chip-Erase Time	T_{CE}		150	ms
Block-Erase Time	T_{BE}		100	ms
Sector-Erase Time	T_{SE}		30	ms
Program Setup Time	T_{PROG}	1.2		µs
Address, Command, Data Hold	T_{DH}	0		ns
Byte-Program Time[4]	T_{PB}		50	µs
Select-Block Program Time	T_{PSB}		500	ns
Re-map or Security bit Program Time	T_{PS}		80	µs
Verify Command Delay Time	T_{OA}		50	ns
Verify High Order Address Delay Time	T_{AHA}		50	ns
Verify Low Order Address Delay Time	T_{ALA}		50	ns

T13-11.1 1207

1. For IAP operations, the program execution overhead must be added to the above timing parameters.
2. Program and Erase times will scale inversely proportional to programming clock frequency.
3. All timing measurements are from the 50% of the input to 50% of the output.
4. Each byte must be erased before programming.

EOL Data Sheet

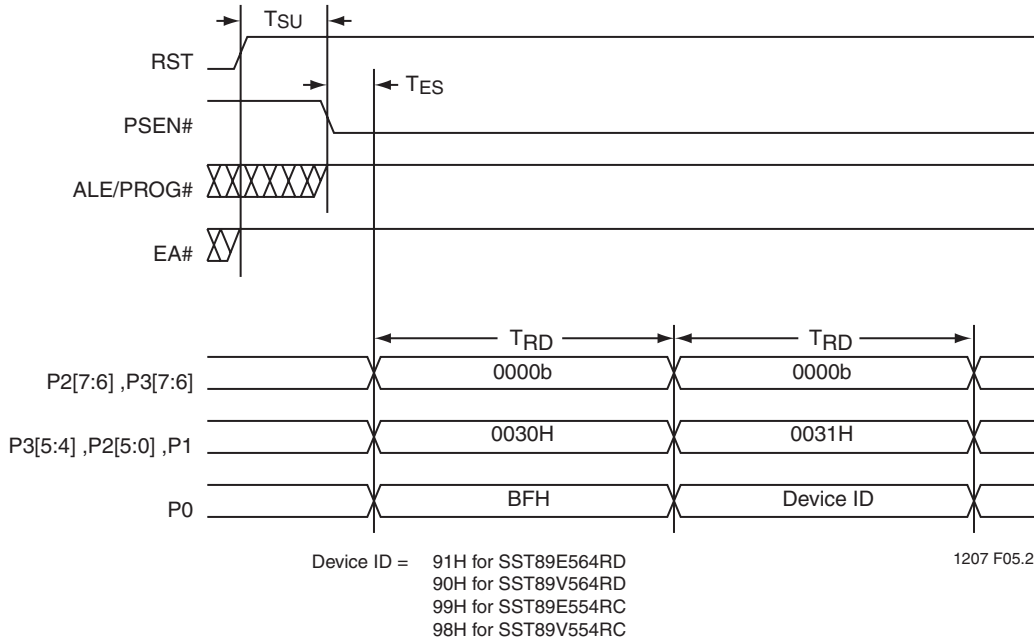## 13.3 Flash Memory Programming Timing Diagrams with External Host Mode

Device ID = 91H for SST89E564RD
90H for SST89V564RD
99H for SST89E554RC
98H for SST89V554RC

1207 F05.2

FIGURE 13-14: Read-ID
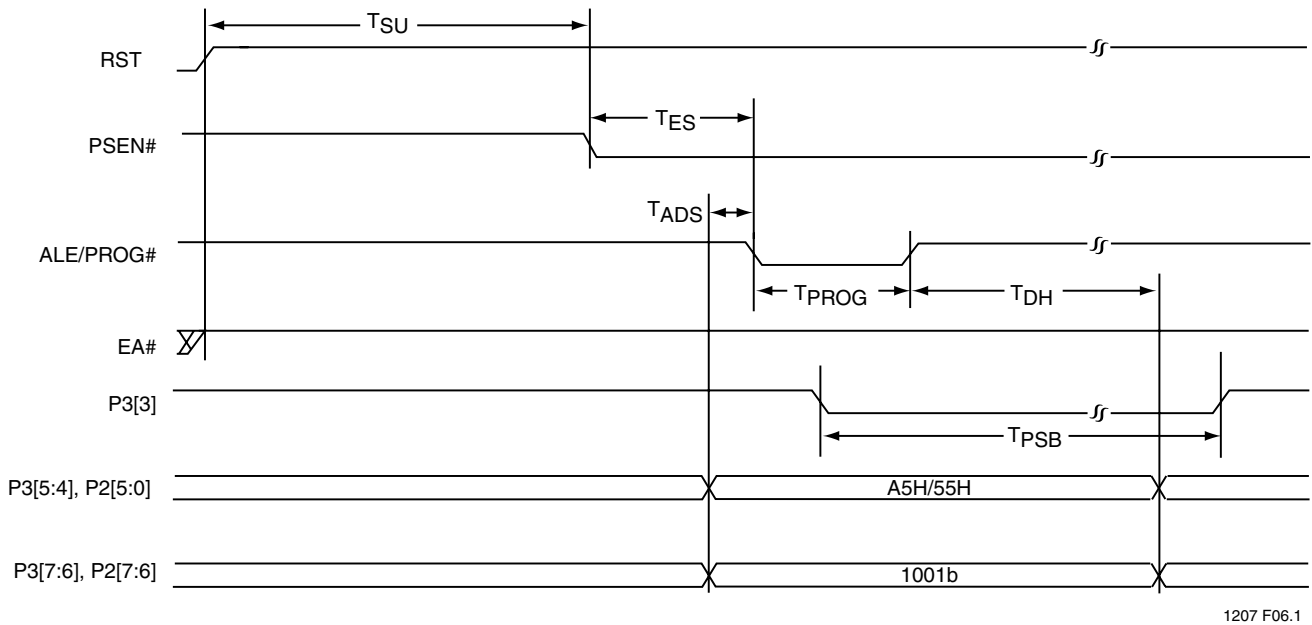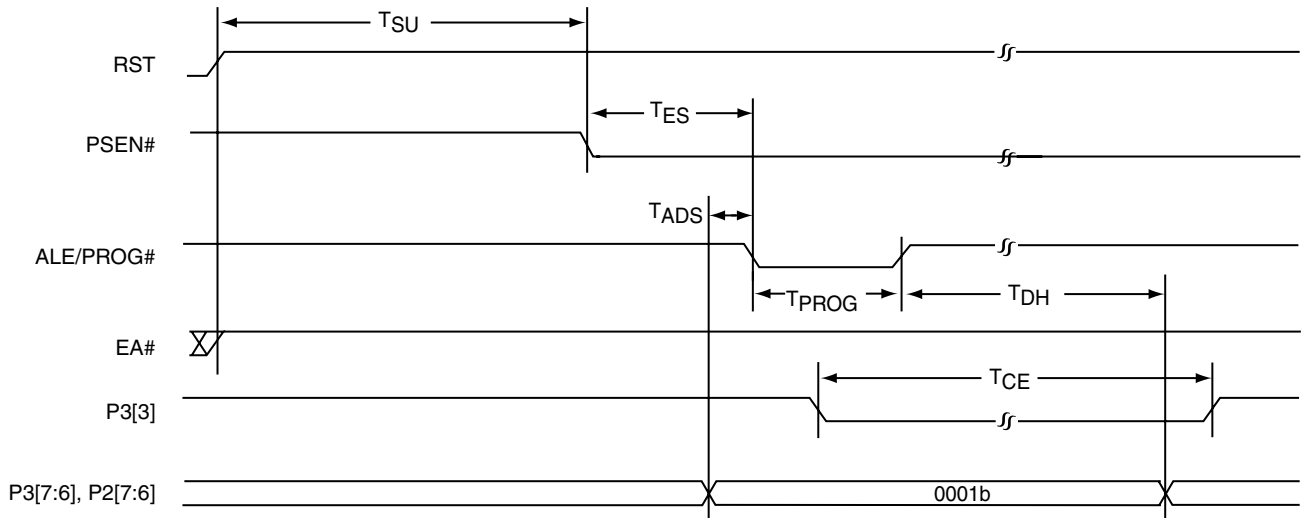Reads chip signature and identification registers at the addressed location.

1207 F06.1

FIGURE 13-15: Select-Block1 / Select-Block0 (For SST89E/V564RD only)
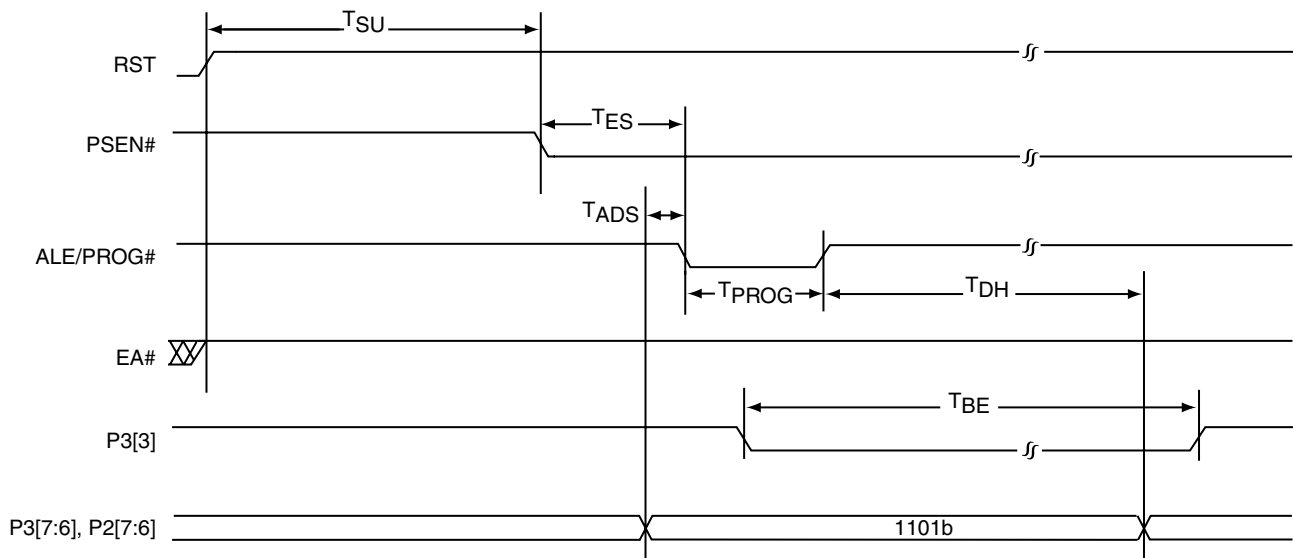
Enables the selection of either of the flash memory blocks prior to issuing a Byte-Verify, Block-Erase, Sector-Erase, or Byte-Program.

FIGURE 13-16: CHIP-ERASE
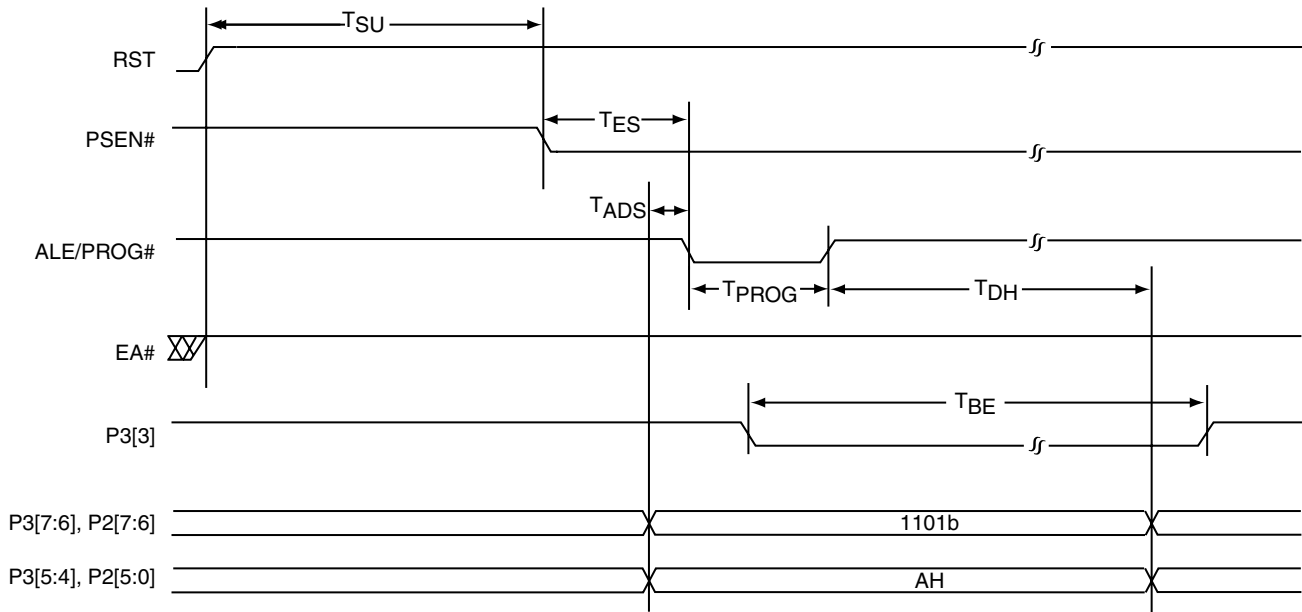Erases both flash memory blocks. Security lock is ignored and the security bits are erased too.

FIGURE 13-17: BLOCK-ERASE FOR SST89E/V564RD
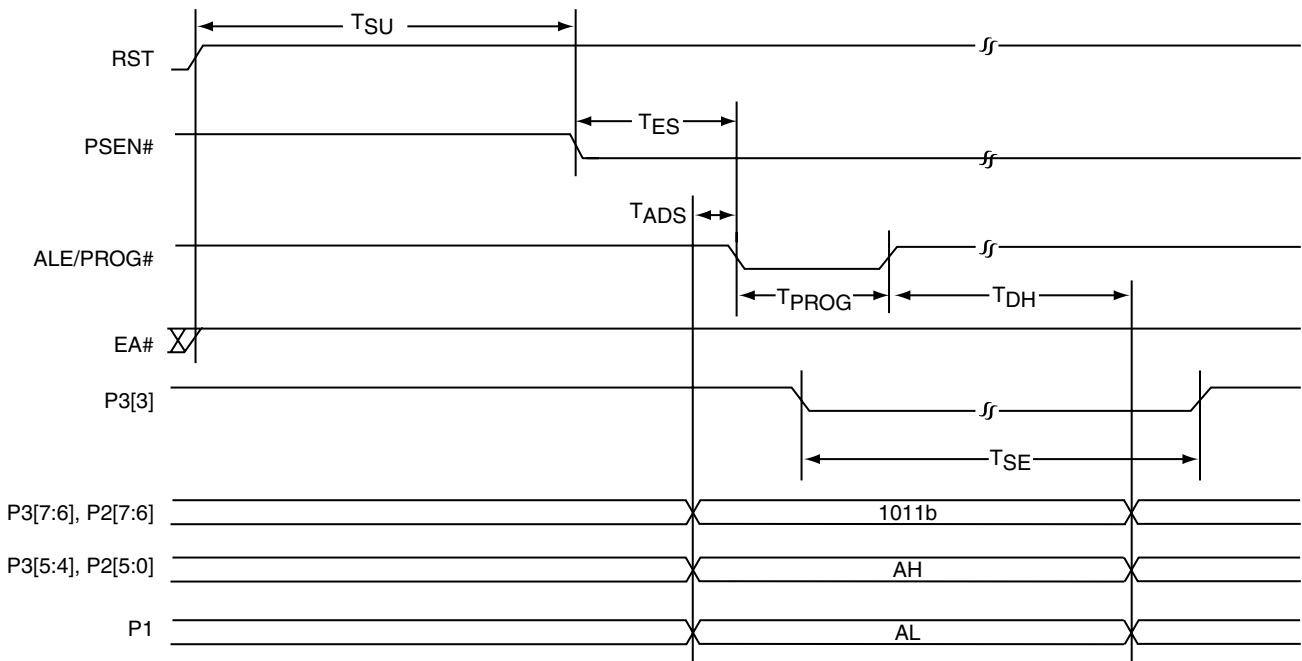Erases one of the flash memory blocks, if the security lock is not activated on that flash memory block.

1207 F09.1

FIGURE 13-18: BLOCK-ERASE FOR SST89E/V554RC
Erases one of the flash memory blocks, if the security lock is not activated on that flash memory block.

1207 F10.1

FIGURE 13-19: SECTOR-ERASE
Erases the addressed sector if the security lock is not activated on that flash memory block.
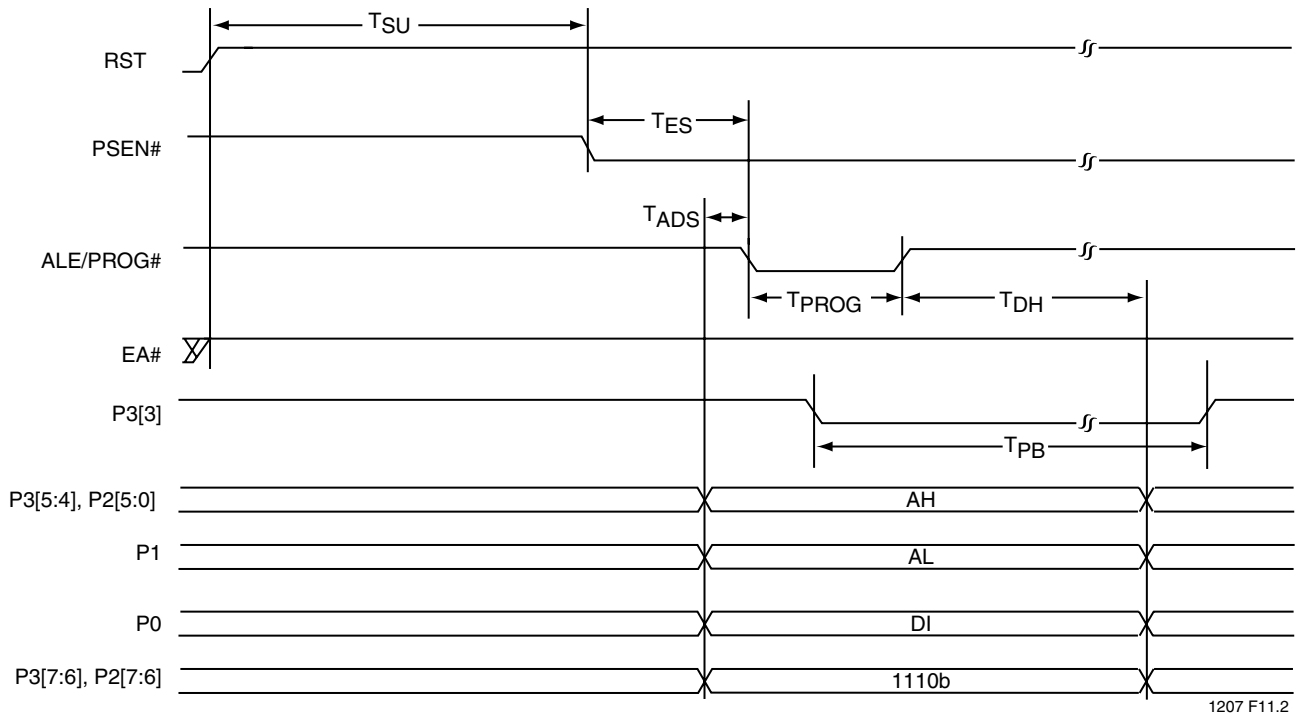
FIGURE 13-20: BYTE-PROGRAM
Programs the addressed code byte if the byte location has been successfully erased and not yet programmed.
Byte-Program operation is only allowed when the security lock is not activated on that flash memory block.
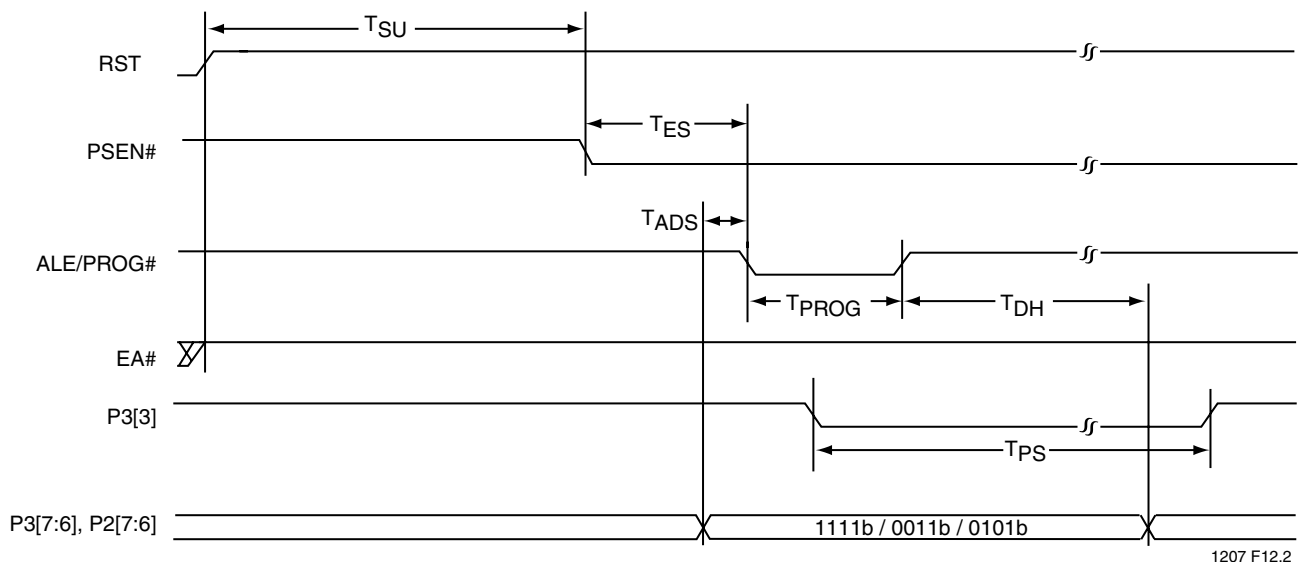
FIGURE 13-21: PROG-SB1 / PROG-SB2 / PROG-SB3
Programs the Security bits SB1, SB2 and SB3 respectively. Only a Chip-Erase will erase a programmed security bit.
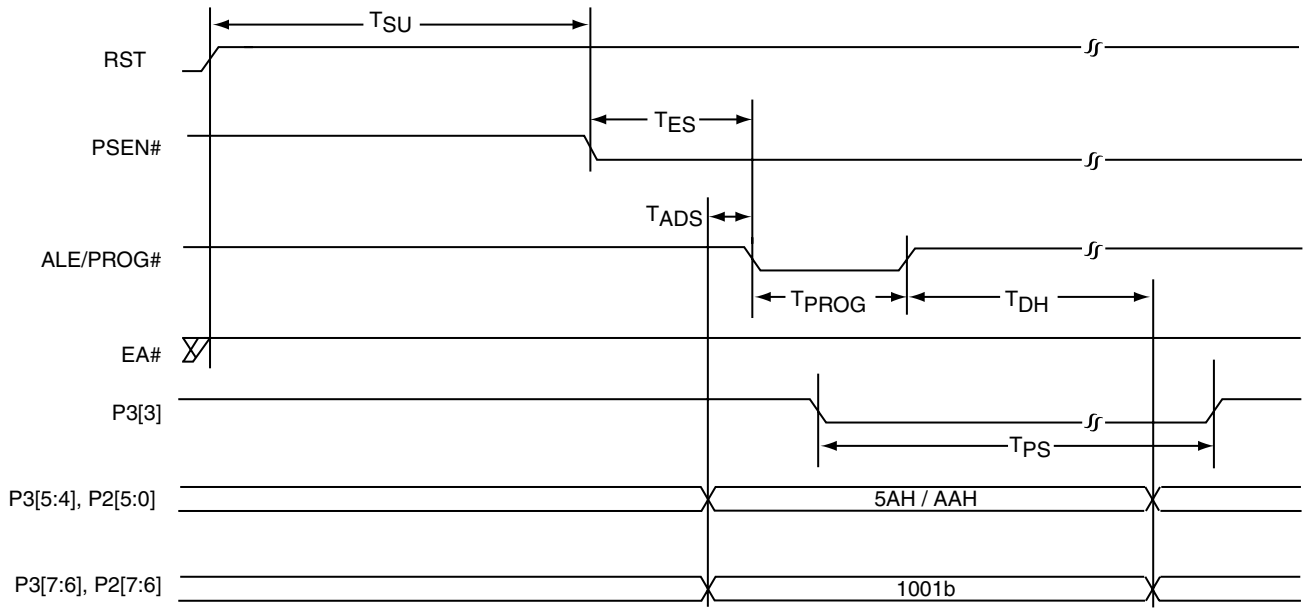
FIGURE 13-22: PROG-SC0 / PROG-SC1
Programs the start-up configuration bit SC0/SC1. Only a Chip-Erase will erase a programmed SC0/SC1 bit.
Prog-SC1 applies to SST89E554RC/SST89V554RC only.
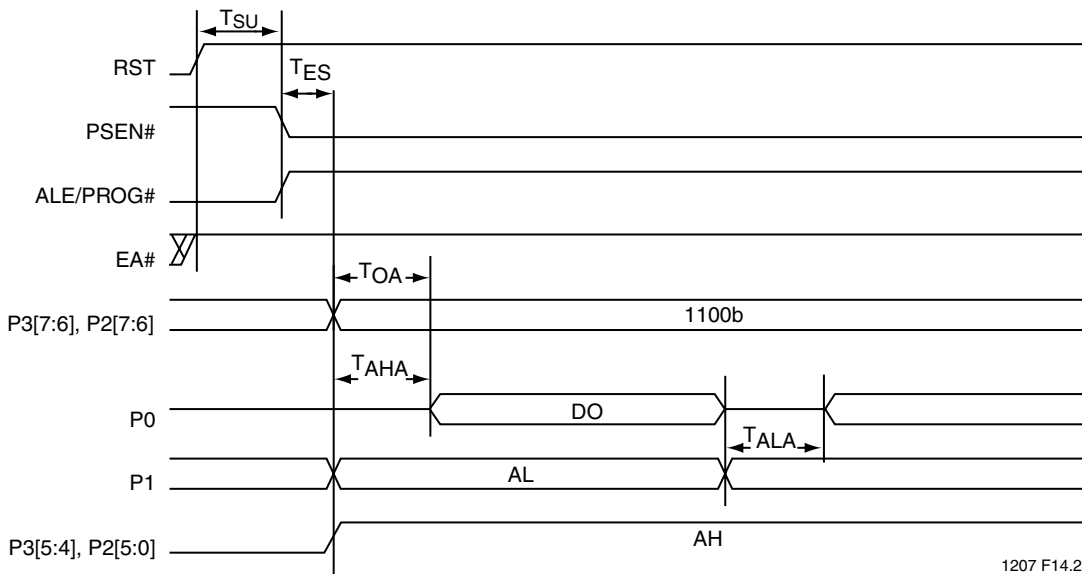
FIGURE 13-23: BYTE-VERIFY
Reads the code byte from the addressed flash memory location if the security lock is not activated on that flash
memory block.

14.0 PRODUCT ORDERING INFORMATION

Device	Speed	Suffix1	Suffix2

SST89x5x4xx - XX - X - X X X

Package Attribute
  E^1 = non-Pb
  F^1 = non-Pb / non-Sn contact (lead) finish:
    Nickel-Palladium with Gold flash outer layer

Package Modifier
  I = 40 contacts or pins
  J = 44 leads

Package Type
  P = PDIP
  N = PLCC
  Q = WQFN
  TQ = TQFP

Operation Temperature
  C = Commercial = 0°C to +70°C
  I = Industrial = -40°C to +85°C

Operating Frequency
  33 = 0-33MHz
  40 = 0-40MHz

Feature Set and Flash Memory Size
  564RD = C52 feature set + 64(72) KByte
  554RC = C52 feature set + 32(40) KByte
  Note: Number in parenthesis includes an additional 8 KByte flash which can be enabled.

Voltage Range
  E = 4.5-5.5V
  V = 2.7-3.6V

Product Series
  89 = C51 Core

1. Environmental suffixes "E" and "F" denote non-Pb solder. SST non-Pb solder devices are "RoHS Compliant".

EOL Data Sheet

14.1 Valid Combinations

Valid combinations for SST89E564RD

SST89E564RD-40-C-PI	SST89E564RD-40-C-NJ	SST89E564RD-40-C-TQJ	
SST89E564RD-40-C-PIE	SST89E564RD-40-C-NJE	SST89E564RD-40-C-TQJE	SST89E564RD-40-C-QIF
SST89E564RD-40-I-PI	SST89E564RD-40-I-NJ	SST89E564RD-40-I-TQJ	
SST89E564RD-40-I-PIE	SST89E564RD-40-I-NJE	SST89E564RD-40-I-TQJE	SST89E564RD-40-I-QIF

Valid combinations for SST89V564RD

SST89V564RD-33-C-PI	SST89V564RD-33-C-NJ	SST89V564RD-33-C-TQJ	
SST89V564RD-33-C-PIE	SST89V564RD-33-C-NJE	SST89V564RD-33-C-TQJE	SST89V564RD-33-C-QIF
SST89V564RD-33-I-PI	SST89V564RD-33-I-NJ	SST89V564RD-33-I-TQJ	
SST89V564RD-33-I-PIE	SST89V564RD-33-I-NJE	SST89V564RD-33-I-TQJE	SST89V564RD-33-I-QIF

Valid combinations for SST89E554RC

SST89E554RC-40-C-PI	SST89E554RC-40-C-NJ	SST89E554RC-40-C-TQJ
SST89E554RC-40-I-PI	SST89E554RC-40-I-NJ	SST89E554RC-40-I-TQJ

Valid combinations for SST89V554RC

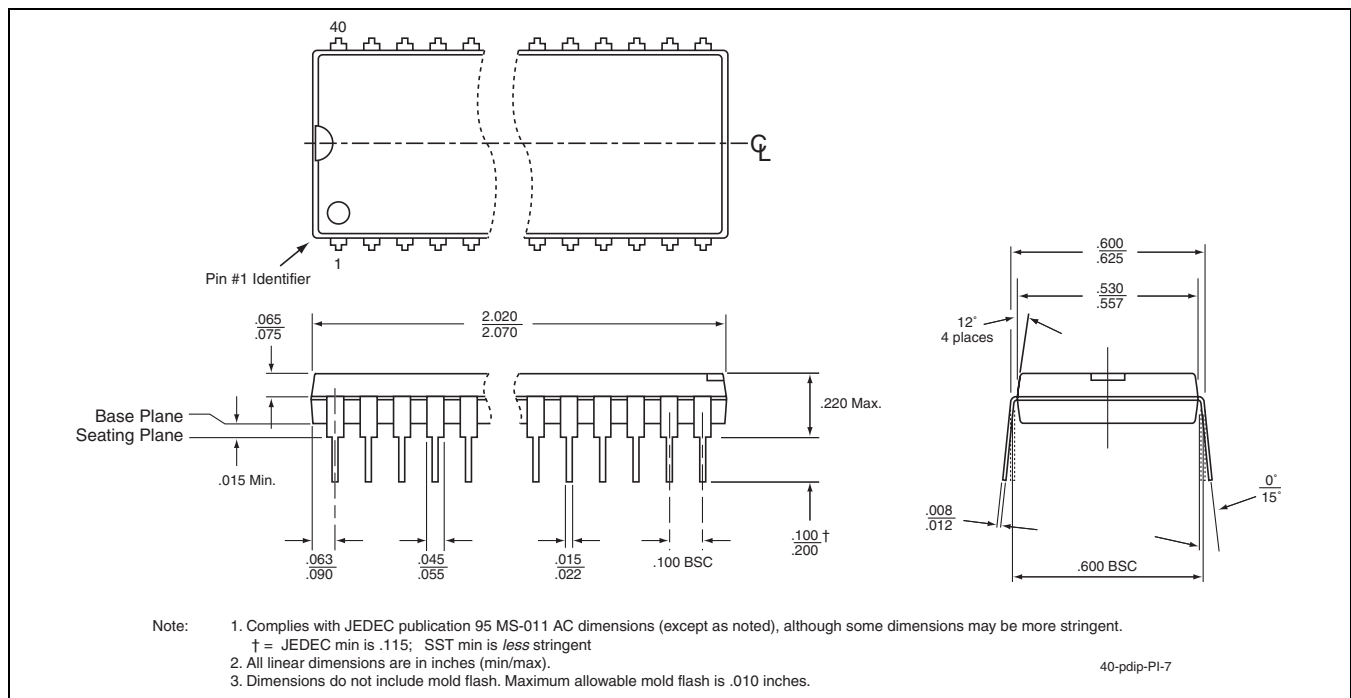|		
SST89V554RC-40-C-PI	SST89V554RC-40-C-NJ	SST89V554RC-40-C-TQJ
SST89V554RC-40-I-PI	SST89V554RC-40-I-NJ	SST89V554RC-40-I-TQJ

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

15.0 PACKAGING DIAGRAMS

TOP VIEW   SIDE VIEW   BOTTOM VIEW

Note: 1. Complies with JEDEC JEP95 MO-220I, variant WJJD-5 except external paddle nominal dimensions.
2. From the bottom view, the pin #1 indicator may be either a 45-degree chamfer or a half-circle notch.
3. The external paddle is electrically connected to the die back-side and possibly to certain V_{SS} leads.
This paddle can be soldered to the PC board; it is suggested to connect this paddle to the V_{SS} of the unit.
Connection of this paddle to any other voltage potential can result in shorts and/or electrical malfunction of the device.
4. Untoleranced dimensions (shown with box surround) are nominal target dimensions.
5. All linear dimensions are in millimeters (max/min).

40-wqfn-6x6-QI-0.0

40-CONTACT VERY-VERY-THIN QUAD FLAT NO-LEAD (WQFN)
SST PACKAGE CODE: QI

Note: 1. Complies with JEDEC publication 95 MS-011 AC dimensions (except as noted), although some dimensions may be more stringent.
† = JEDEC min is .115; SST min is *less* stringent
2. All linear dimensions are in inches (min/max).
3. Dimensions do not include mold flash. Maximum allowable mold flash is .010 inches.

40-pdip-PI-7

40-PIN PLASTIC DUAL IN-LINE PINS (PDIP)
SST PACKAGE CODE: PI

EOL Data Sheet

TOP VIEW   SIDE VIEW   BOTTOM VIEW

Note: 1. Complies with JEDEC publication 95 MS-018 AC dimensions (except as noted), although some dimensions may be more stringent.
        † = JEDEC min is .650; SST min is *less* stringent
        2. All linear dimensions are in inches (min/max).
        3. Dimensions do not include mold flash. Maximum allowable mold flash is .008 inches.
        4. Coplanarity: 4 mils.
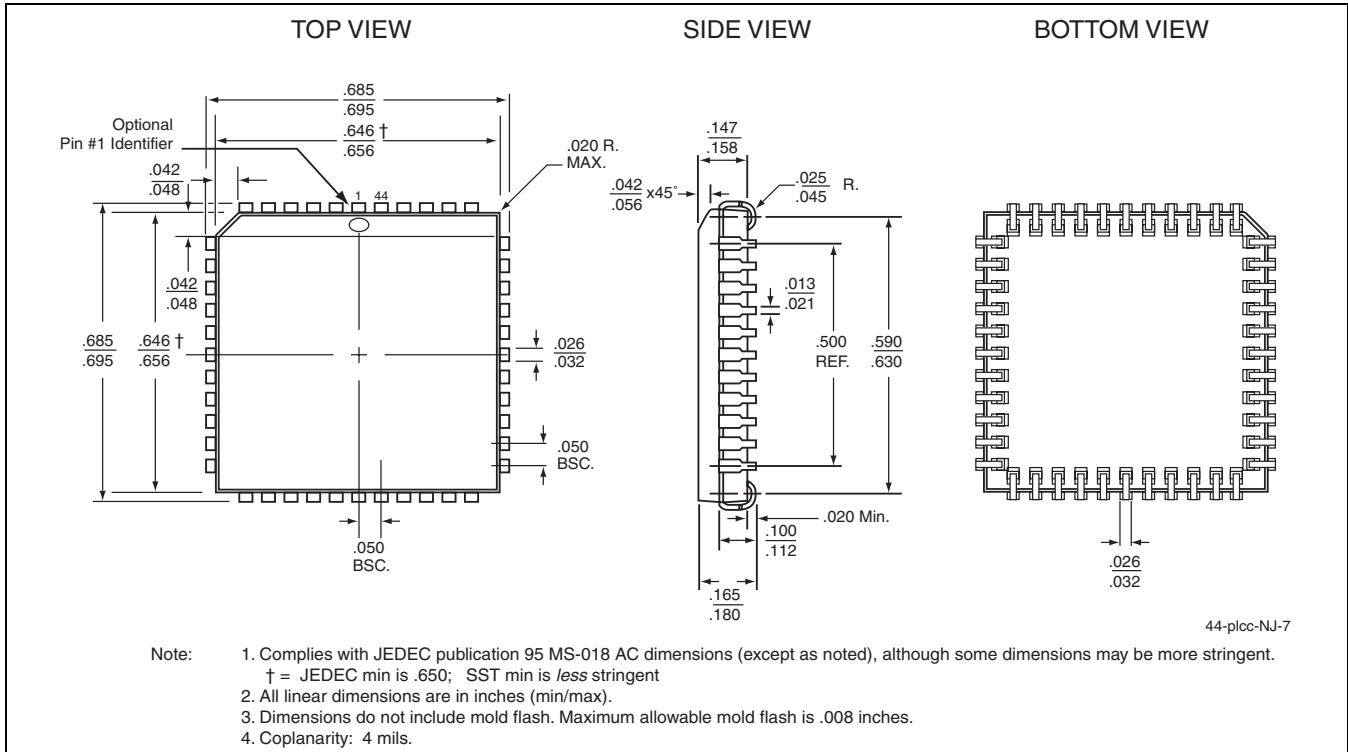
44-LEAD PLASTIC LEAD CHIP CARRIER (PLCC)
SST PACKAGE CODE: NJ

Pin #1 Identifier

44   34

1   33

10.00 ± 0.10

12.00 ± 0.25

11   23

12   22

10.00 ± 0.10

12.00 ± 0.25

.30
.45

.80 BSC

.09
.20

1.2 max.

.95
1.05

.05
.15

.45
.75

0˚- 7˚

1.00 ref

44-tqfp-TQJ-7

1mm

Note: 1. Complies with JEDEC publication 95 MS-026 ACB dimensions, although some dimensions may be more stringent.
2. All linear dimensions are in millimeters (min/max).
3. Coplanarity: 0.1 (±0.05) mm.
4. Package body dimensions do not include mold flash. Maximum allowable mold flash is .25mm.
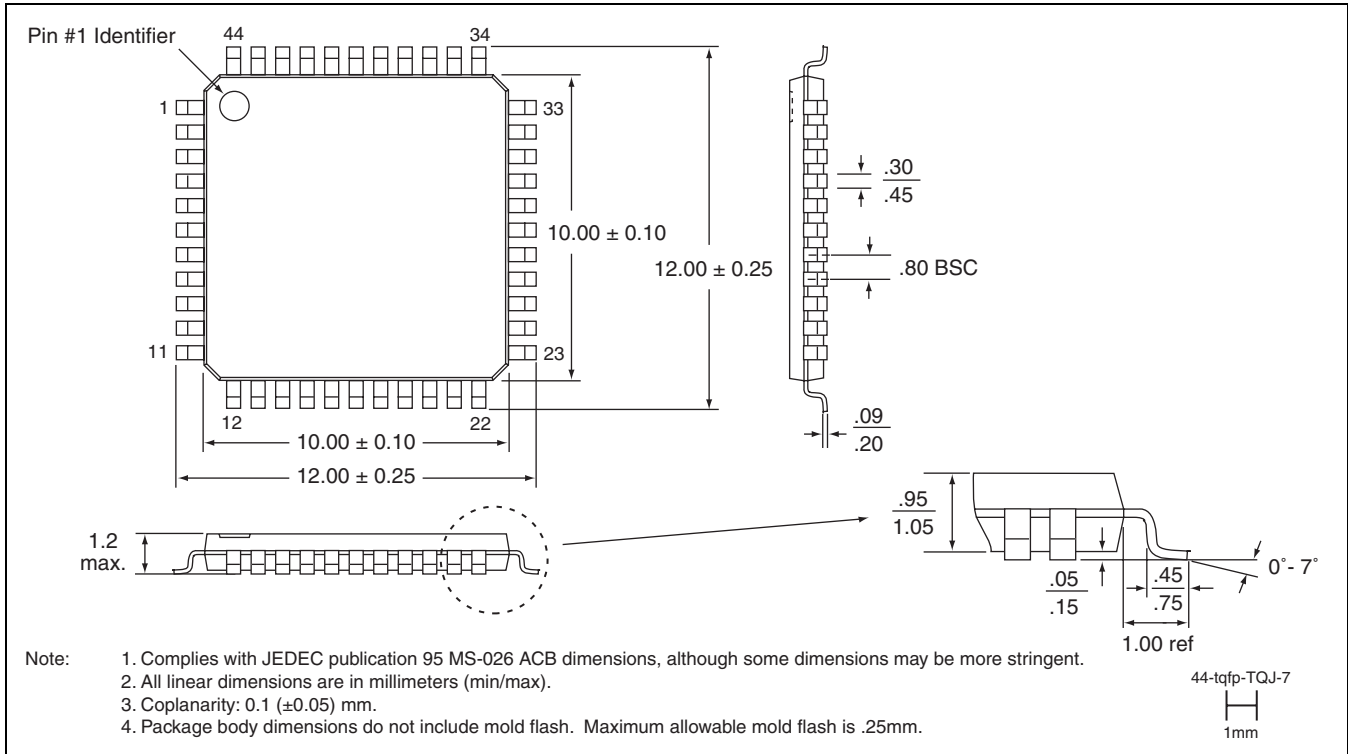
44-LEAD THIN QUAD FLAT PACK (TQFP)
SST PACKAGE CODE: TQJ

EOL Data Sheet

TABLE 15-1: REVISION HISTORY

Revision	Description	Date
00	• S71207: Initial release of the data sheet	Sep 2001
01	• S71207: Data Sheet changes • Updated product features • Clarified the x2 (6 clock) mode • General clean-up	Mar 2002
02	• S71207: Data Sheet changes • Added T2MOD SFR • General clarifications throughout	Oct 2002
03	• S71207: Data Sheet changes • Removed Serial Peripheral Interface (SPI) function • Added Programmed (P) and Unprogrammed (U) to Tables 3-3 and 3-4 • Corrected PCA diagrams • Removed XTAL1 and XTAL2 from Figure 4-1 • Removed timing parameter T_{QVWX}	Feb 2003
00[1]	• S71207(02): Initial release of the fact sheet for 2003/2004 ECU Data Book	Jun 2003
04	• S71207: Data Sheet changes • Inserted Serial Peripheral Interface (SPI) function • Inserted timing parameter T_{QVWX} to Table 13-8 on page 73 and Figure 13-5 on page 76	Dec 2003
05	• S71207: Data sheet and fact sheet synchronized • S71207(02): Fact sheet integrated into data sheet • S71207 and S71207(02): Added non-Pb part numbers for SST89E/V564RD devices	Jun 2004
06	• S71207 and S71207(02): Added 40-WQFN (QI) package and associated MPNs • Clarified the solder temperature profile under "Absolute Maximum Stress Ratings" on page 67	Nov 2004
07	• End-of-Life data sheet for all products in S71207	Dec 2006

1. Fact sheet released as separate document.

S71207-07-EOL   12/06